



Cell-Based IC Physical Design and Verification - SOC Encounter

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CIC2004/07



Class Schedule

◆ Day1

- Design Flow Over View
- Prepare Data
- Getting Started
- Importing Design
- Specify Floorplan
- Power Planning
- Placement
- Synthesize Clock Tree

◆ Day2

- Timing Analysis
- Trial Route
- Power Analysis
- SRoute
- NanoRoute
- Fill Filler
- Output Data
- DRC
- LVS
- extraction/nanosim

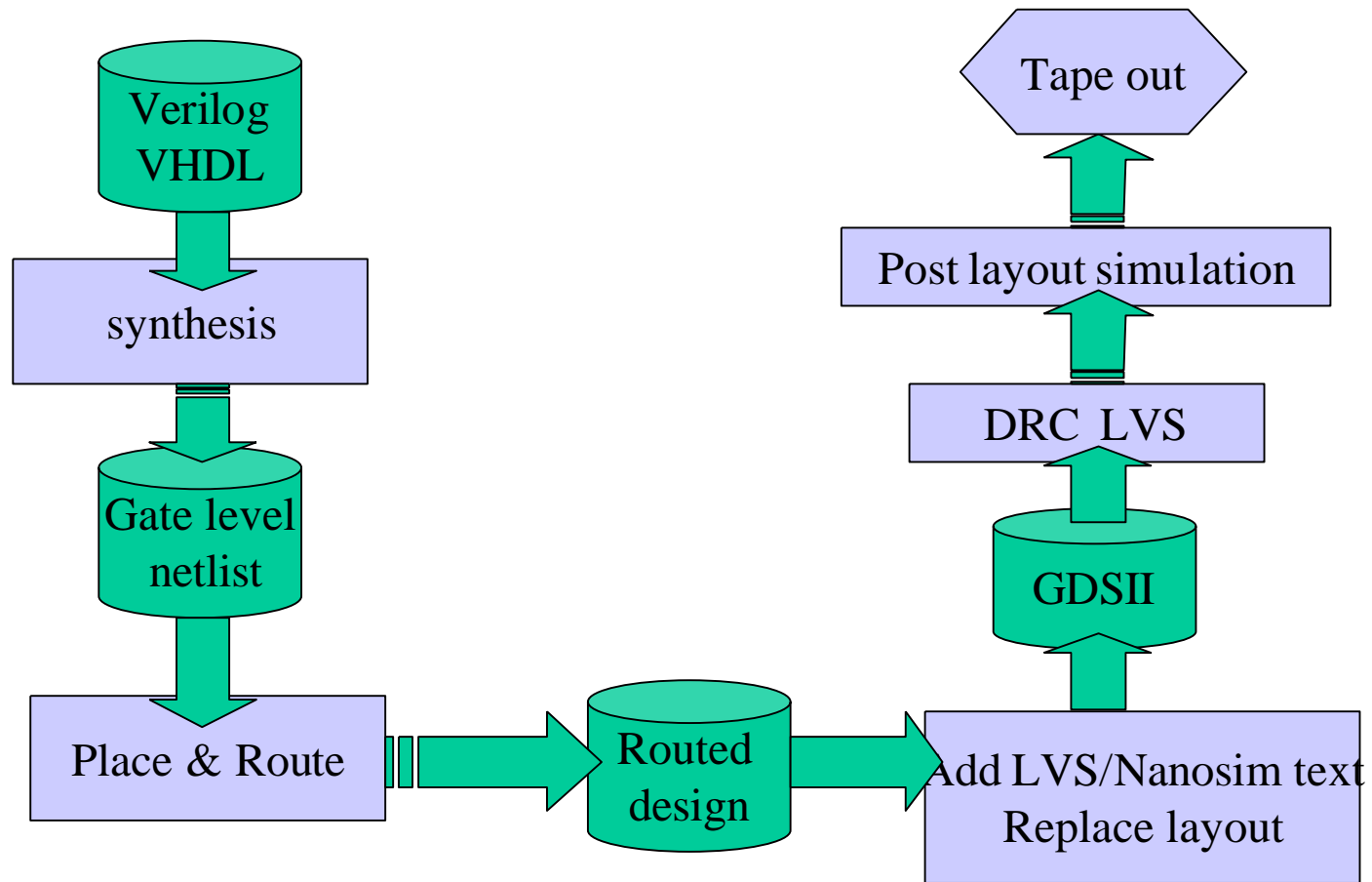


Chapter1

Cell-Based Physical Design – SOC Encounter 3.2

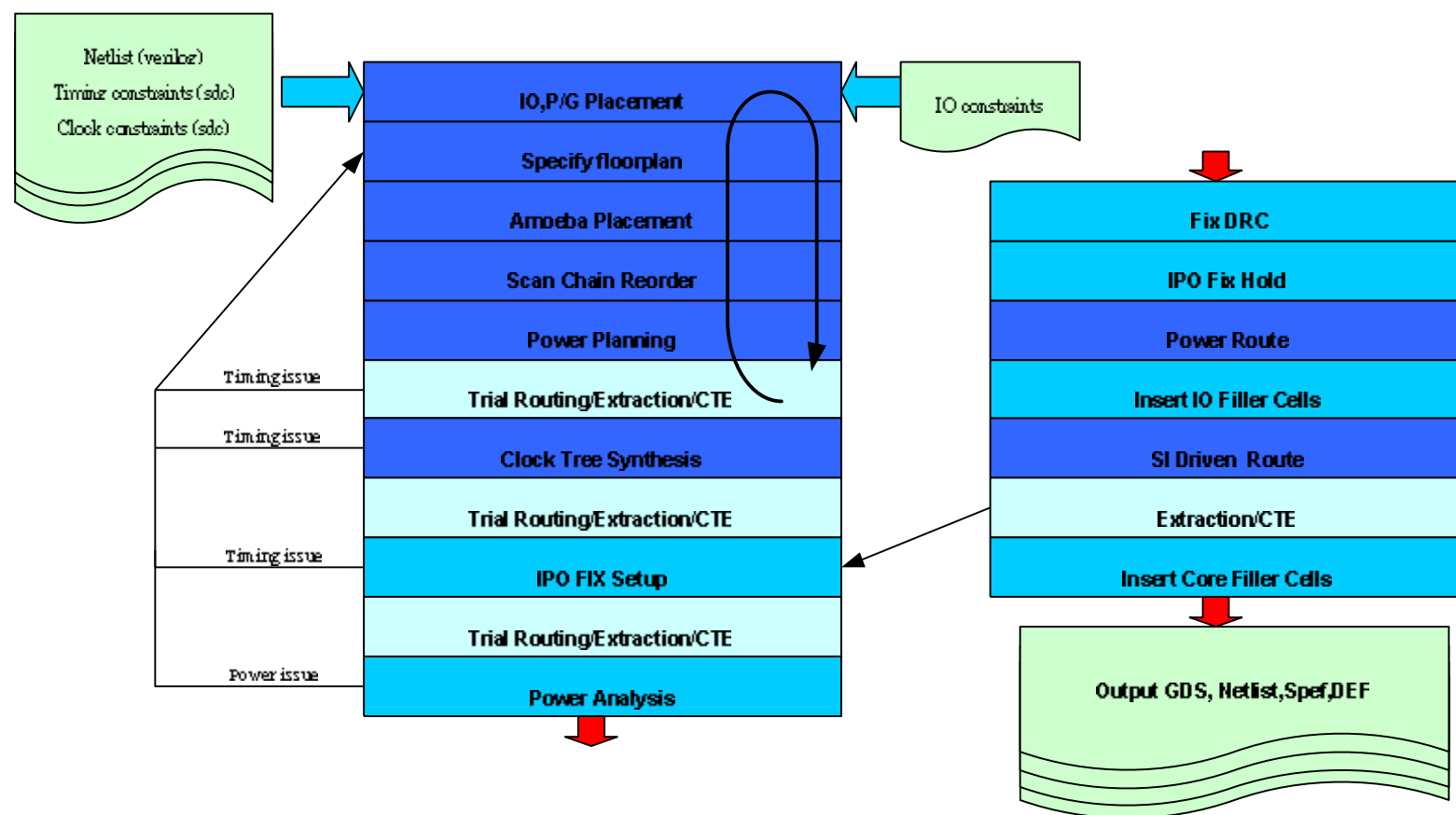


Cell-Based Design Flow



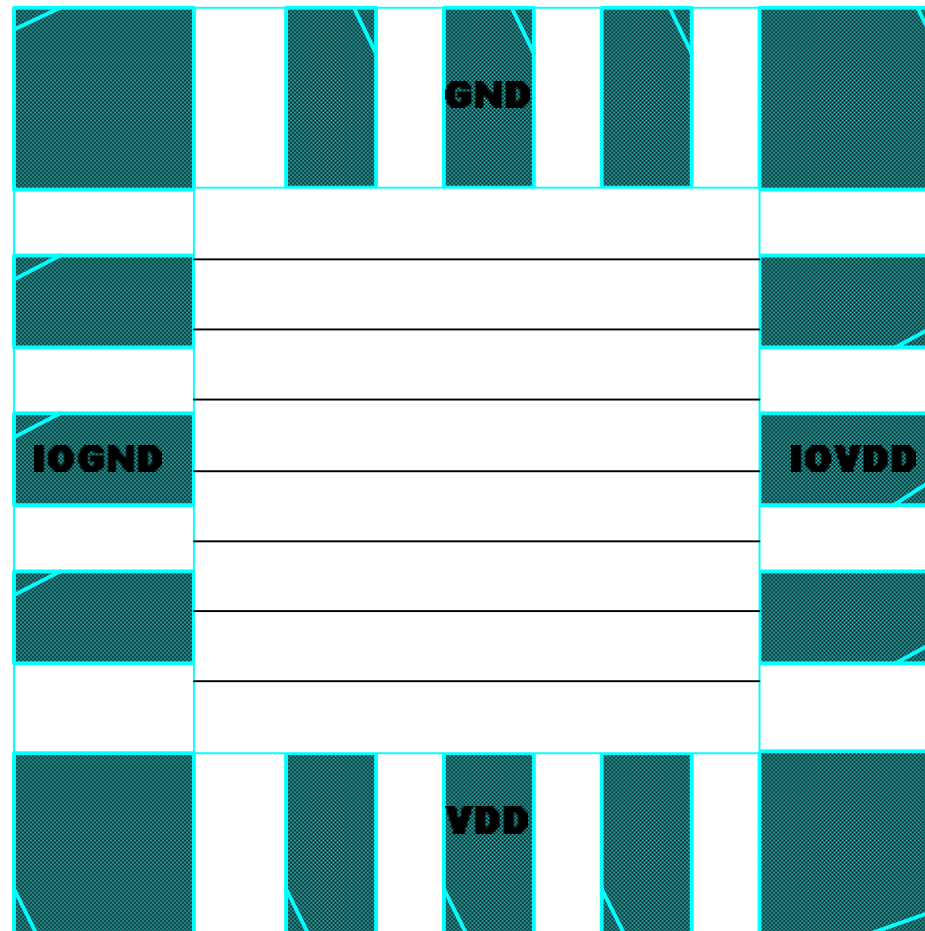


SOC Encounter P&R flow



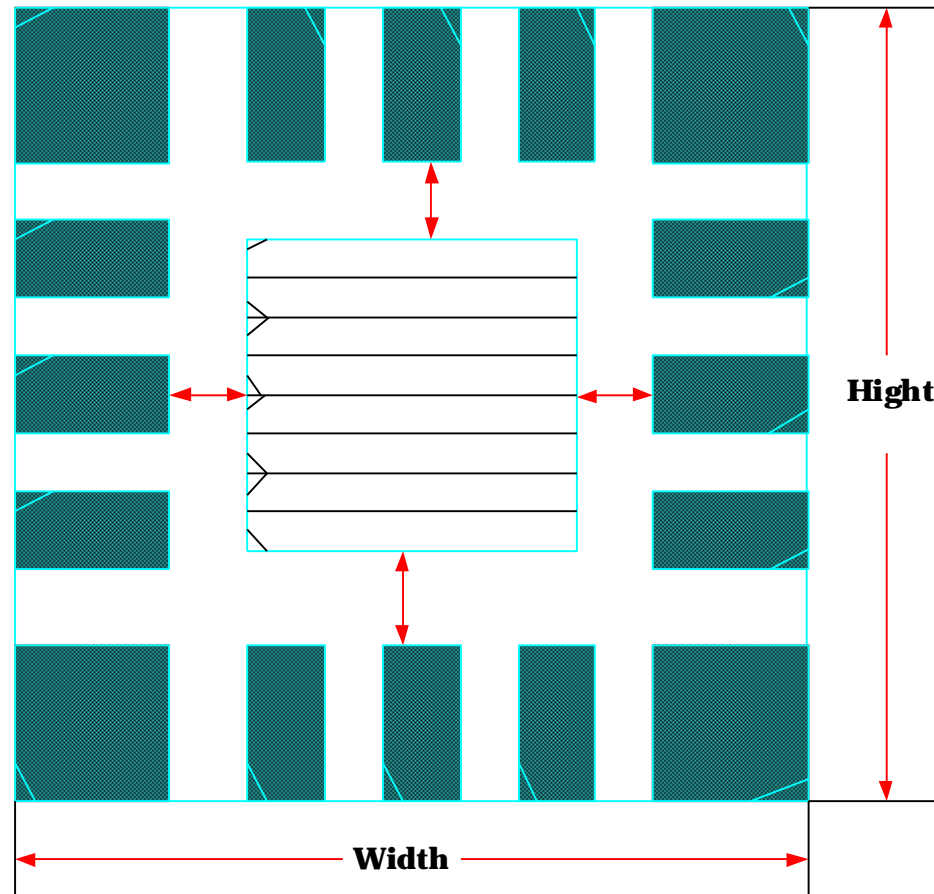


IO, P/G Placement



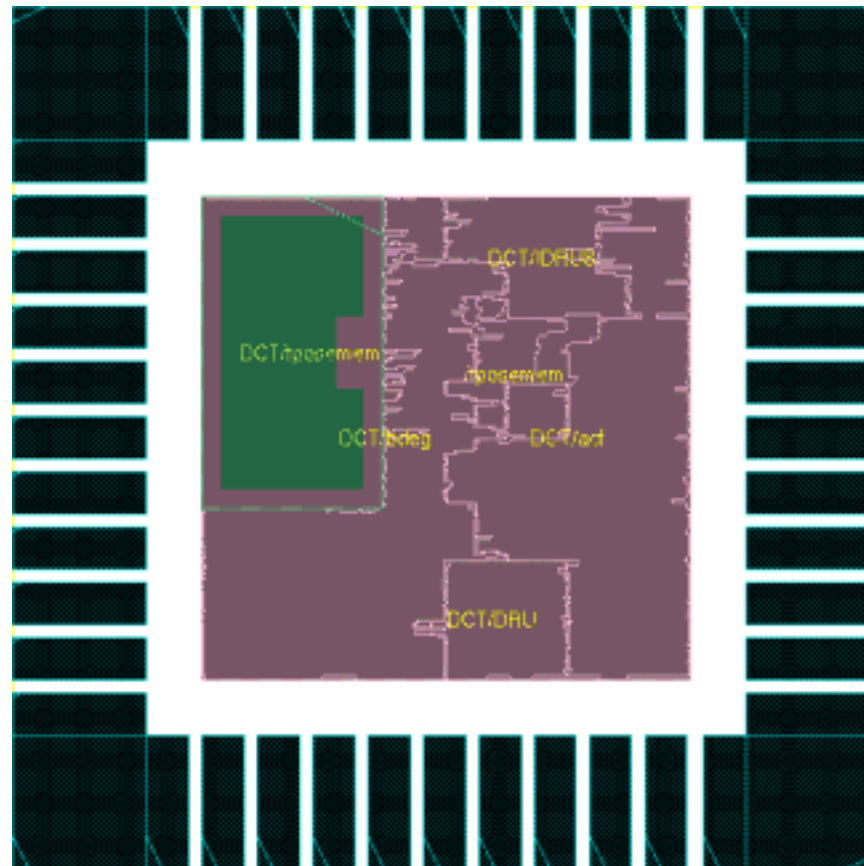


Specify Floorplan

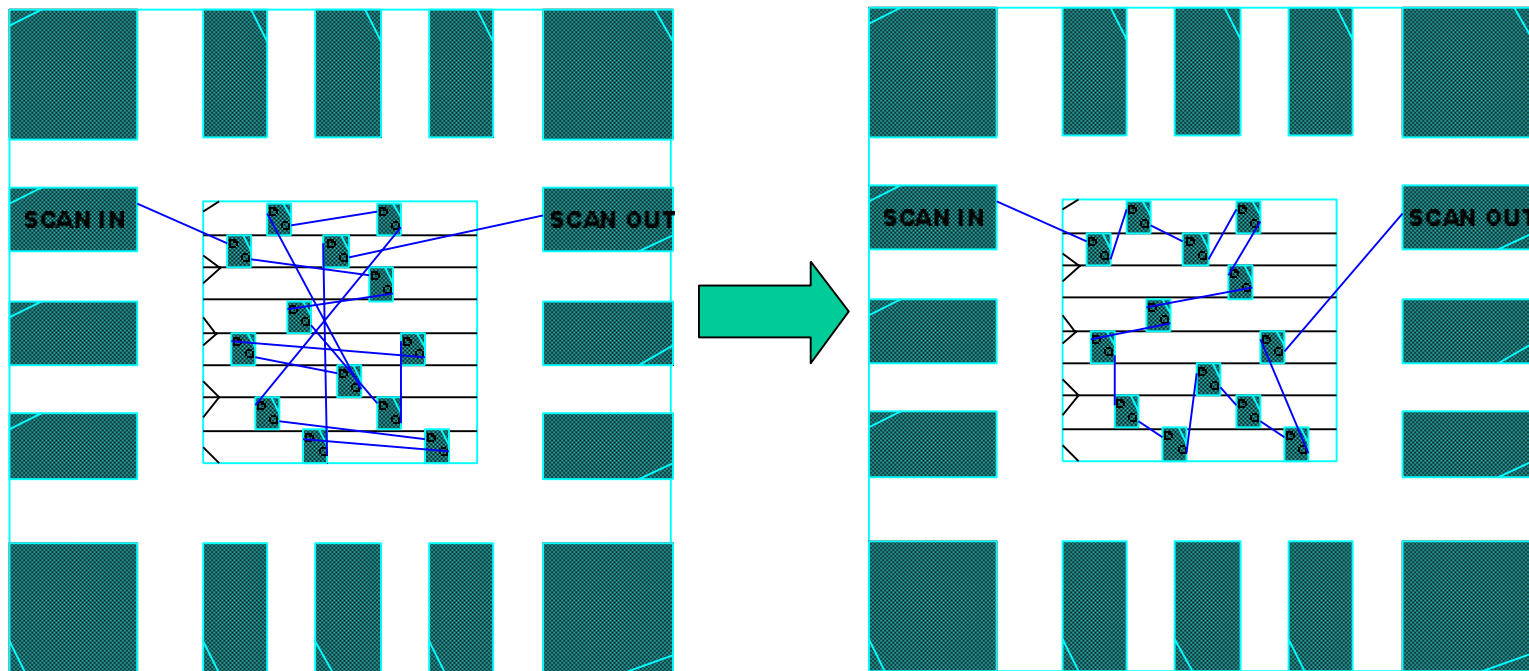




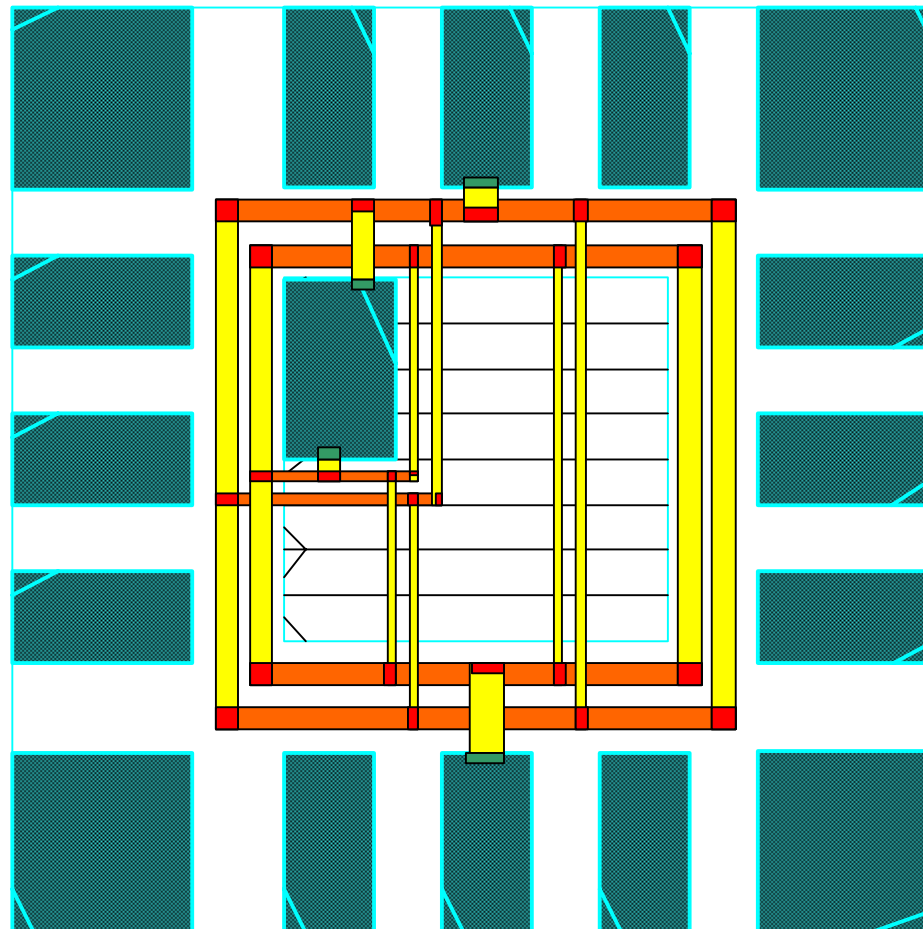
Amoeba Placement



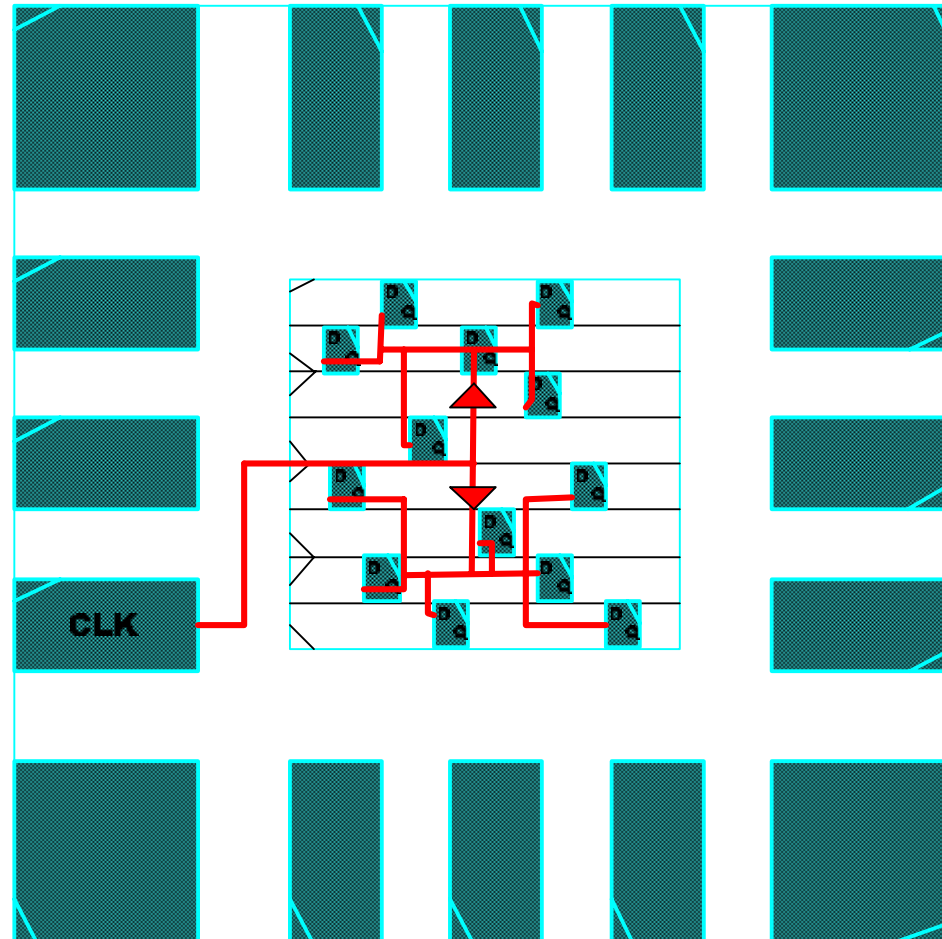
Scan Chain Reorder



Power Planning

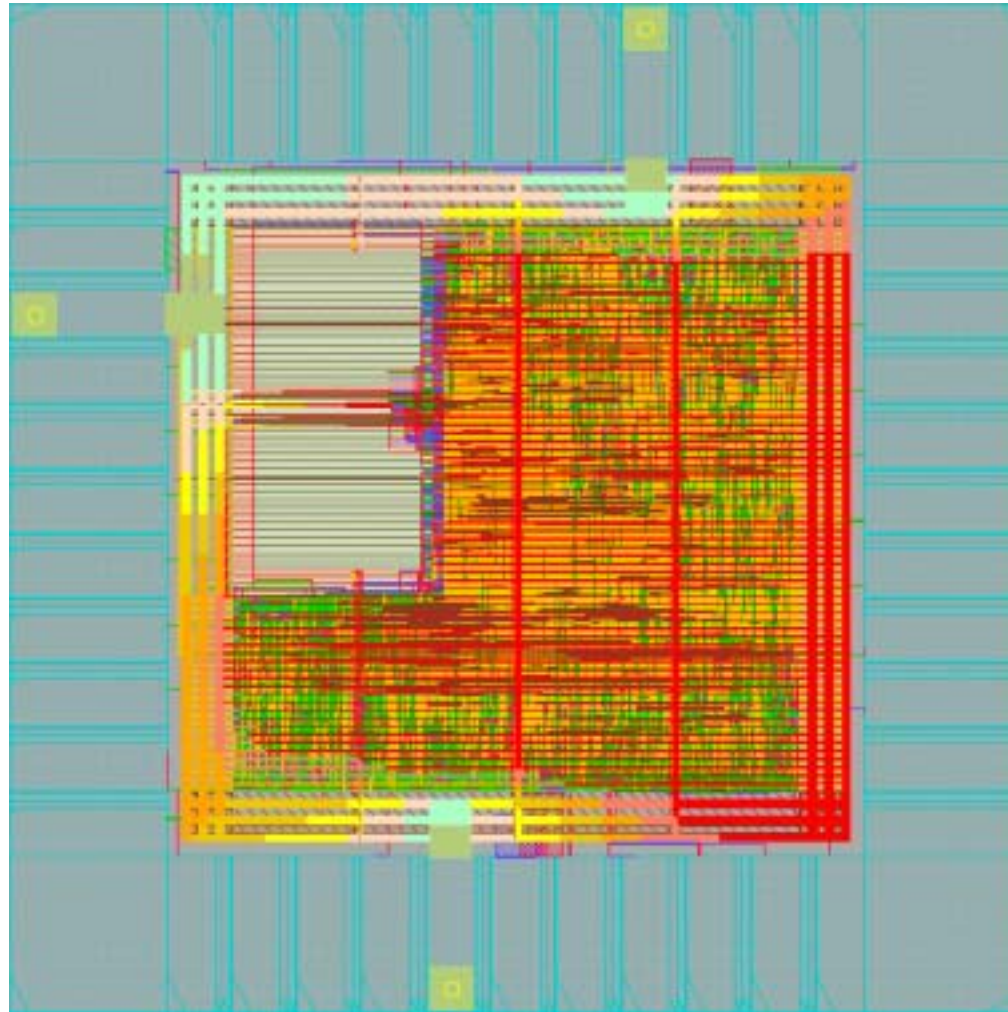


Clock Tree Synthesis

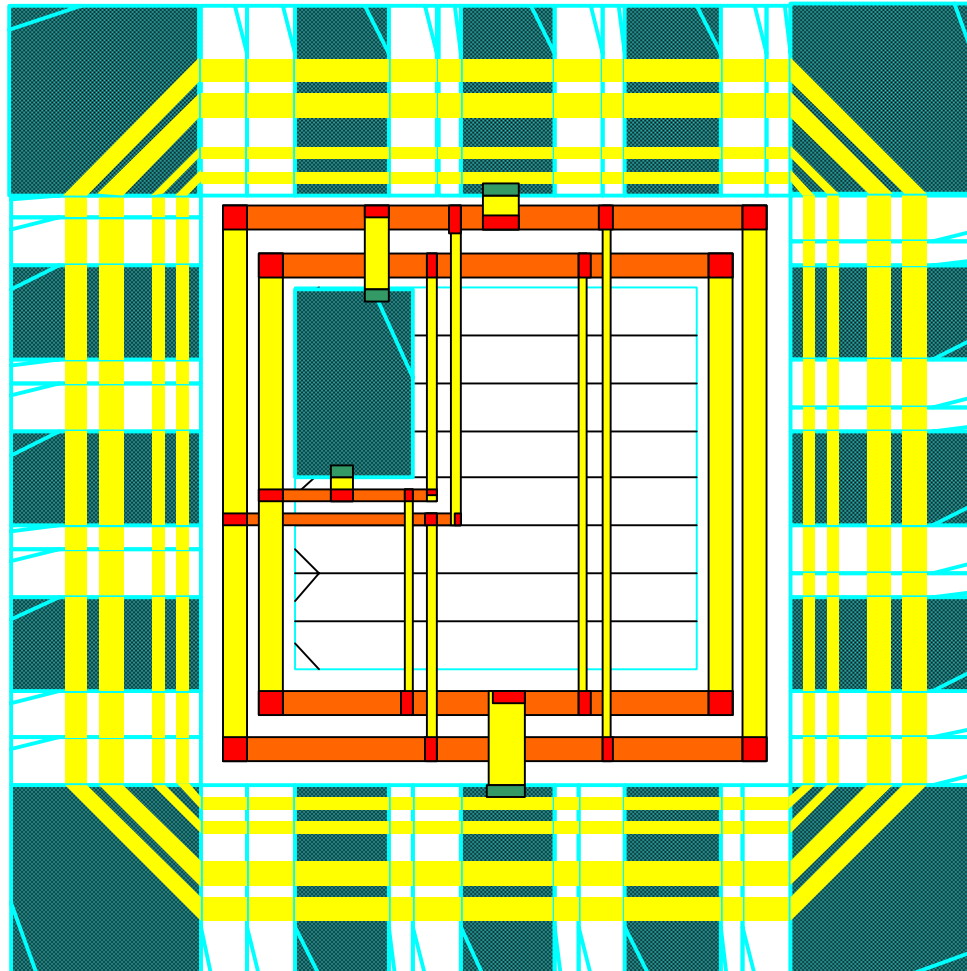




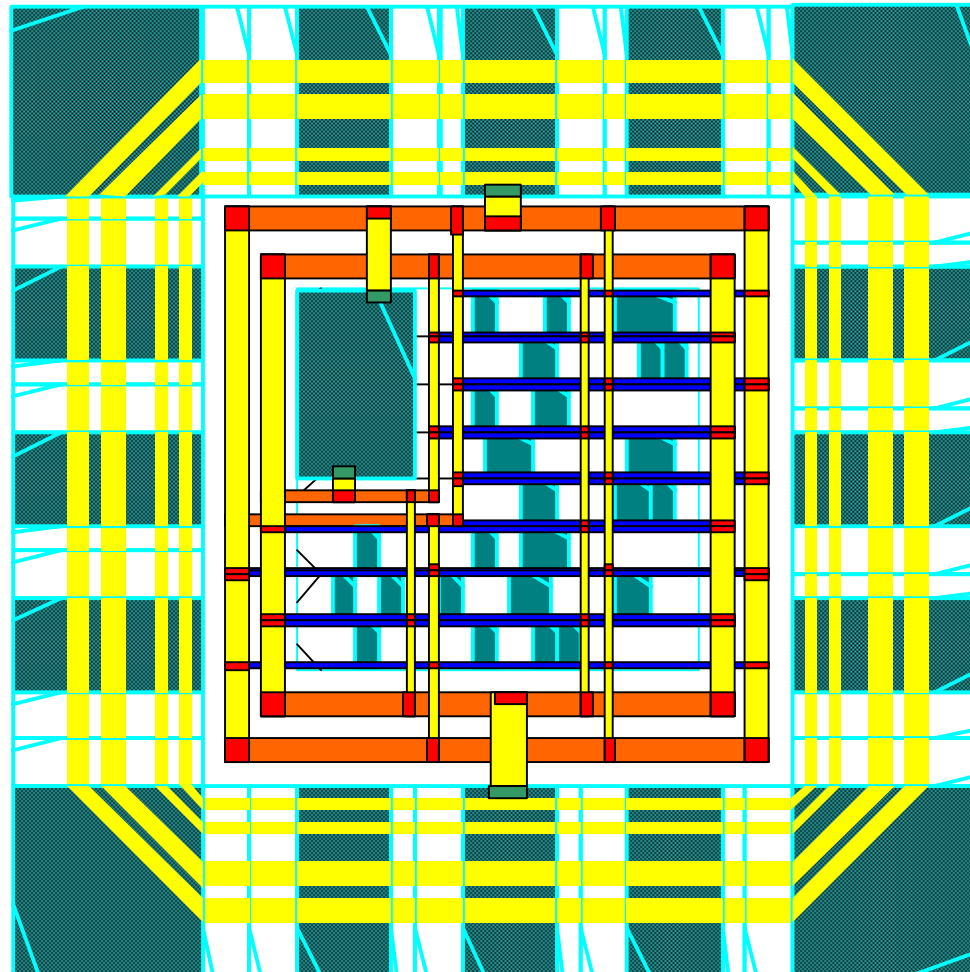
Power Analysis



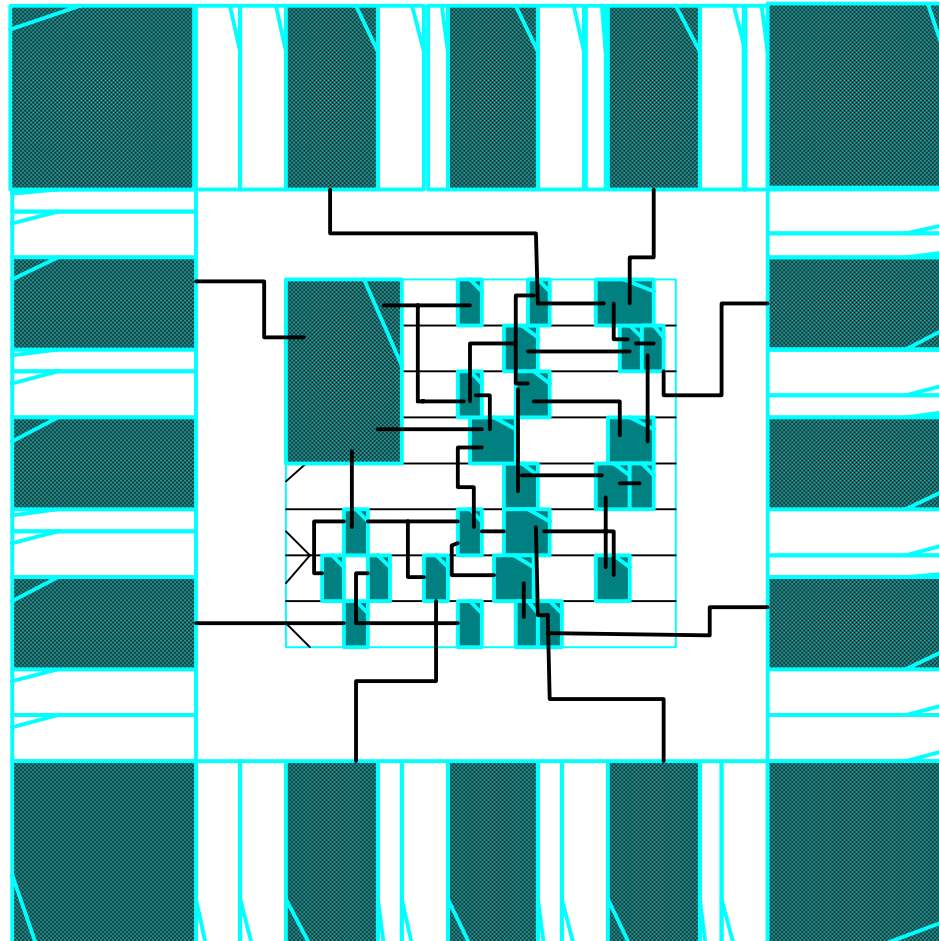
Add Filler



Power Route



Routing





Prepare Data

- ◆ Gate-Level netlist (verilog)
- ◆ Physical Library (LEF)
- ◆ Timing Library (LIB)
- ◆ Timing constraints (sdc)
- ◆ IO constraint








Preparing Data : gate-level netlist

- ◆ If designing a chip , **IO pads** , **power pads** and **Corner pads** should be added before the netlist is imported.
- ◆ Make sure that there is **no** “**assign**” statement and **no** “***cell***” cell name in the netlist.
 - Use the synthesis command below to remove assign statement.
`set_boundary_optimization`
 - Use the synthesis commands below to remove “*cell*” cell name
`define_name_rules name_rule –map { {*cell* cell”} }`
`change_names –hierarchy –output name_rule`



Prepare Data : LEF

-- Process Technology

Layers	Design Rule	Parasitic
 POLY	Net width	Resistance
 Contact	Net spacing	Capacitance
 Metal1	Area	
 Via1	Enclosure	
 Metal2	Wide metal slot	
	Antenna	
	Current density	



Prepare Data: LEF

-- APR technology

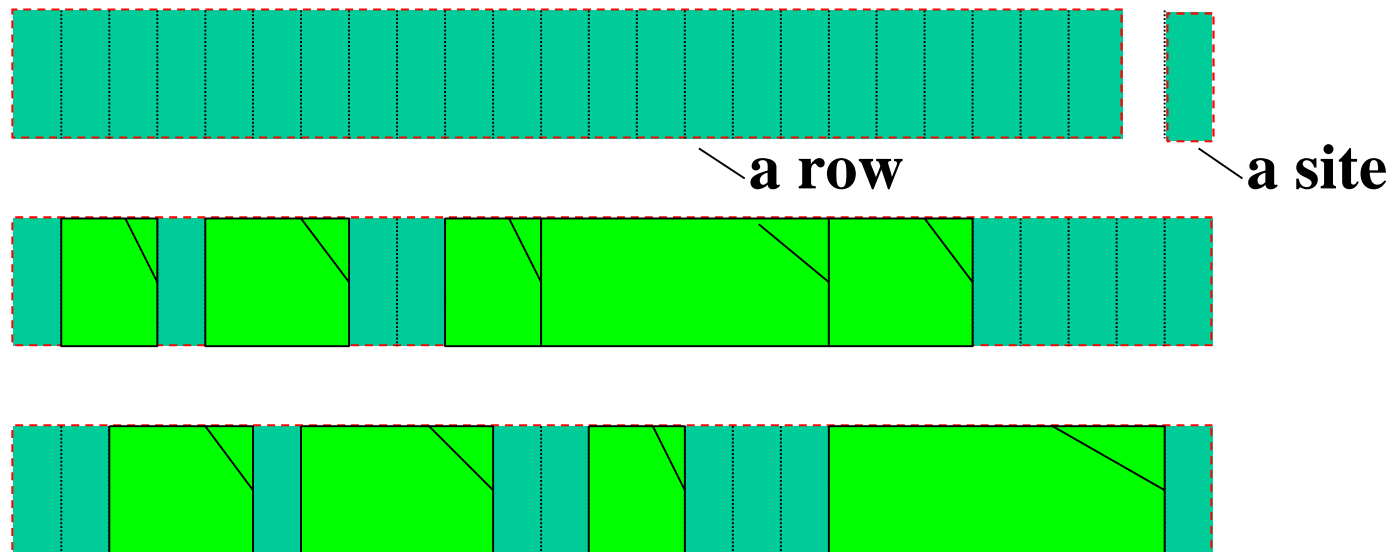
- ◆ Unit
- ◆ Site
- ◆ Routing pitch
- ◆ Default direction
- ◆ Via generate
- ◆ Via stack



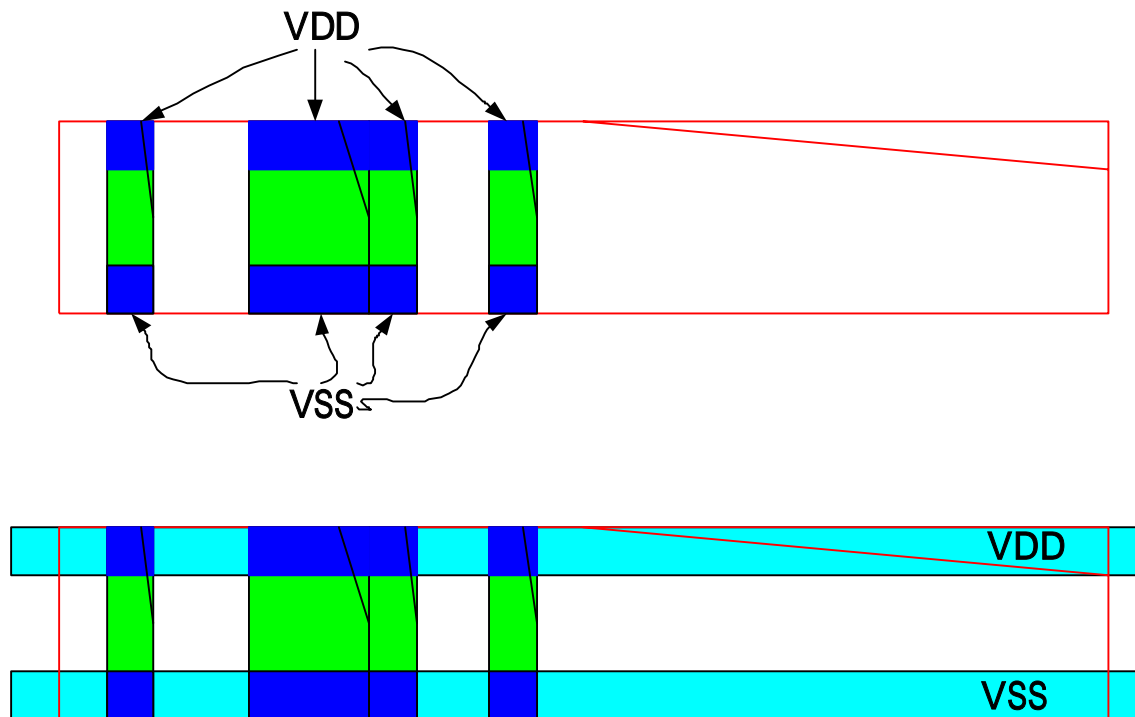
Prepare Data: LEF

-- APR technology : SITE

- The Placement site give the placement grid of a family of macros



Row Based PR

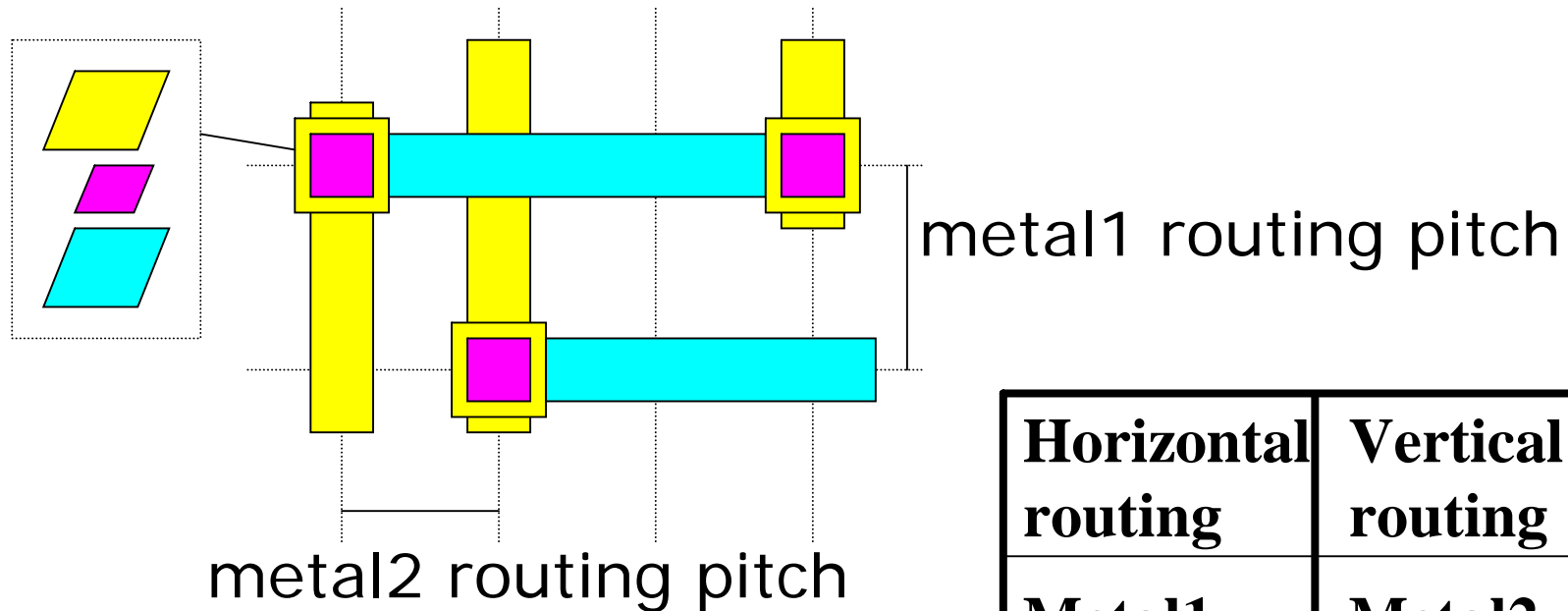




Prepare Data: LEF

-- APR technology :

routing pitch , default direction



Horizontal routing	Vertical routing
Metal1	Metal2
Metal3	Metal4
Metal5	Metal6

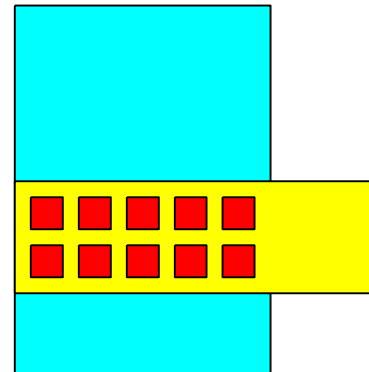


Prepare Data: LEF

-- APR technology : via generate

- ◆ To connect wide metal , create a via array to reduce via resistance
- ◆ Defines formulas for generating via arrays

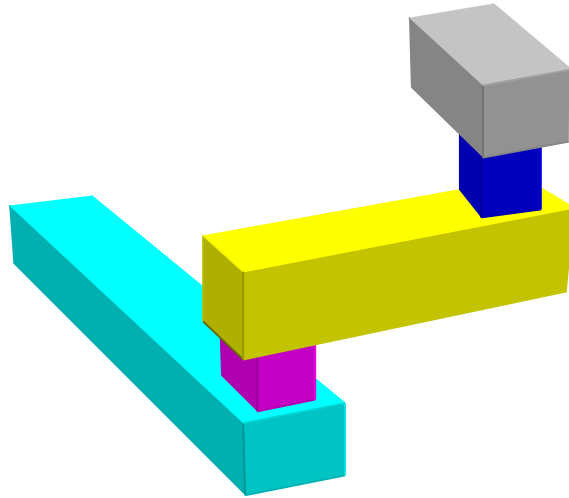
```
Layer Metal1
  Direction HORIZONTAL
  OVERHANG 0.2
Layer Metal2
  Direction VERTICAL
  OVERHANG 0.2
Layer Via1
  RECT -0.14 -0.14 0.14 0.14
  SPACING 0.56 BY 0.56
```



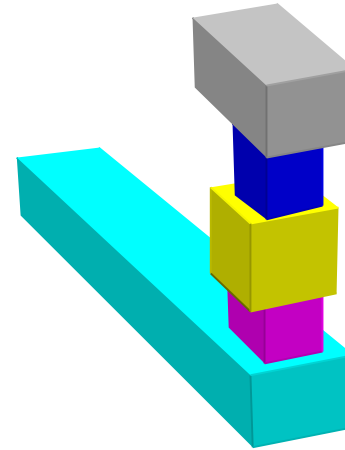


Prepare Data: LEF

-- APR technology : via stack



Without via stack



With via stack

- ◆ Higher density routing
- ◆ Easier usage of upper layer
- ◆ Must Follow minimum area rule



Prepare Data: LEF

-- APR technology : Physical Macros

◆ Define physical data for

- Standard cells
- I/O pads
- Memories
- other hard macros

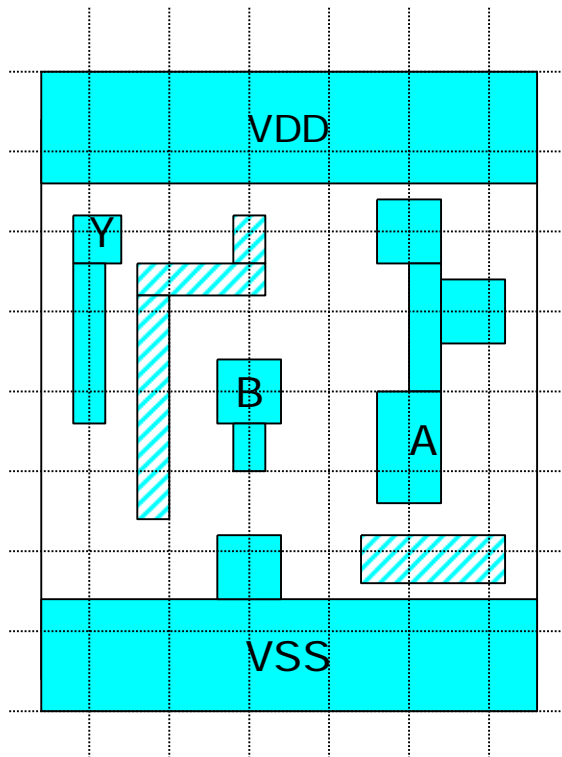
◆ describe abstract shape

- Size
- Class
- Pins
- Obstructions



Prepare Data: LEF

-- APR technology : Physical Macros cont.



```

MACRO ADD1
  CLASS CORE ;
  FOREIGN ADD1 0.0 0.0 ;
  ORIGIN 0.0 0.0 ;
  LEQ ADD ;
  SIZE 19.8 BY 6.4 ;
  SYMMETRY x y ;
  SITE coresite
  PIN A
    DIRECTION INPUT ;
  PORT
    LAYER Metal1 ;
    RECT 19.2 8.2 19.5 10.3

    .....
  END
END A
OBS
    .....
  END
END ADD1
  
```



Prepare Data: LIB

- ◆ Operating condition
 - slow, fast, typical
- ◆ Pin type
 - input/output/inout
 - function
 - data/clock
 - capacitance
- ◆ Path delay
- ◆ Timingconstraint
 - setup, hold, mpwh, mpwl, recovery



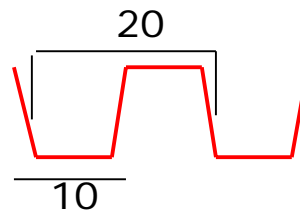
Prepare Data: Timing constraint

- ◆ Create clock
- ◆ Input delay
- ◆ Output delay
- ◆ Input drive
- ◆ Output loading

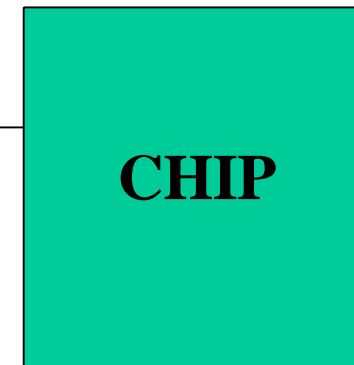


Prepare Data: Timing constraint -- Create Clock

```
create_clock [-name clock_name]
             -period period_value
             [-waveform edge_list]
             [clock_source_list]
```



I_CLK

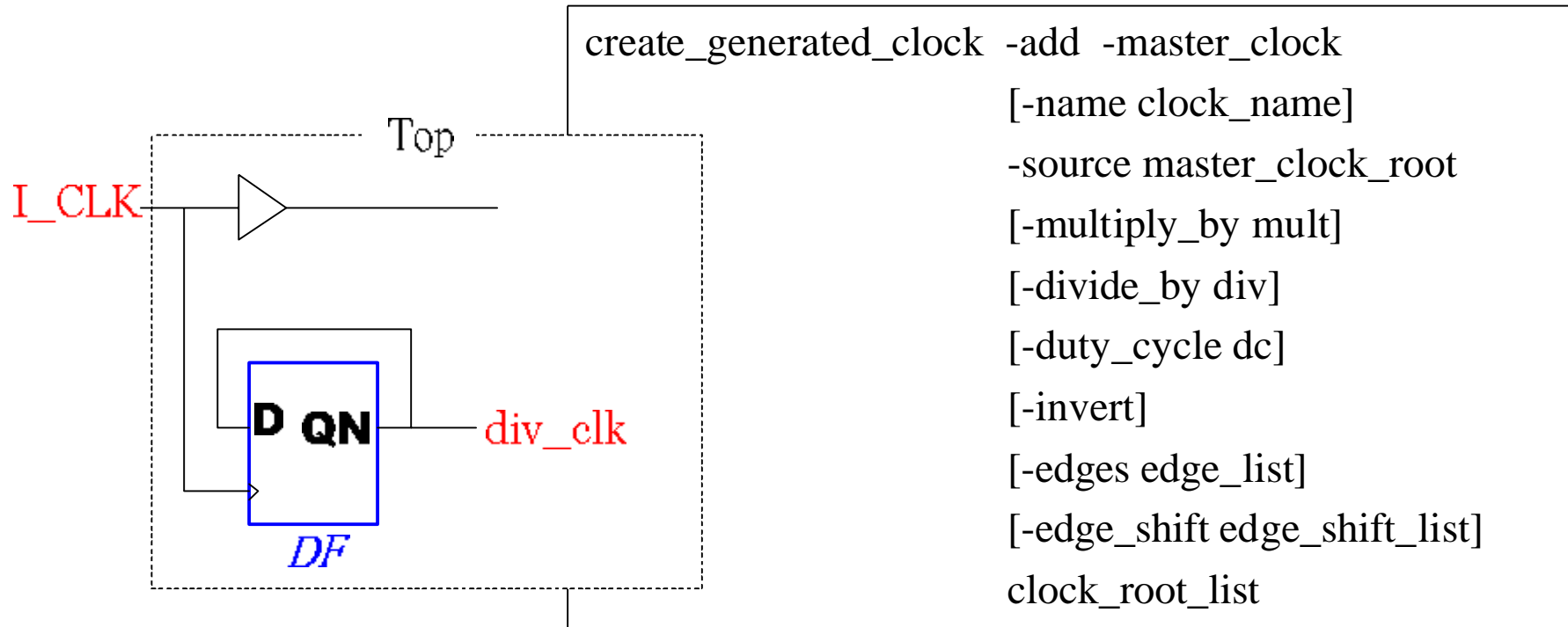


```
create_clock -name CLK1 -period 20 -waveform {0 10} [get_ports I_CLK]
```



Prepare Data: Timing constraint

-- create_generated_clock

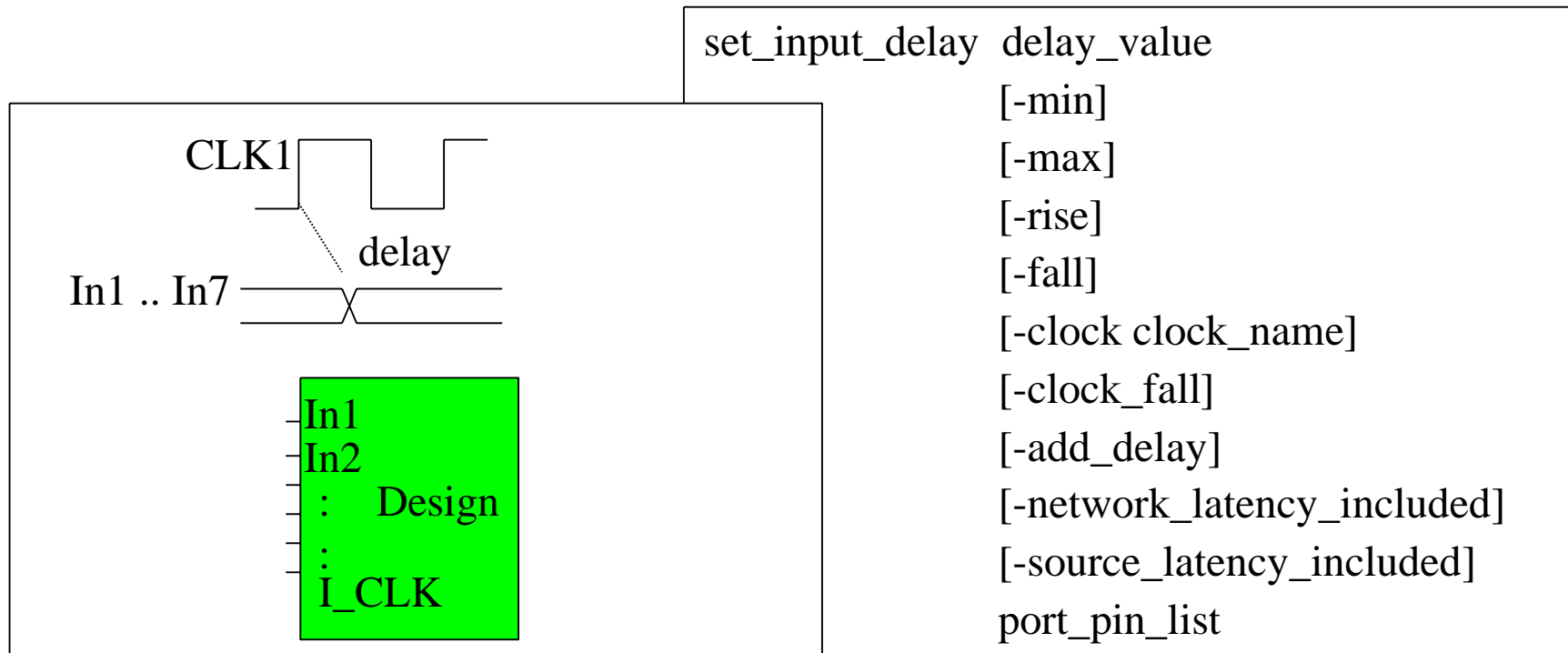


```
create_generated_clock -name CLK2 -source [get_ports I_CLK] -divide_by 2 [get_pins DF/QN]
```



Prepare Data: Timing constraint

--set_input_delay

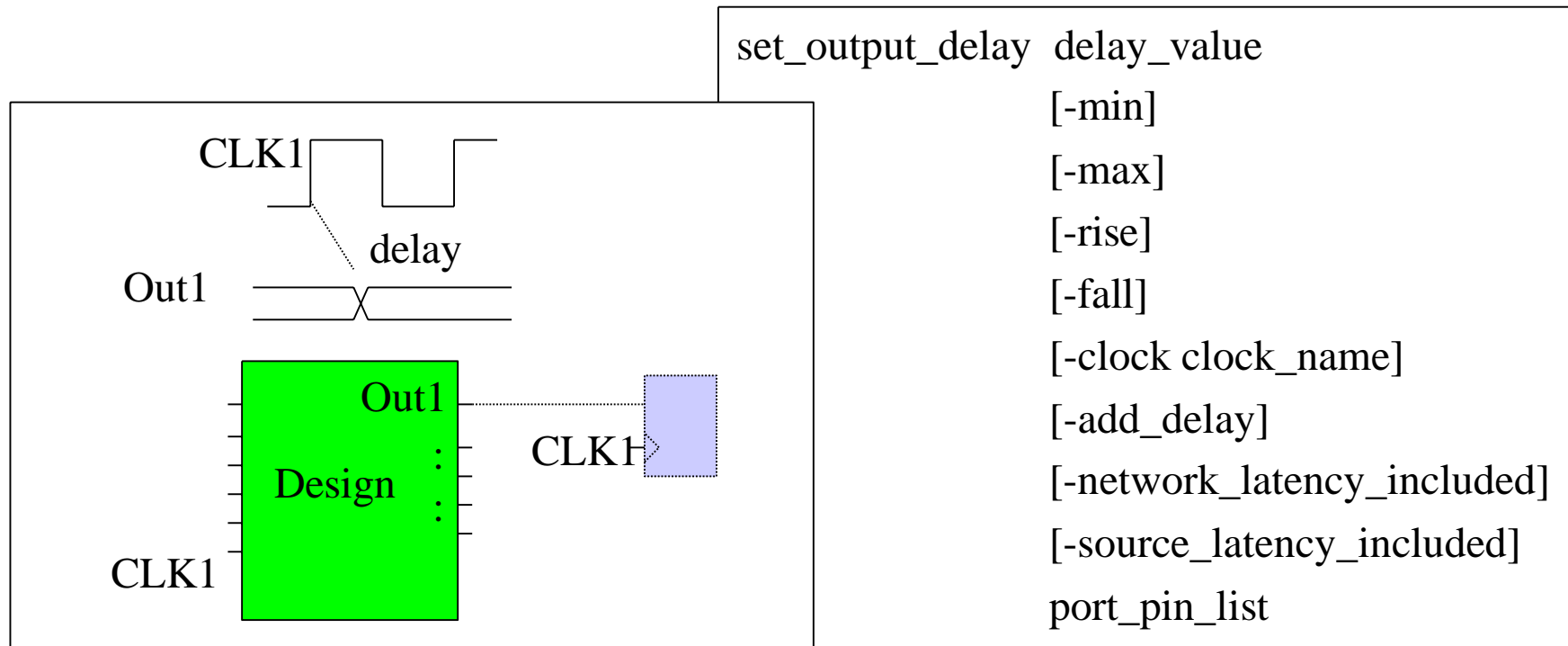


```
set_input_delay 1 -clock [get_clocks {CLK1}] [getports {In1}]
```



Prepare Data: Timing constraint

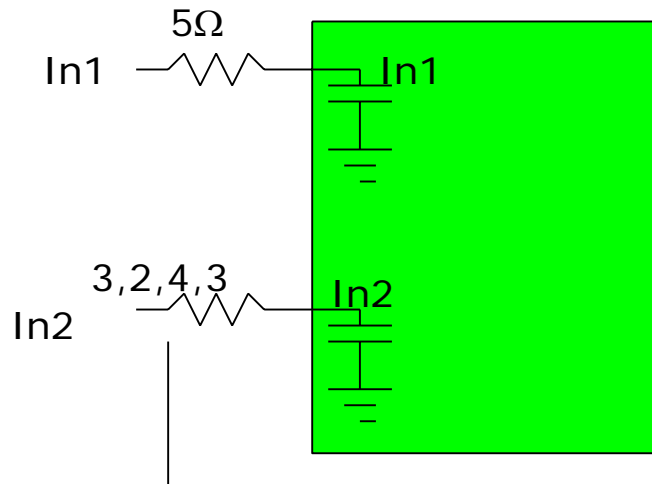
--set_output_delay



```
set_output_delay 1 -clock [get_clocks {CLK1}] [getports {Out1}]
```



Prepare Data: Timing constraint --set_drive



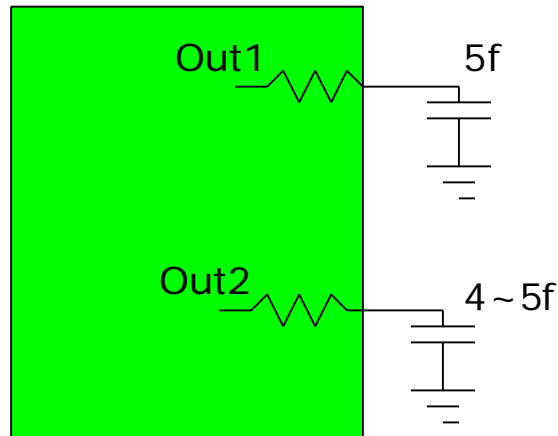
rise_min, rise_max, fall_min, fall_max

```
set_drive 1 [get_ports {In1}]
```

```
set_drive [-min]
          [-max]
          [-rise]
          [-fall]
          drive_strength
          port_list
```



Prepare Data: Timing constraint --set_load



```
set_load [-min]
         [-max]
         [-pin_load]
         [-wire_load]
         load_value
         port_list
```

```
set_load 1 [get_ports {Out1}]
```



Prepare Data: IO constraint

◆ Create an I/O assignment file manually using the following template:

```
Version: 1
MicronPerUserUnit: value
Pin: pinName side |corner
Pad: padInstanceName side|corner [cellName]
Offset: length
Skip: length
Spacing: length
Keepclear: side offset1 offset2
```



Prepare Data: IO constraint cont.

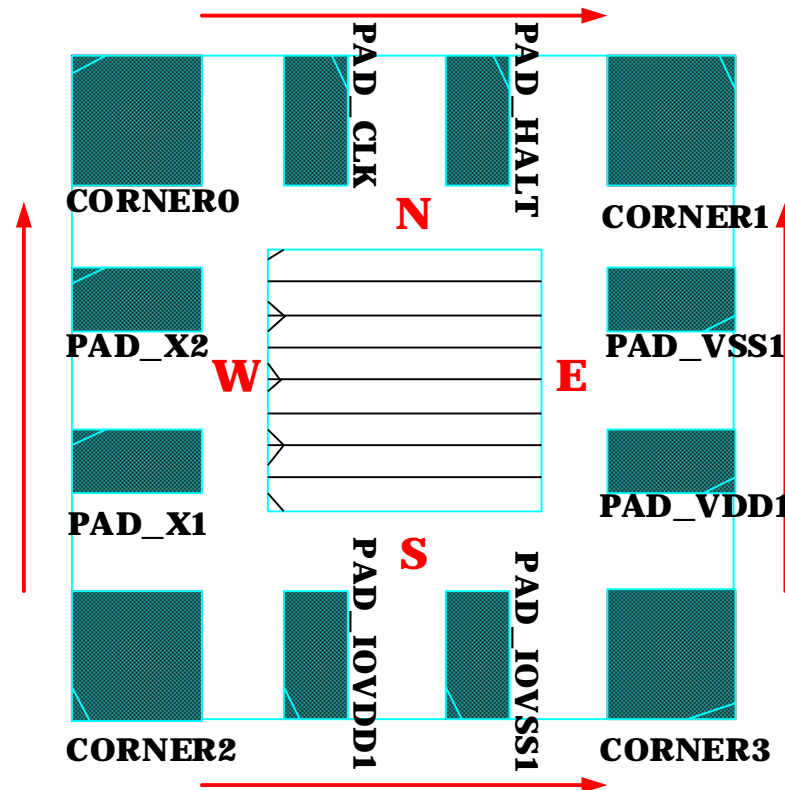
Version: 1

Pad: CORNER0 NW
 Pad: PAD_CLK N
 Pad: PAD_HALT N

Pad: CORNER1 NE
 Pad: PAD_X1 W
 Pad: PAD_X2 W

Pad: CORNER2 SW
 Pad: PAD_IOVDD1 S
 Pad: PAD_IOVSS1 S

Pad: CORNER3 SE
 Pad: PAD_VDD1 E
 Pad: PAD_VSS1 E



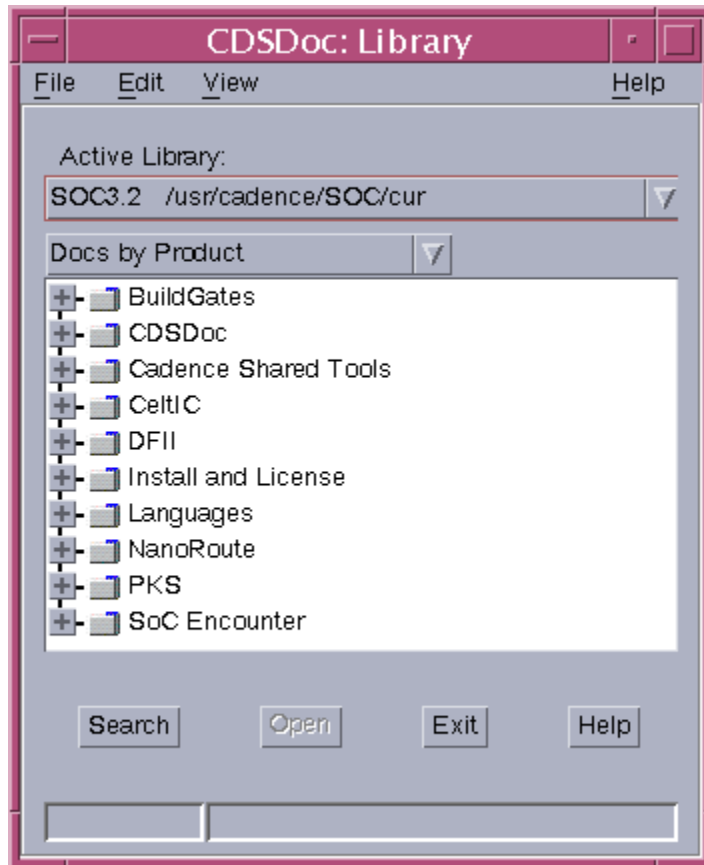


Tips to Reduce the Power/Ground Bounce

- ◆ Don't use stronger output buffers than what is necessary
- ◆ Use slew-rate controlled outputs
- ◆ Place power pad near the middle of the output buffer
- ◆ Place noise sensitive I/O pads away from SSO I/Os
- ◆ Place VDD and VSS pads next to clock input buffer
- ◆ Consider using double bonding on the same power pad to reduce inductance



Cadence On-Line document



unix% /usr/cadence/SOC/cur/tools/bin/cdsdoc &
unix% /usr/cadence/IC/cur/tools/bin/cdsdoc &
unix% /usr/cadence/LDV/cur/tools/bin/cdsdoc &

.....

- ◆ html browser must be installed
- ◆ do not set the proxy in html browser

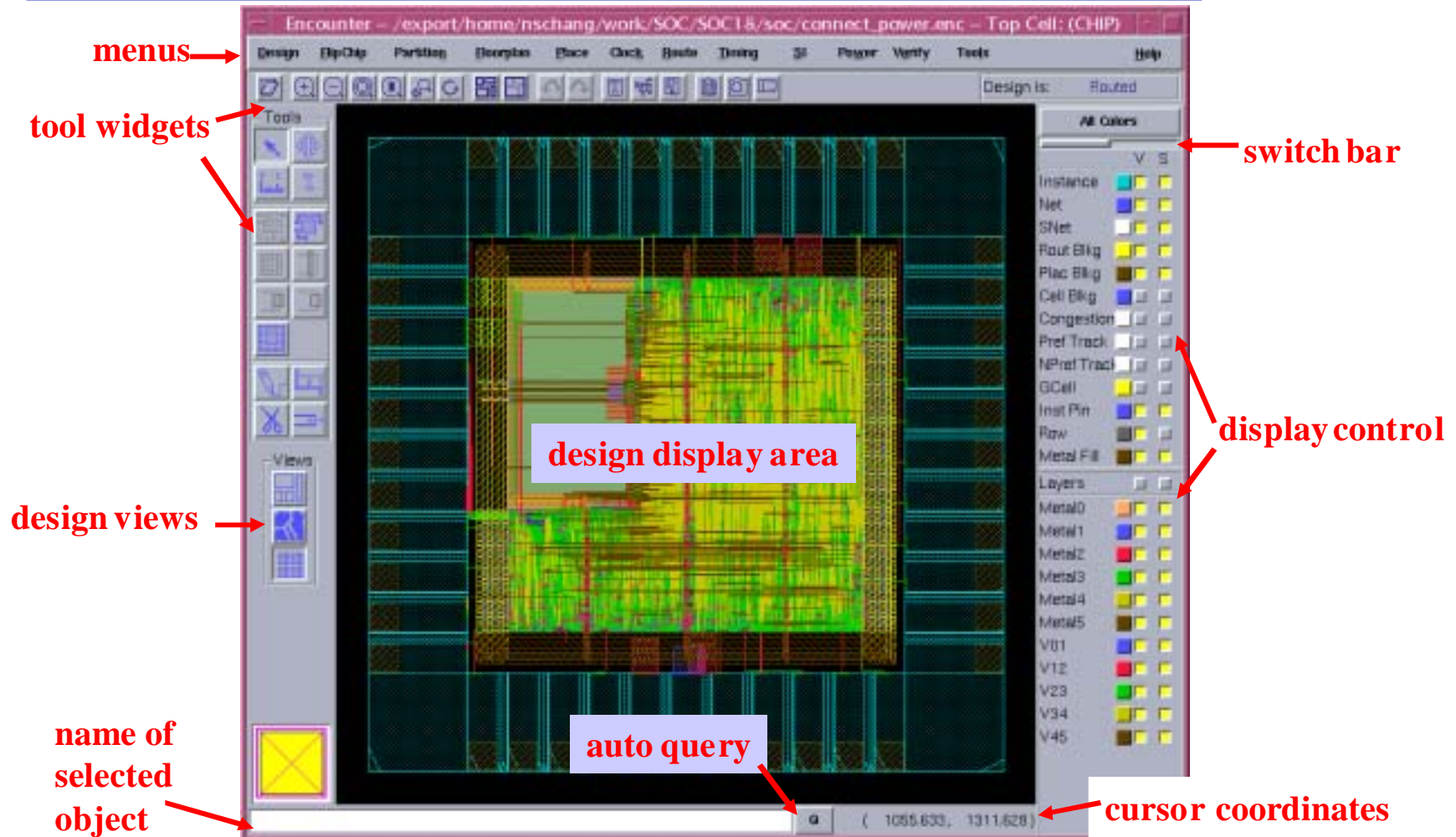


Getting Started

- ◆ Source the encounter environment:
`unix% source /usr/cadence/cic_setup/soc.csh`
- ◆ Invoke soc encounter in 64 bit mode:
`unix% encounter -64`
- ◆ Do **not** run in background mode. Because the terminal become the interface of command input while running soc encounter.
- ◆ The Encounter reads the following initialization files:
 - \$ENCOUNTER/etc/enc.tcl
 - ./enc.tcl
 - ./enc.pref.tcl
- ◆ Log file:
 - encounter.log*
 - encounter.cmd*

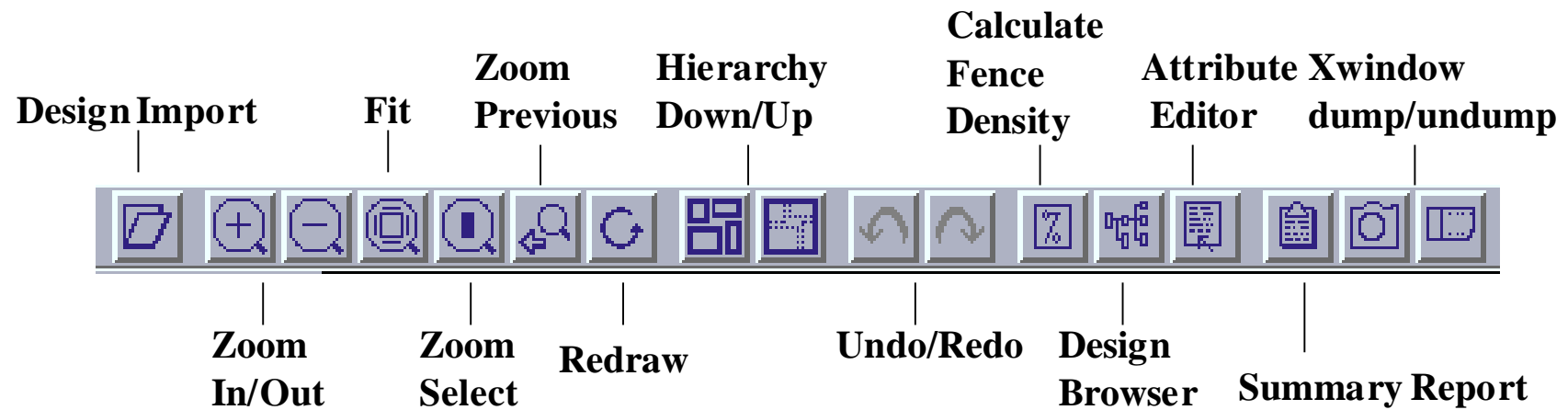


GUI





Tool Wedgits





Design Views



◆ Floorplan View

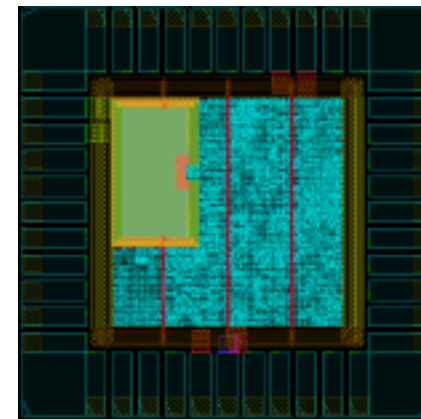
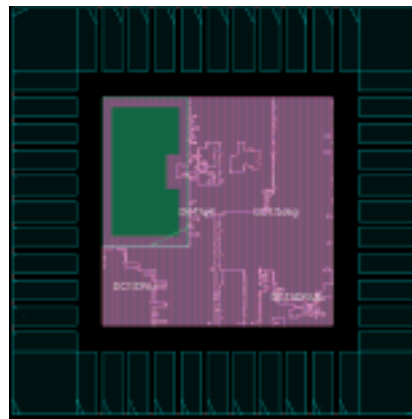
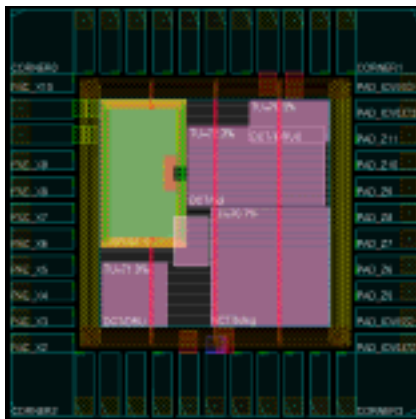
- displays the hierarchical module and block guides, connection flight lines and floorplan objects

◆ Amoeba View

- display the outline of modules after placement

◆ Placement View

- display the detailed placements of cells, blocks.





Display Control

Select Bar

All Colors

V
S

Module			
Black Box			
Fence			
Guide			
Obstruct			
Region			
Screen			
Instance			
Net			
SNet			
Pin			
Ruler			
VCongest			
HCongest			
Text			

All Colors

V
S

Instance			
Net			
SNet			
Rout Blkg			
Plac Blkg			
Cell Blkg			
Congestion			
Pref Track			
NPref Track			
GCell			
Inst Pin			
Row			
Metal Fill			

Layers

Metal0			
Metal1			
Metal2			
Metal3			
Metal4			
Metal5			
V01			
V12			
V23			
V34			
V45			



Common Used Bindkeys

Key	Action
q	Edit attribute
f	Fits display
z	Zoom in
Z	Zoom out
Arrows	pans design area in the direction of the arrow
Delete	Removes the last ruler
Esc	Removes all rulers

Key	Action
d	popup Delete
e	popup Edit
T	editTrim
0-9	View layer [0-9]
h	hierarchy up
H	hierarchy down

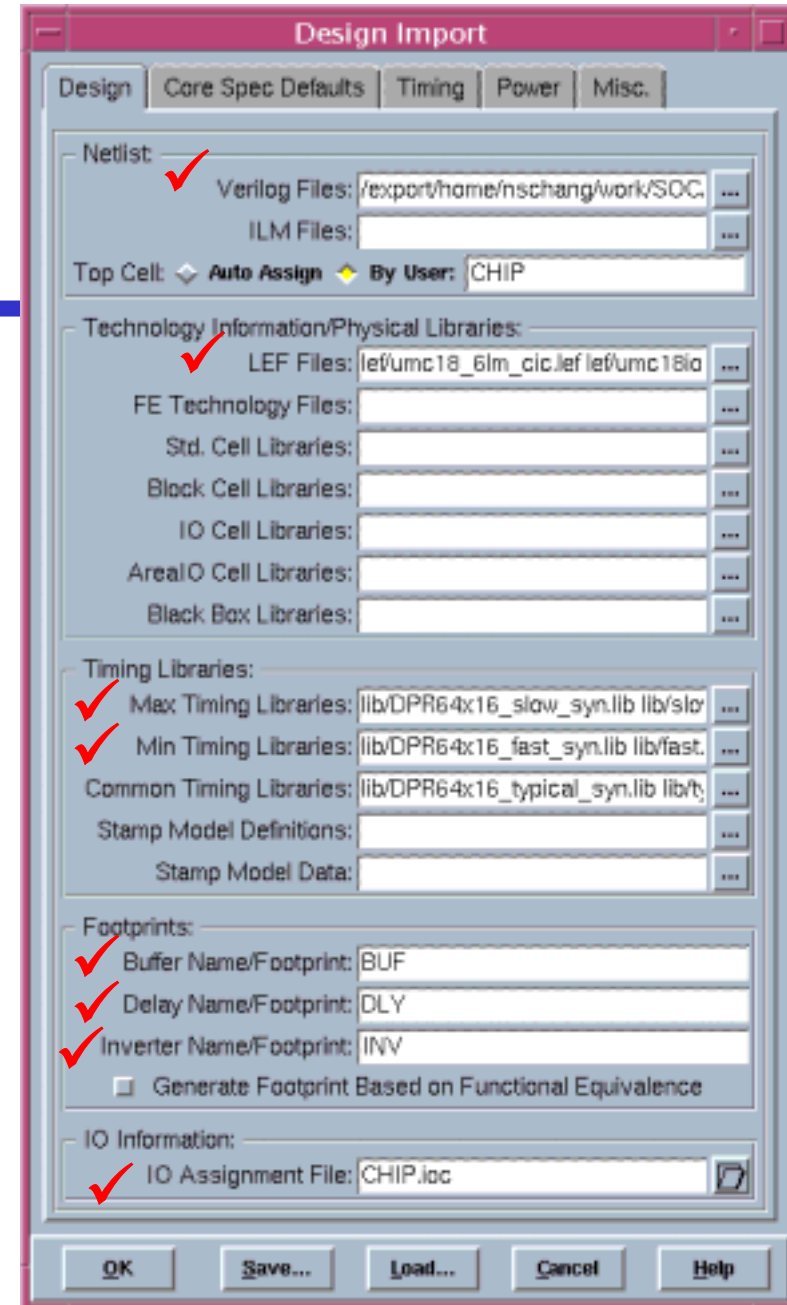
Looking for more bindkey:
Design->Preference, Binding Key



Import Design

Design → Design Import...

- ◆ Max Timing Libraries
 - containing worst-case conditions for setup-time analysis
- ◆ Min Timing Libraries
 - containing best-case conditions for hold-time analysis
- ◆ Common Timing Libraries
 - used in both setup and hold analysis
- ◆ IO Assignment File:
 - get a IO assignment template:
Design → Save → I/O File...





Import Design cont.

◆ Buffer Name/Footprint:

- specifies the buffer cell family to be inserted or swapped.
- required to run IPO and TD placement.

◆ Delay Name/Footprint:

- required to run a fix hold time violation

◆ Inverter Name/Footprint:

- required to run IPO and TD placement.

◆ Get footprint of library cells by:

- *Timing → Report → Cell Footprint*

Footprint Example:

For Cells:

BUFXL

BUFX1

BUFX2

BUFX3

BUFX4

BUFX8

BUFX12

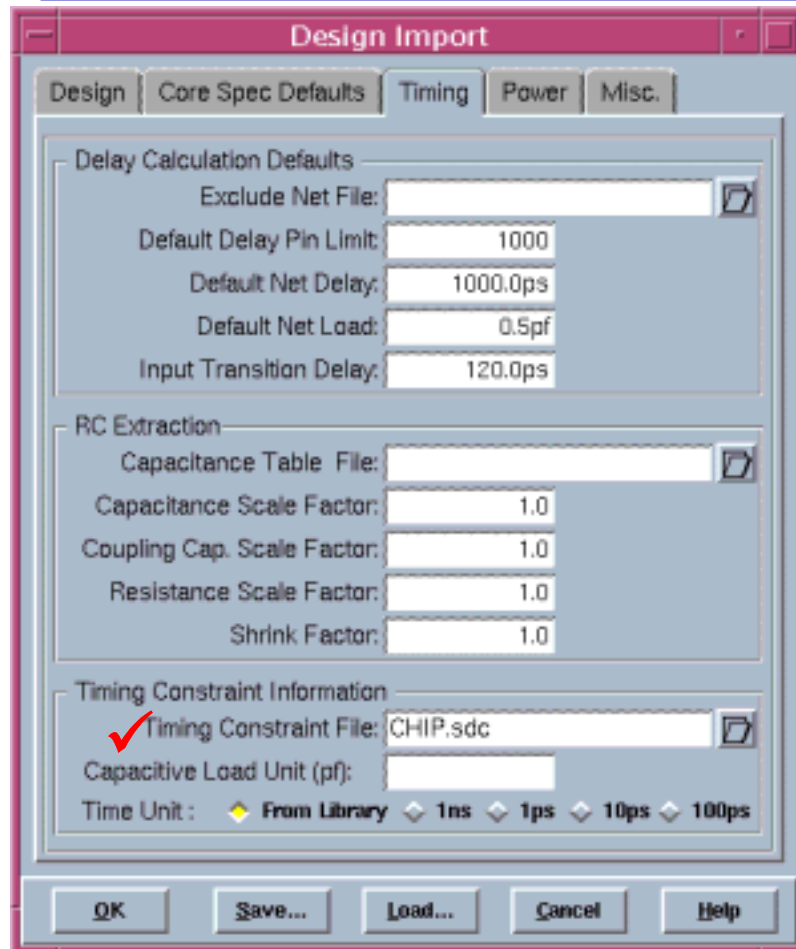
BUFX16

BUFX20

Footprint : buf



Import Design -- Timing



◆ Default Delay Pin Limit:

- Nets with terminal counts greater than the specified value are assigned the default net delay and net load entries.

◆ Default Net Delay:

- Set the delay values for a net that meets the pin limit default.

◆ Default Net Load:

- Set the load for a net that meets the pin limit default.

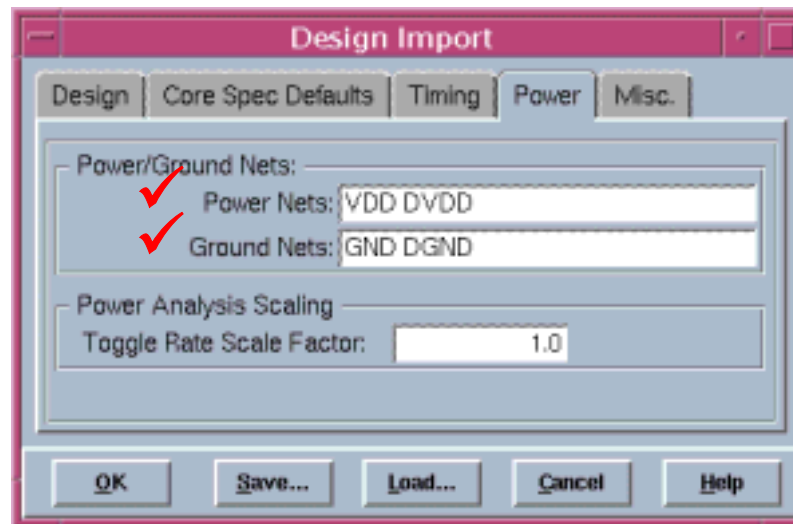
◆ Input Transition Delay:

- Set the Primary inputs and clock nets.



Import Design -- Power

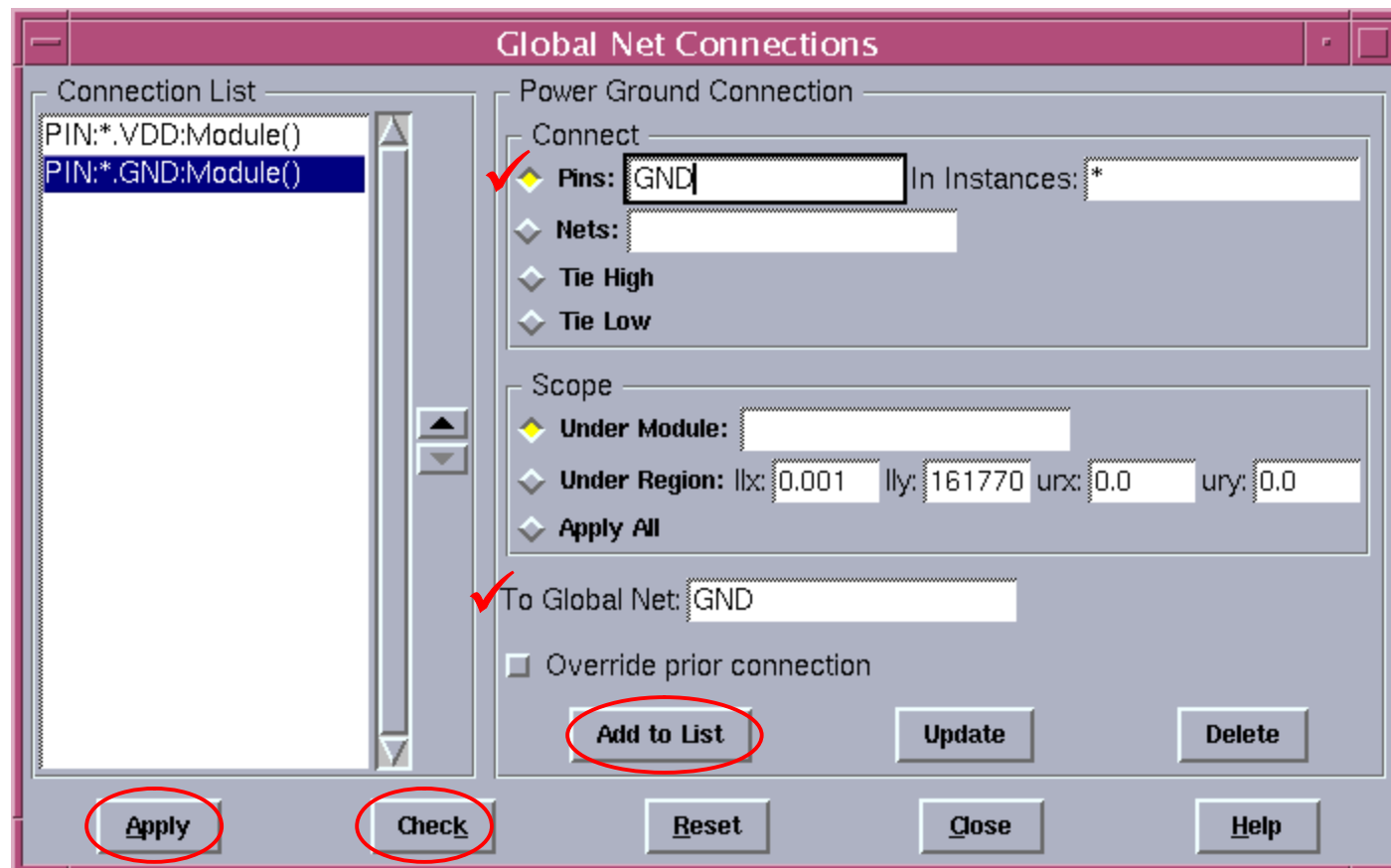
- ◆ Specify the names of Power Nets and Ground Nets





Global Net Connection

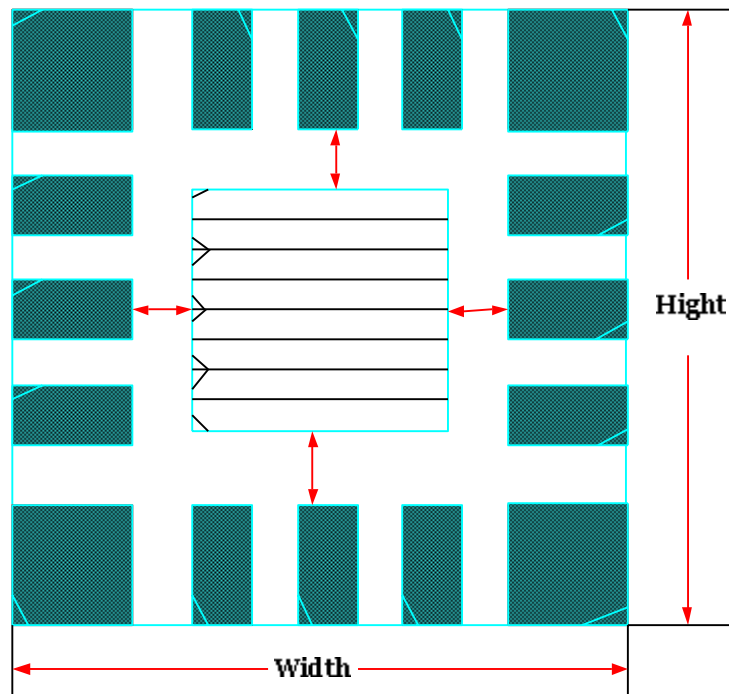
Floorplan → Gloval Net Connections...





Specify Floorplan

Floorplan → Specify Floorplan ...



Specify Floorplan

Design Dimensions

Specify Dimensions by:

Size by:

Core Size by: ☒ Aspect Ratio: ☒ Ratio (H/W): 0.99300209

Core Utilization: 0.711806

Width and Height: Core Height: 700.56
Core Width: 705.497

Die Size by: Width and Height Die Height: 1251.12
Die Width: 1255.617

Core Margins by: ☒ Core to IO Boundary

Core to Die Boundary

Core to Left: 80.32 Core to Top: 80.7
Core to Right: 80.0 Core to Bottom: 80.06

Die Size Calculation Use: ☐ Max IO Height
☒ Min IO Height

Floorplan Origin at: ☒ Lower Left Corner
☐ Center

Die/IO/Core Coordinates:

Die LL:	0.0	0.0	UR:	1255.617	1251.12
IO LL:	194.9	194.9	UR:	1060.717	1056.22
Core LL:	275.22	274.96	UR:	980.717	975.52

unit: micron

Standard Cell Rows

Double-back rows: ☒ Bottom row orient: ☐

Row Spacing: 0.0 um For Every 2 Row

Row height: 5.04

IO Specifications

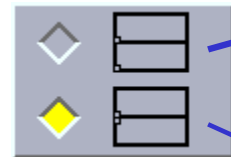
Bottom IO Pad Orientation: ☐

OK Apply Cancel Help

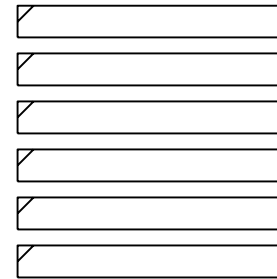


Specify Floorplan – Double back rows

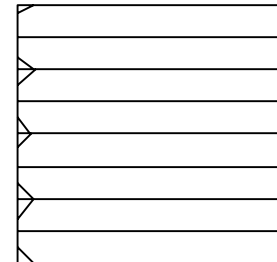
Double-back rows:



Row Spacing > 0

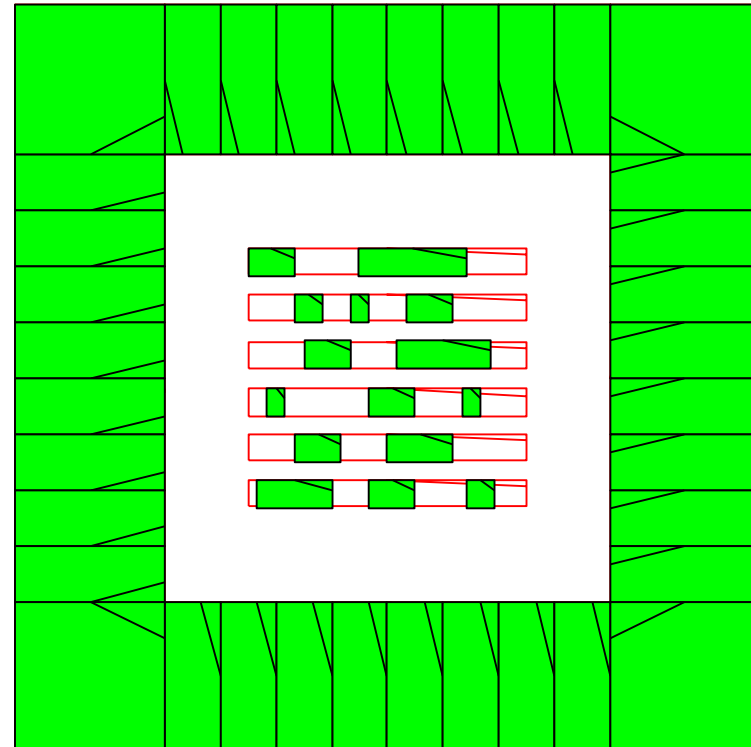
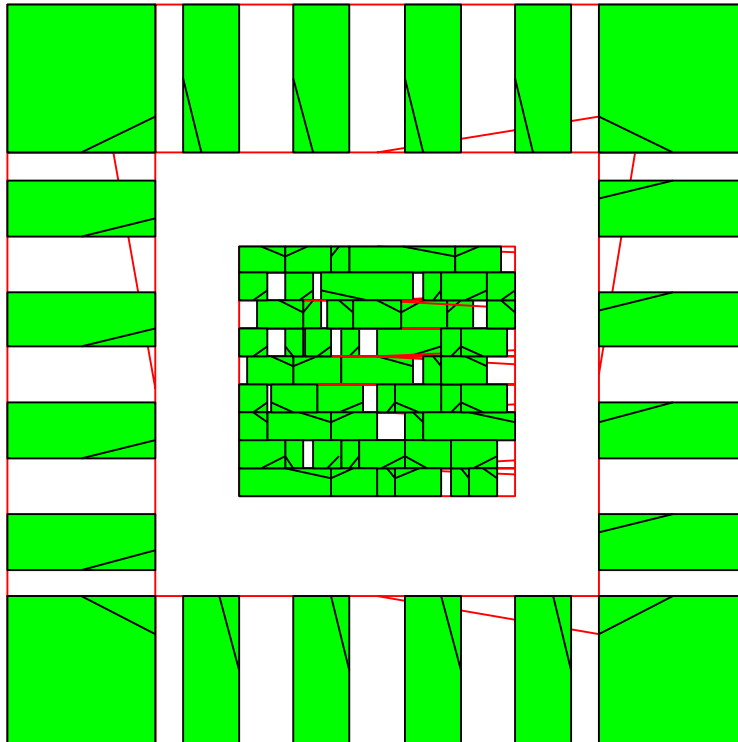


Row Spacing = 0





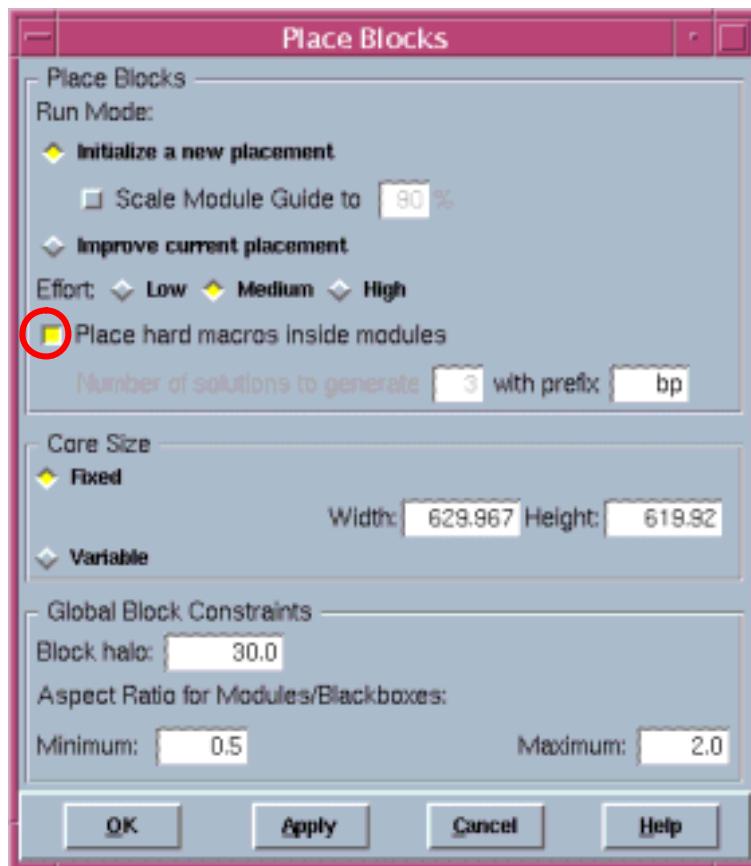
Core Limit, I/O Limit





Place Blocks


Floorplan → Place Blocks/Modules → Place ...



- ◆ automatic place blocks (blackboxes and partitions) and hard macros at the top-level design.
- ◆ Block halo
 - Specifies the minimum amount of space around blocks that is preserved for routing.



Manually Place Block

- ◆  Move/Resize/Reshape floorplan object.
- ◆ Use functions in : *Floorplan* → *Edit Floorplan* to edit floorplan.

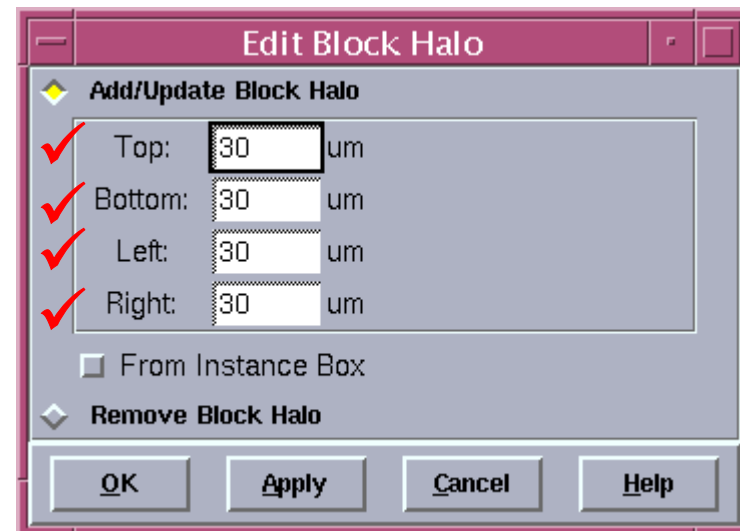
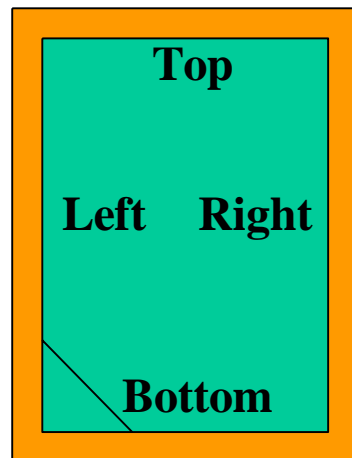
Align Instances...
Shift Instances...
Space Instances...
Flip/Rotate Instances...
Snap Floorplan...
Legalize Floorplan...
Set Block Placement Status...
- ◆ Set placement status of all pre-placed block to *preplaced* in order to avoid these blocks be moved by amoebaPlace later.
- ◆ *Floorplan* → *Edit Floorplan* → *Set Block Placement Status ...*



Add Halo To Block

Floorplan → Edit Block Halo...

- ◆ Prevent the placement of blocks and standard cells in order to reduce congestion around a block.





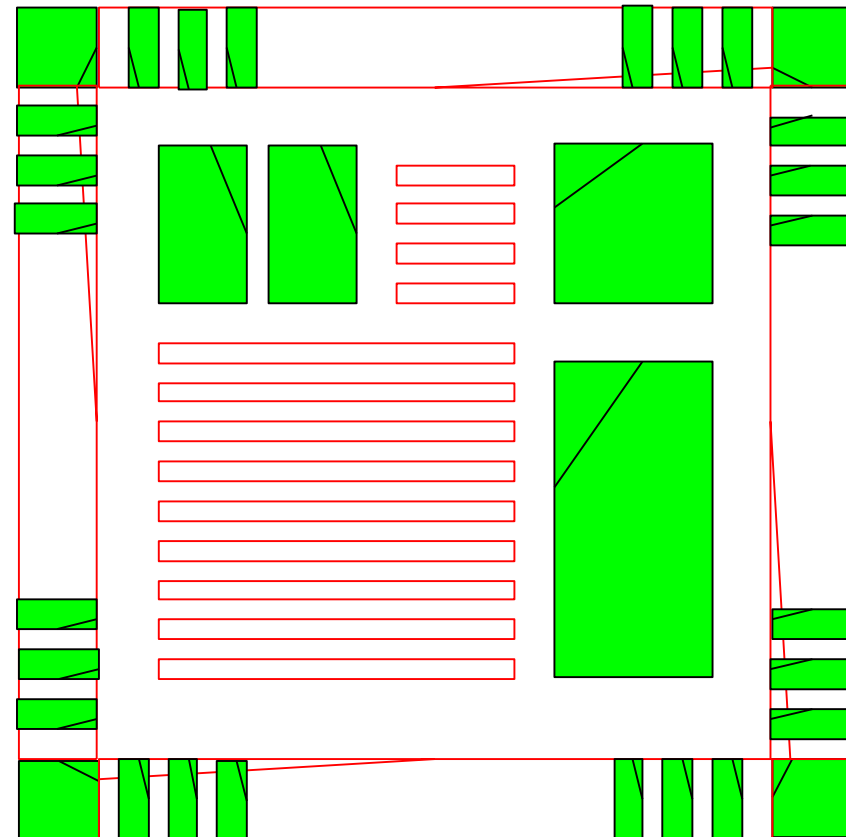
Block Placement

◆ Flow step

- I/O pre-placed
- Run quick block placement
- Throw away standard cell placement
- Manually fit blocks

◆ Block place issue

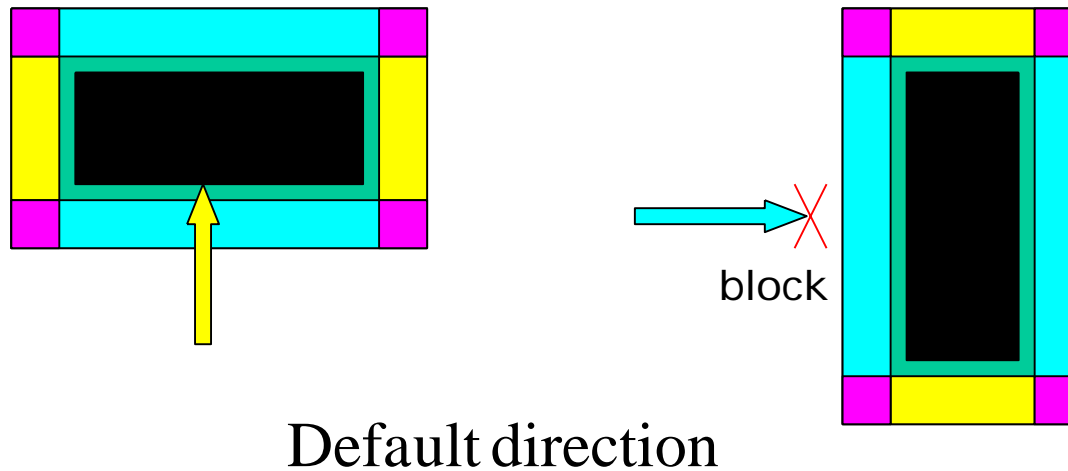
- power issue
- noise issue
- route issue





Block Placement

- ◆ Preserve enough power pad
- ◆ Create power rings around block
- ◆ Follow default routing direction rule
- ◆ Reserve a rounded core row area for placer

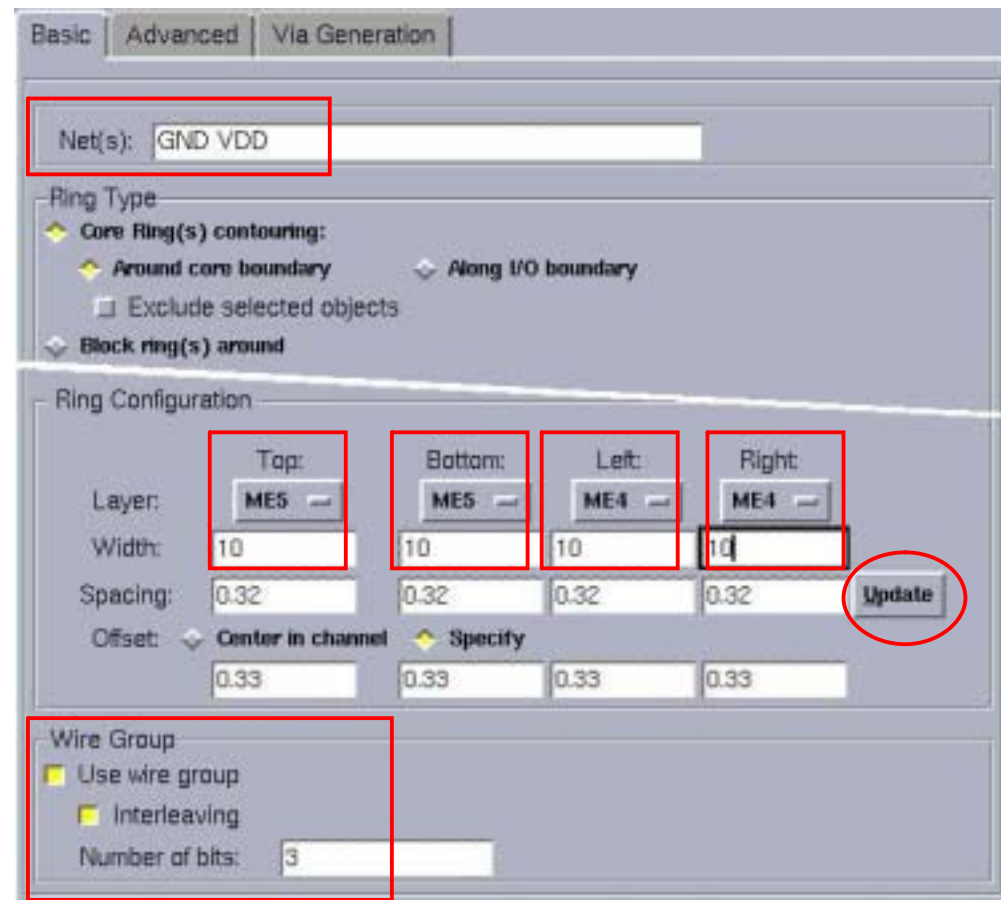
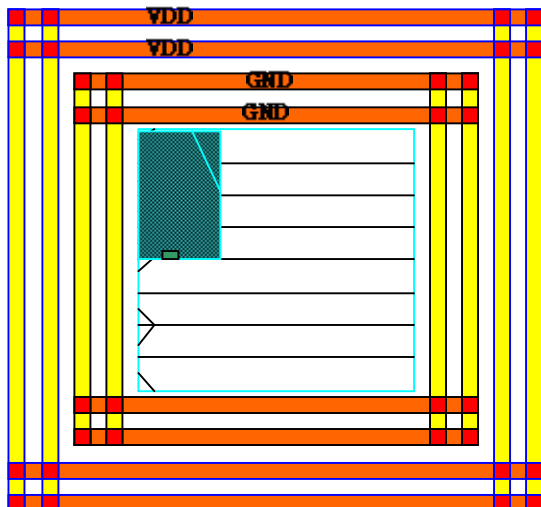




Power Planning: Add Rings

Floorplan → Power Planning → Add Rings

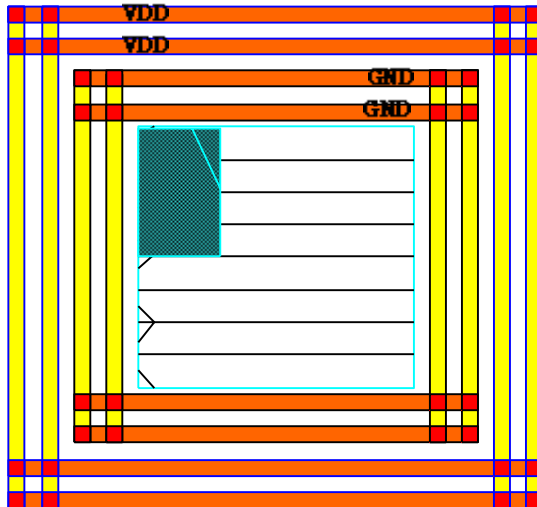
Use wire group to avoid slot DRC error



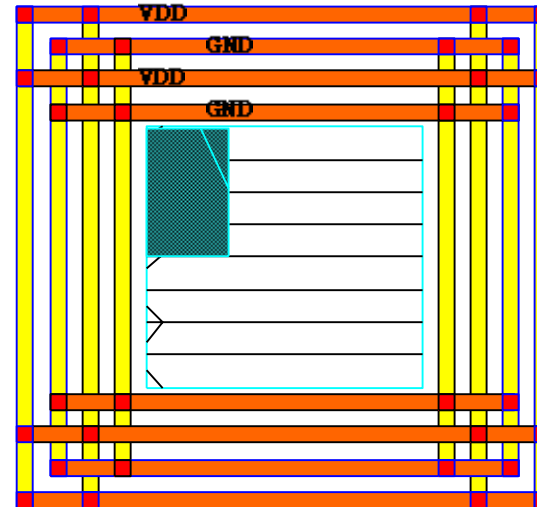


Power Planning: Wire Group

- ✓ Use wire group
- no interleaving
- ✓ number of bits = 2



- ✓ Use wire group
- ✓ interleaving
- ✓ number of bits = 2





Power Planning: Block Ring

Basic Advanced Via Generation

Net(s): GND VDD

Block ring(s) around

- Each block
- Selected power domain/fences
- Each selected block and/or group of core rows
- Clusters of selected blocks and/or groups of core rows

☐ With shared ring edges

	Top:	Bottom:	Left:	Right:
Layer:	ME5	ME5	ME4	ME4
Width:	10	10	10	10
Spacing:	0.32	0.32	0.32	0.32
Offset:	<input checked="" type="radio"/> Center in channel <input type="radio"/> Specify			
	0.33	0.33	0.33	0.33

Update

Wire Group

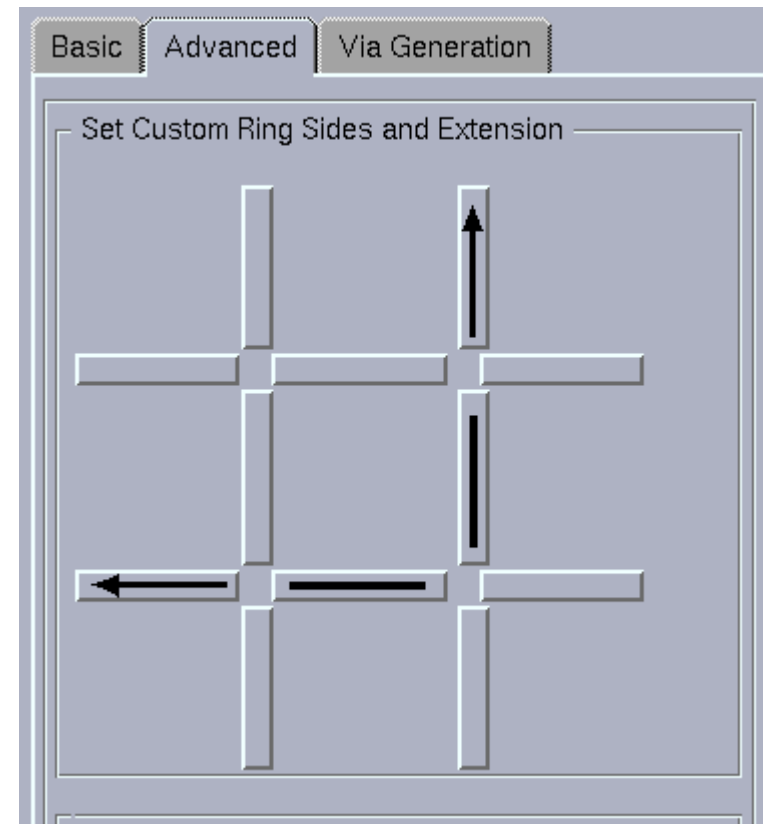
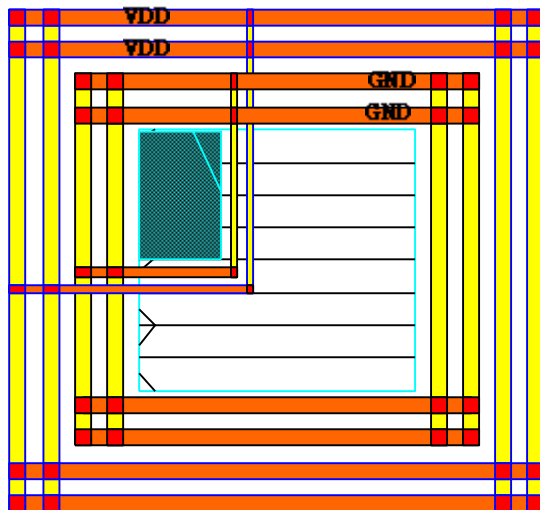
☐ Use wire group

☒ Interleaving

Number of bits: 3



Power Planning: Block Ring cont.





Power Planning: Add Stripes

Basic Advanced Via Generation

Set Configuration

Net(s): GND VDD

Layer: ME4

Direction: ☒ Vertical ☐ Horizontal

Width: 5

Spacing: 0.28

Set Pattern

☒ Set-to-set distance: 100

☒ Number of sets: 3

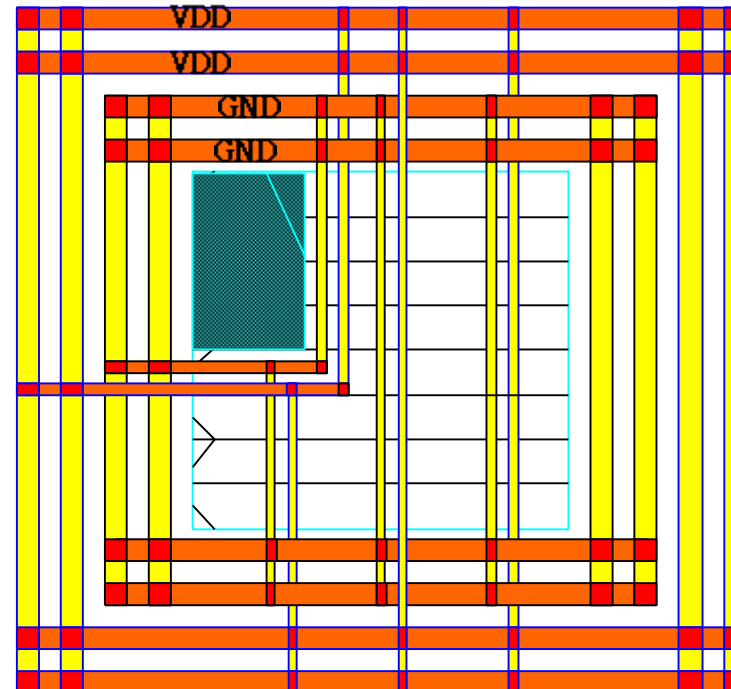
Stripe Offset Boundary

☐ Selected power domain/fence

☒ Relative from core or area:

X from left: 150

X from right: 150





Edit Route

Duplicate wire

Fix wire wider than max width

Change layer

Split wire

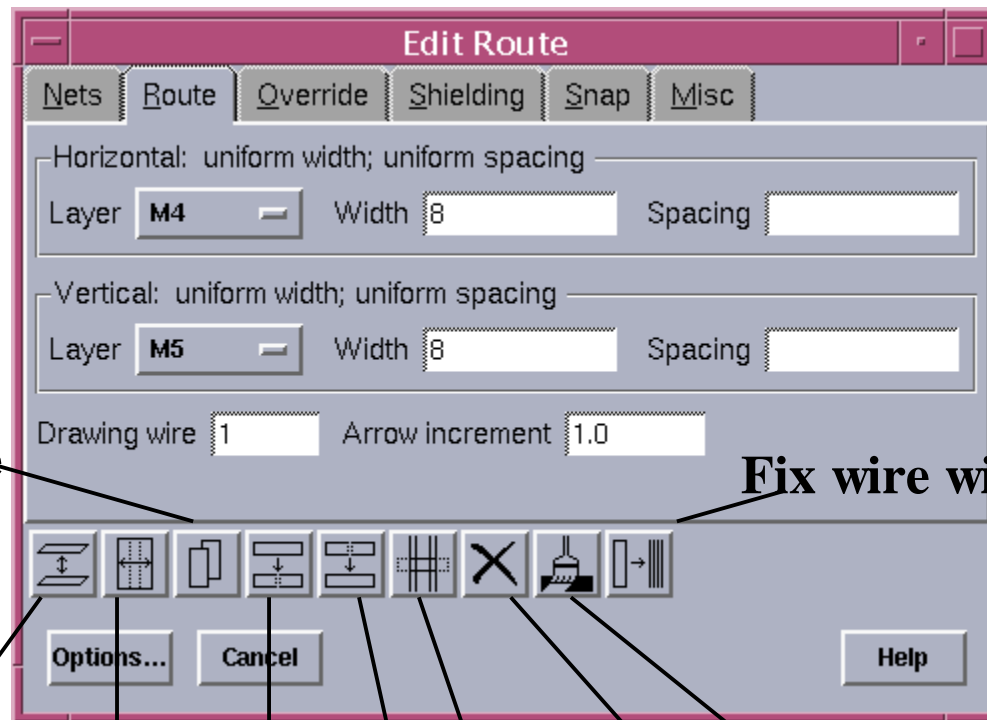
Trim wire

Clear DRC markers

Change width

Merge wire

Delete wire





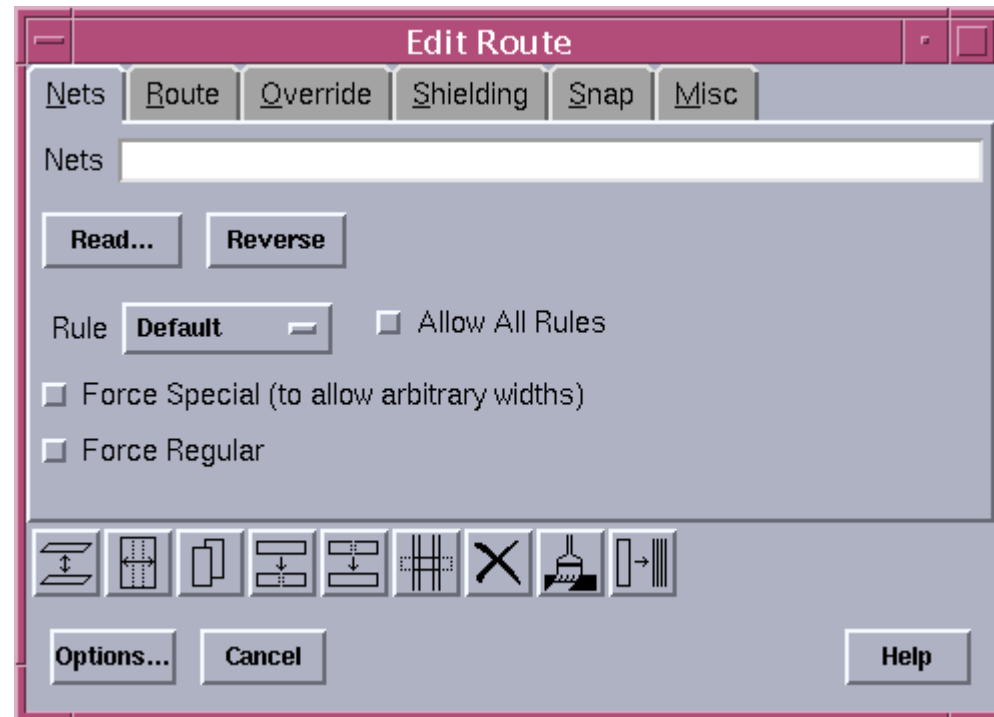
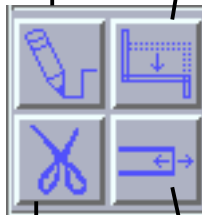
Edit Route cont.

Add Wire

Move Wire

Cut Wire

Stretch Wire

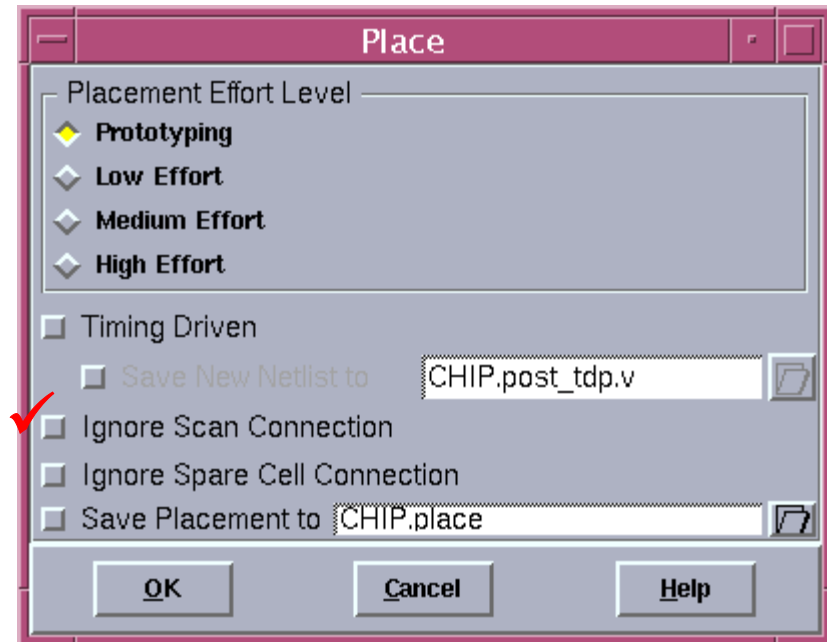




Placement

Place → Place...

- ◆ Prototyping : Runs quickly, but components may not be placed at legal location.
- ◆ Timing Driven:
 - Build timing graph before place.
 - meeting setup timing constraints with routability.
 - Limited IPO by upsizeing/downsizing instances.
- ◆ Ignore Scan Connection
 - nets connected to either the scan-in or scan-out are ignored.
- ◆ Check placement after placed
 - *place → Check Placement*





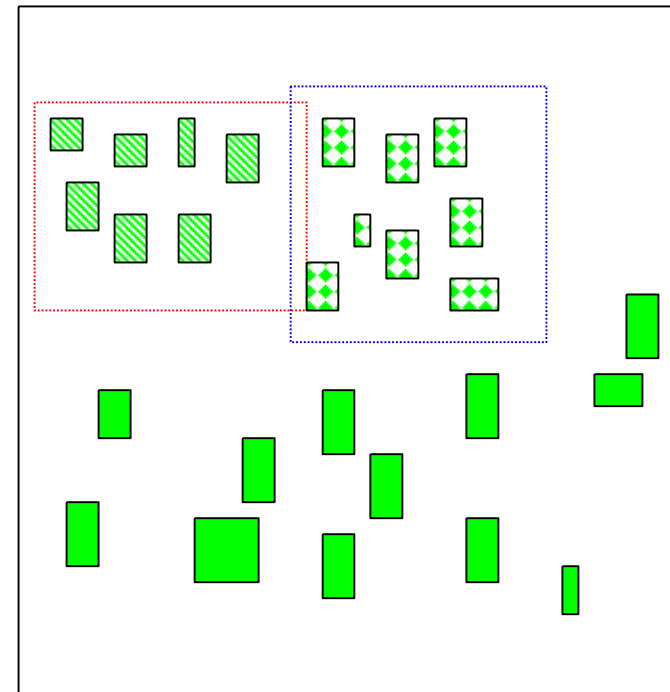
Floorplan Purposes

- ◆ Develop early physical layout to ensure design objective can be archived
 - Minimum area for low cost
 - Minimum congestion for design routable
 - Estimate parasitic for delay calculation
 - Analysis power for reliability
- ◆ gain early visibility into implementation issues



Guide , Region, Fence

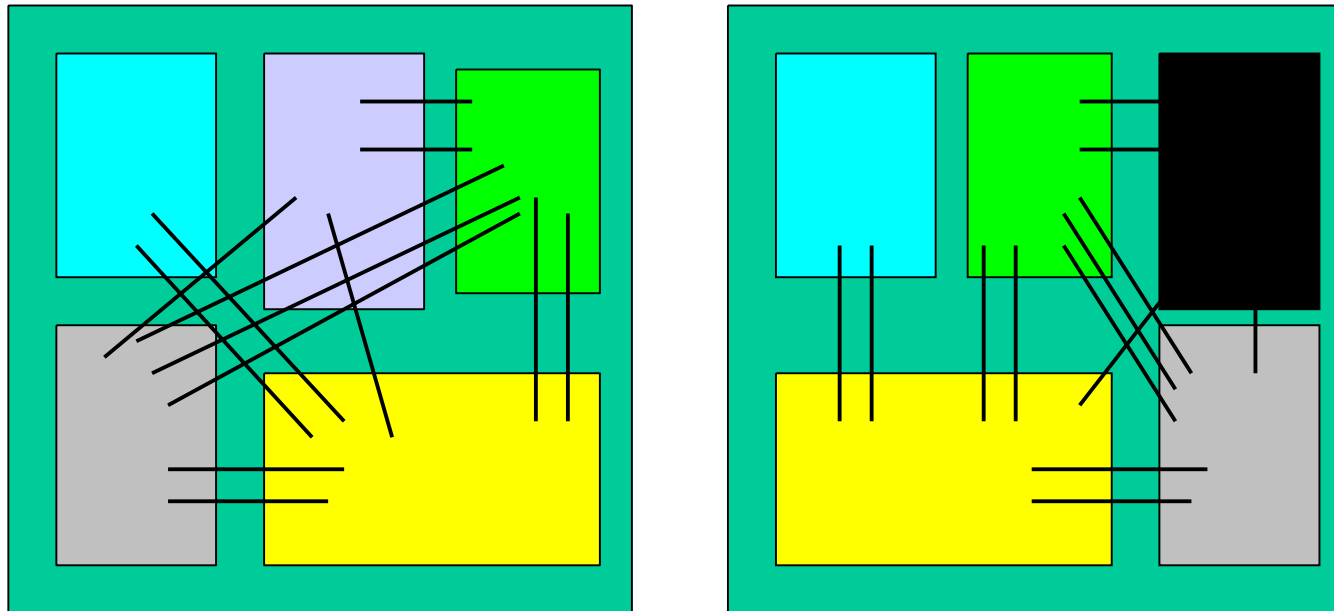
- ◆ Placement constraint
- ◆ Create guide for timing issue
- ◆ A critical path should not through two different modules
- ◆ The more region, the more complicated floorplanning





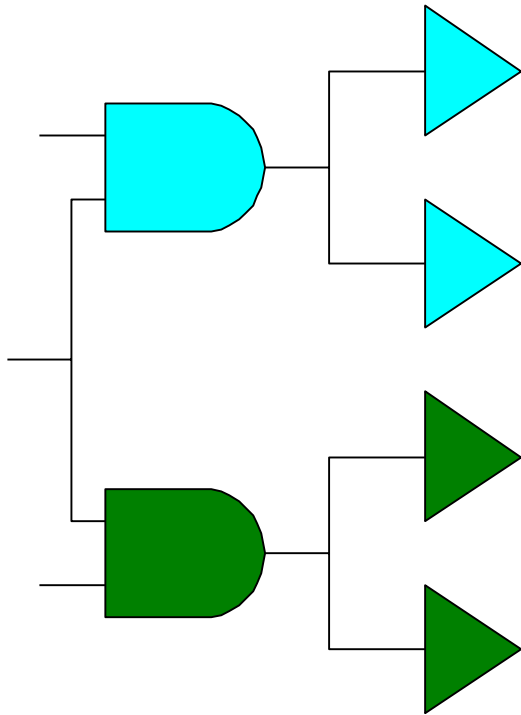
Difference Floorplan

Difference Performance

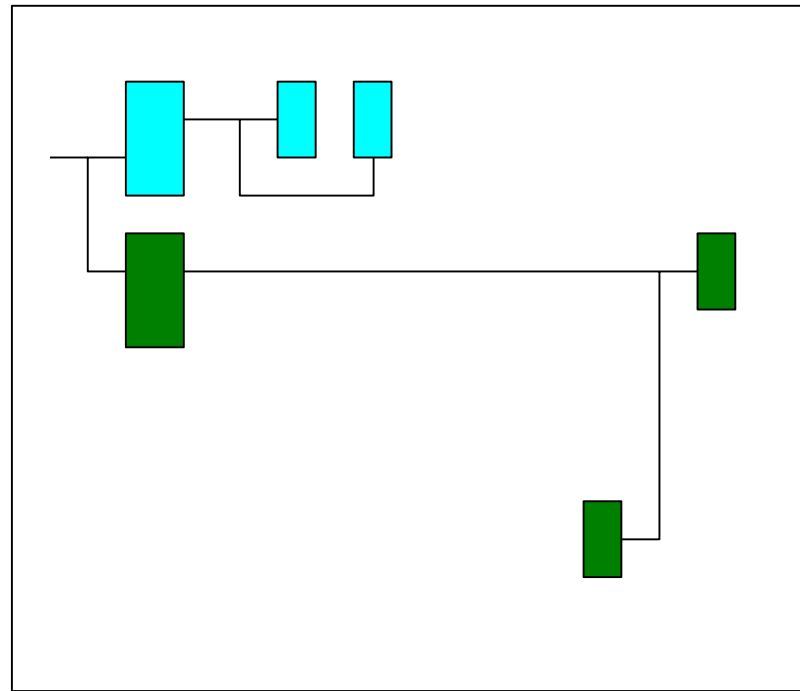




Wire Load After Placement



Logical



wire load after placement

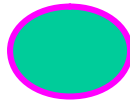
Module Constraint

◆ Soft Guide

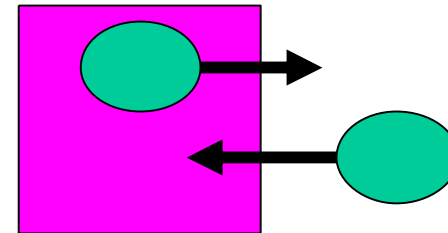
◆ Guide

◆ Region

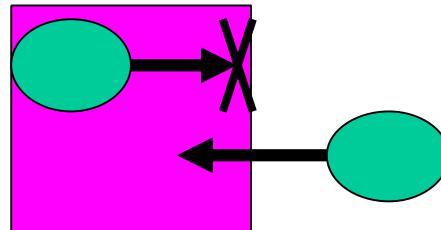
◆ Fence



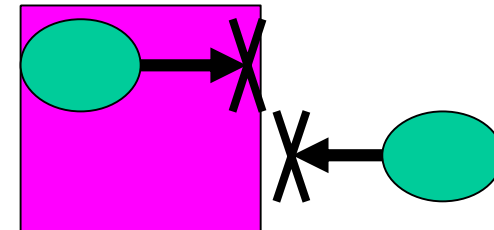
Soft Guide



Guide



Region



Fence



Specify Scan Chain

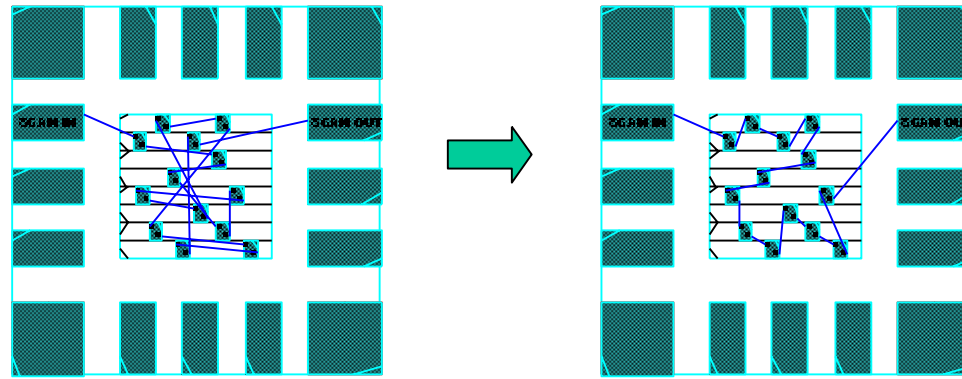
```
encounter > specifyScanChain scanChainName  
             -start {ftname /instPinName}  
             -stop  {ftname /instPinName}
```

- ◆ Specifies a scan chain in a design. The actual tracing of the scan chain is performed by the *scanTrace* or *scanReorder* command
- ◆ *ftname*
 - The design input/output pin name
- ◆ *instPinName*
 - The design instance input/output pin name



Scan Chain Reorder

Place → Reorder Scan



◆ No Skip

- Buffers and inverters remain after the scan chain reorder

◆ Skip Buffer

- Ignores buffers in the scan chain.

◆ Skit Two Pin Cell

- Ignores buffers and inverters in the scan chain



Clock Problem

◆ Clock problem

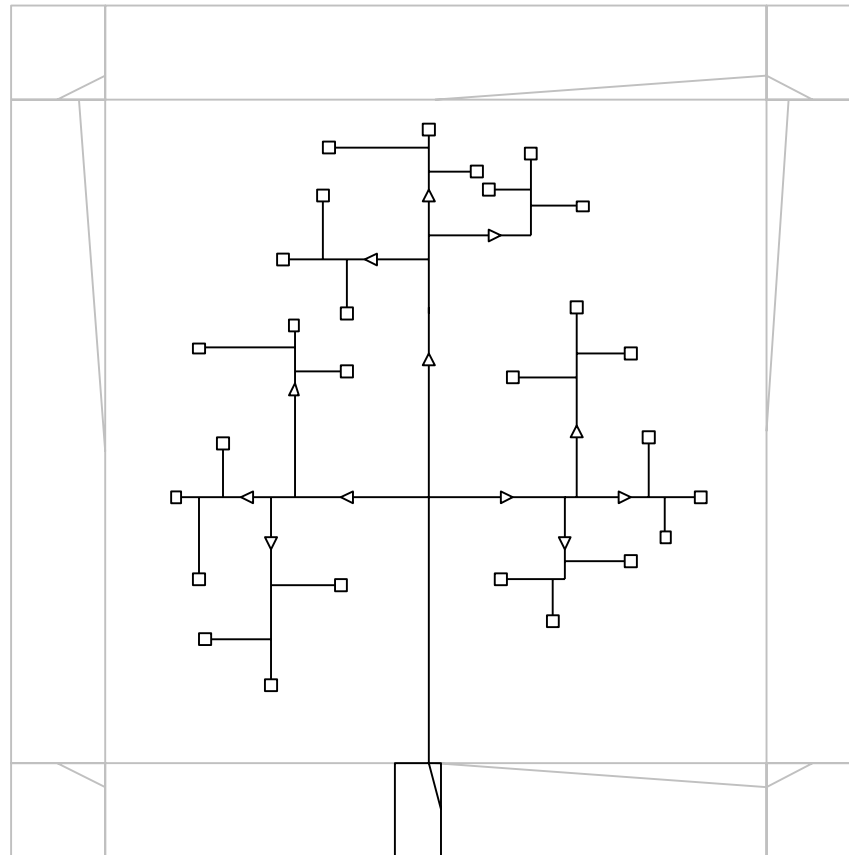
- Heavy clock net loading
- Long clock insertion delay
- Clock skew
- Skew across clocks
- Clock to signal coupling effect
- Clock is power hungry
- Electromigration on clock net

◆ Solutions of these problems may be conflict

◆ Clock is one of the most important treasure in a chip, do not take it as other use.

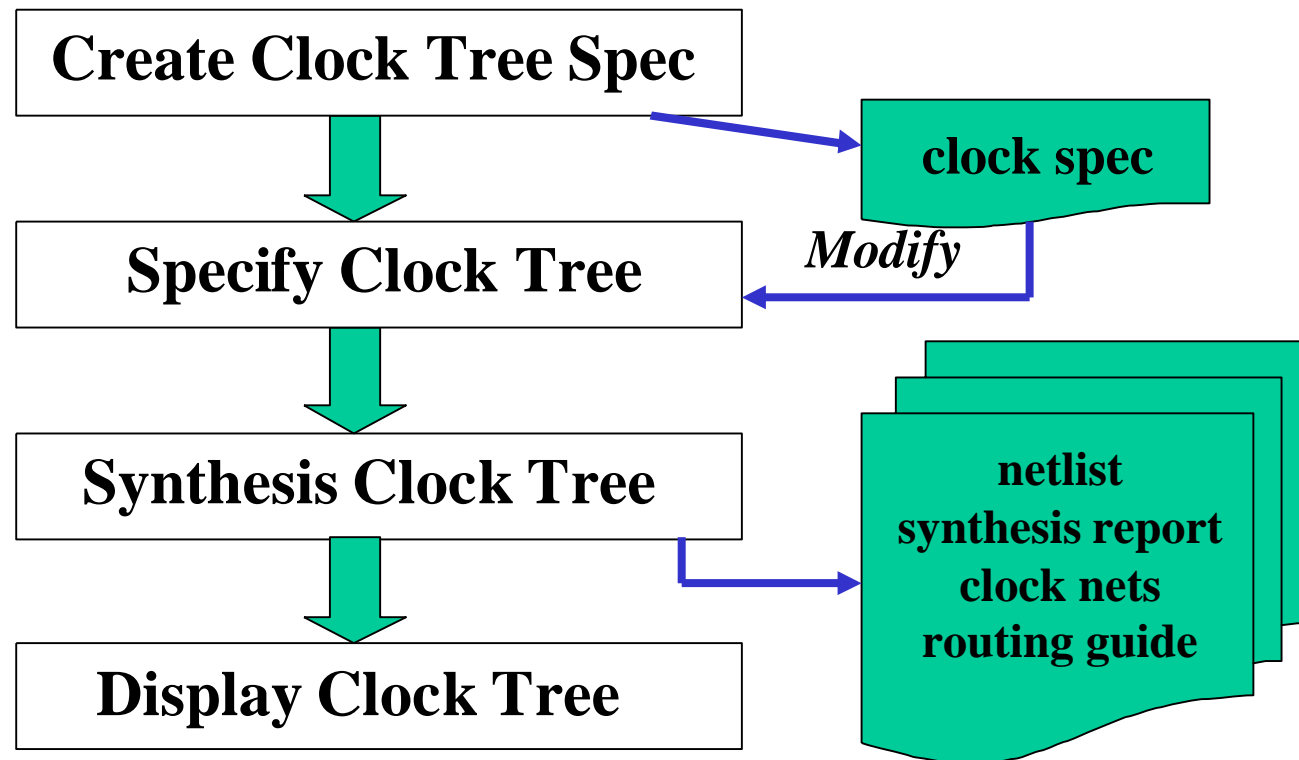


Clock Tree Topology





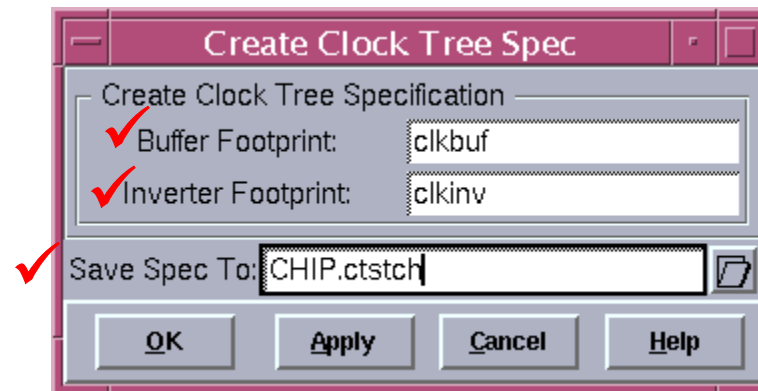
Synthesize Clock Tree





Create Clock Tree Spec.

Clock → Create Clock Tree Spec





CTS

- ◆ CTS traces the clock starting from a root pin, and stops at:
 - A clock pin
 - A D-input pin
 - An instance without a timing arc
 - A user-specified leaf pin or excluded pin
- ◆ Write a CTS spec. template:
 - *specifyClockTree -template*



CTS spec.

- ◆ A CTS spec. contain the following information.
 - Timing constraint file (optional)
 - Naming attributes (optional)
 - Macro model data (optional)
 - Clock grouping data (optional)
 - Attributes used by NanoRoute routing solution (optional)
 - Requirement for manual CTS or automatic, gated CTS



CTS spec.

--Naming Attributes Section

◆ *TimingConstraintFile filename*

- define a timing constraint file for use during CTS

◆ *NameDelimiter delimiter*

- name delimiter used when inserting buffers and updating clock root and net names.
- *NameDelimiter* # ➔ create names clk##L3#I2
- default ➔ clk__L3_I2

◆ *UseSingleDelim YES/NO*

- YES ➔ clk_L3_I2
- NO ➔ clk__L3_I2 (default)



CTS Spec.

-- NanoRoute Attribute Section

◆ *RouteTypeName name*

RouteTypeName CK1

.....

END

◆ *NonDefaultRule ruleName*

- Specify LEF NONDEFAULTRULE to be used

◆ *PreferredExtraSpace [0-3]*

- add space around clock wires

◆ *Shielding PGNetName*

- Defines the power and ground net names



CTS Spec.

-- Macro Model Data Section

-- Clock Grouping Section

◆ *MacroModel*

- *MacroModel port R64x16/clk 90ps 80ps 90ps 80ps 17pf*
- *MacroModel pin ram1/clk 90ps 80ps 90ps 80ps 17pf*
- *delay_and_capacitance_value:*
maxRise minRise maxFall minFall inputCap

◆ *ClkGroup*

- Specifies tow or more clock domains for which you want CTS to balance the skew.
- *ClkGroup*
+clockRootPinName1
+clockRootPinName2
.....



CTS Spec.

--Manually Define Clock Tree Topology

ClockNetName netName

LevelNumber number

- Specify the clock tree level number

LevelSpec levelNumber numberOfBuffers bufferType

- *levelNumber*

- ✓ Specify the level number in the clock tree

- *numberOfBuffer*

- ✓ the total number of buffers CTS should allow on the specified level

- Example:

LevelSpec 1 2 CLKBUF2

LevelSpec 2 2 CLKBUF2

End



CTS Spec.

-- Automatic Gated CTS Section

- ◆ ***AutoCTSRootPin*** *clockRootPinName*
- ◆ ***MaxDelay*** *number{ns/ps}*
- ◆ ***MinDelay*** *number{ns/ps}*
- ◆ ***SinkMaxTran*** *number{ns/ps}*
 - maximum input transition time for sinks(clock pins)
- ◆ ***BufMaxTran*** *number{ns/ps}*
 - maximum input transition time for buffers (defalut 400)
- ◆ ***MaxSkew*** *number{ns/ps}*



CTS Spec.

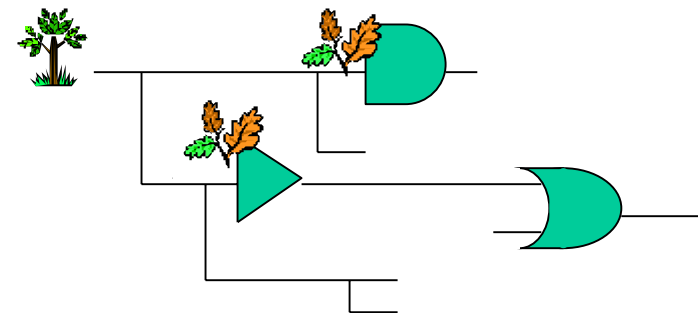
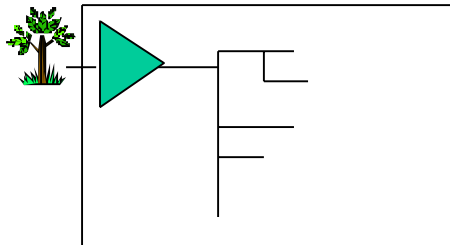
-- Automatic Gated CTS Section cont.

◆ **NoGating** {*rising/falling/NO*}

- *rising* : stops tracing through a gate(include buffers and inverters) and treats the gate as a rising-edge-triggered flip-flop clock pin.
- *falling*: stops tracing through a gate(include buffers and inverters) and treats the gate as a falling-edge-triggered flip-flop clock pin.
- *No*: Allows CTS to trace through clock gating logic. (default)

◆ **AddDriverCell** *driver_cell_name*

- Place a driver cell at the closest possible location to the clock port location .





CTS Spec.

-- Automatic Gated CTS Section cont.

◆ ***MaxDepth*** *number*

◆ ***RouteType*** *routeTypeName*

◆ ***RouteClkNet*** *YES/NO*

➤ Specifies whether CTS routes clock nets.

◆ ***PostOpt*** *YES/NO*

➤ whether CTS resizes buffers of inverters , refines placement, and corrects routing for signal and clock wires.

➤ default YES

◆ ***Buffer*** *cell1 cell2 cell3 ...*

➤ Specifies the names of buffer cells to use during CTS.



CTS Spec.

-- Automatic Gated CTS Section cont.

◆ *LeafPin*

+ *pinName rising/falling*

+

➤ Mark the pin as a “leaf” pin for non-clock-type instances.

➤ *LeafPin*

+ instance1/A rising

+ instance2/A rising

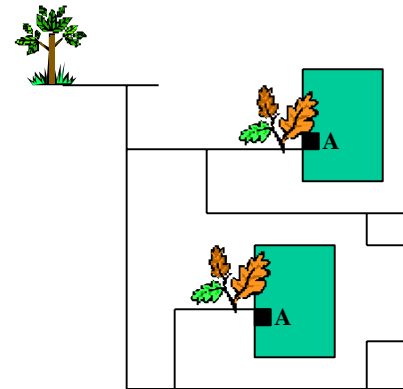
.....

◆ *LeafPort*

+ *portName rising/faling*

+

➤ Mark the port as a “leaf” port for non-clock-type instances





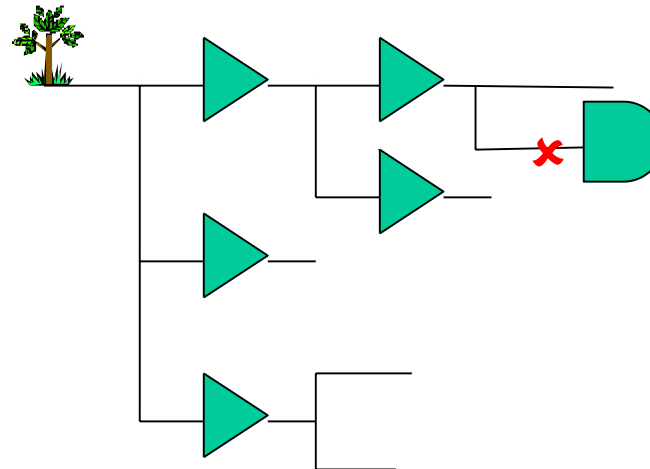
CTS Spec.

-- Automatic Gated CTS Section cont.

◆ *ExcludedPin*
+ *pinName*
+

◆ *ExcludedPort*
+ *portName*
+

- Treats the port as a non-leaf port, and prevents tracing and skew analysis of the pin.





CTS Spec.

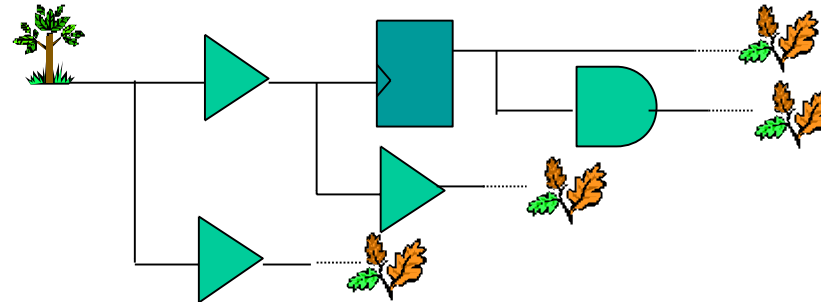
-- Automatic Gated CTS Section cont.

◆ *ThroughPin*

+ *pinName*

+

- Traces through the pin, even if the pin is a clock pin

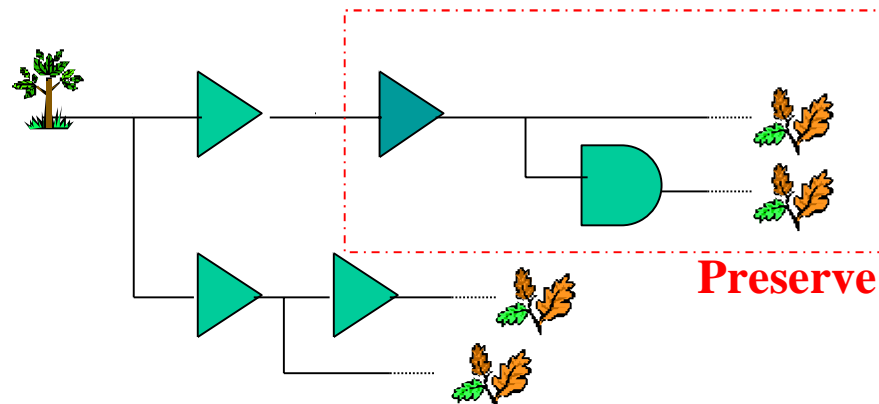


◆ *PreservePin*

+ *inputPinName*

+

- Preserve the netlist for the pin and pins below the pin in the clock tree.





CTS Spec.

-- Automatic Gated CTS Section cont.

◆ *DefaultMaxCap capvalue*

- CTS adheres to the following priority when using maximum capacitance value:
 - ✓ MaxCap statements in the clock tree specification file
 - ✓ DefaultMaxCap statement in the clock tree specification file
 - ✓ Maximum capacitance values in the SDC file
 - ✓ maximum capacitance values in the .lib file

◆ **MaxCap**

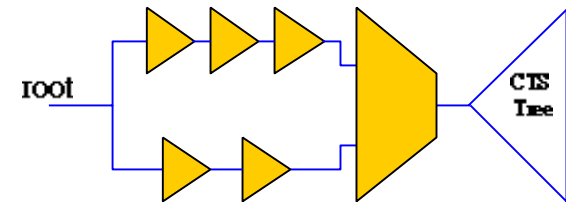
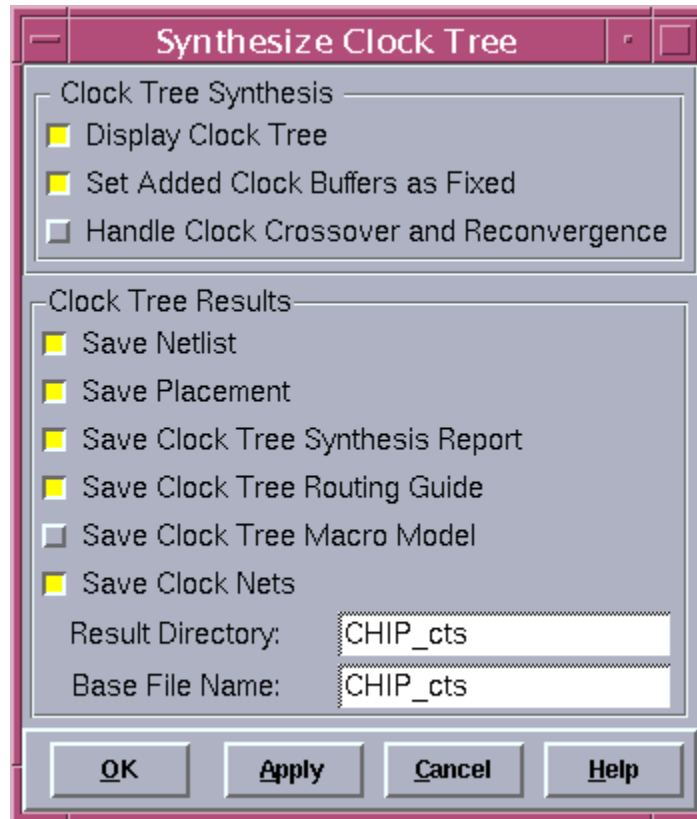
- + *bufferName1 capValue1{pf/ff}*
- + *bufferName2 capValue2{pf/ff}*
- +

- Buffer should be inserted if the given capacitance value is exceeded

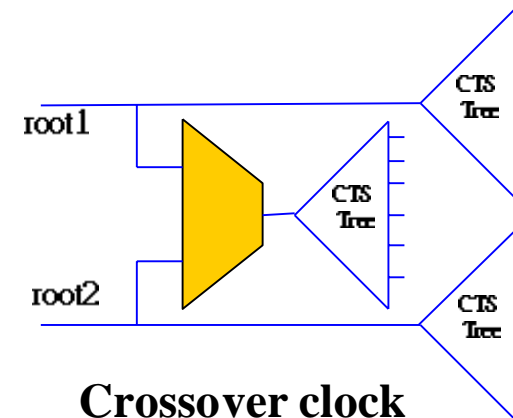


Synthesize Clock Tree

Clock → Synthesize Clock Tree



Reconvergence clock



Crossover clock



Clock Synthesis report

◆ Summary report and detail report

- number of sub trees
- rise/fall insertion delay
- trigger edge skew
- rise/fall skew
- buffer and clock pin transition time
- detailed delay ranges for all buffers add to clocks

◆ Clock nets

- Saves the generated clock nets
- used to guide clock net routing

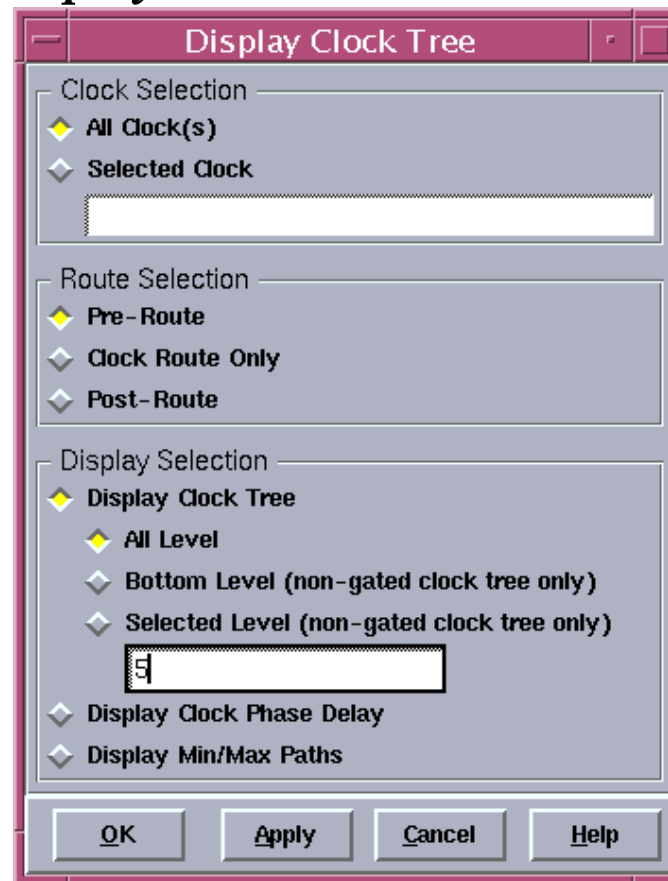
◆ Clock routing guide

- Saves the clock tree routing data
- used as preroute guide while running Trial Route



Display Clock Tree

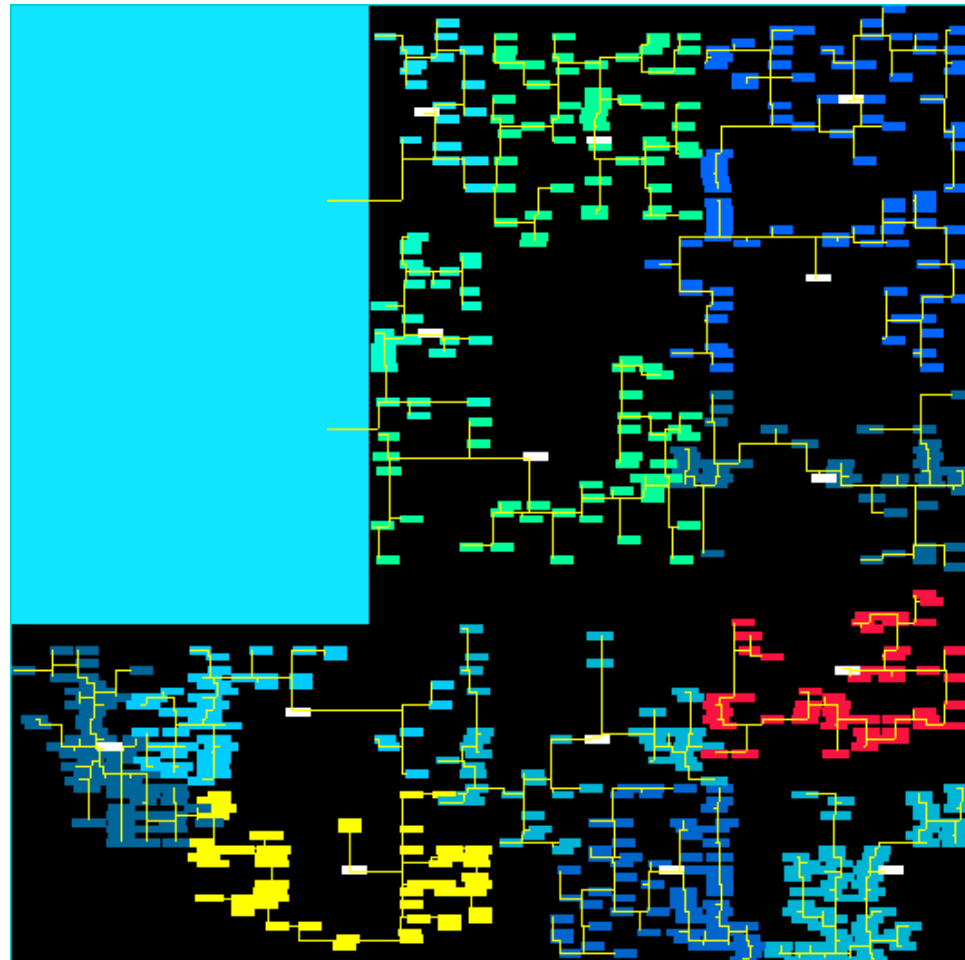
Clock → Display → Display Clock Tree...





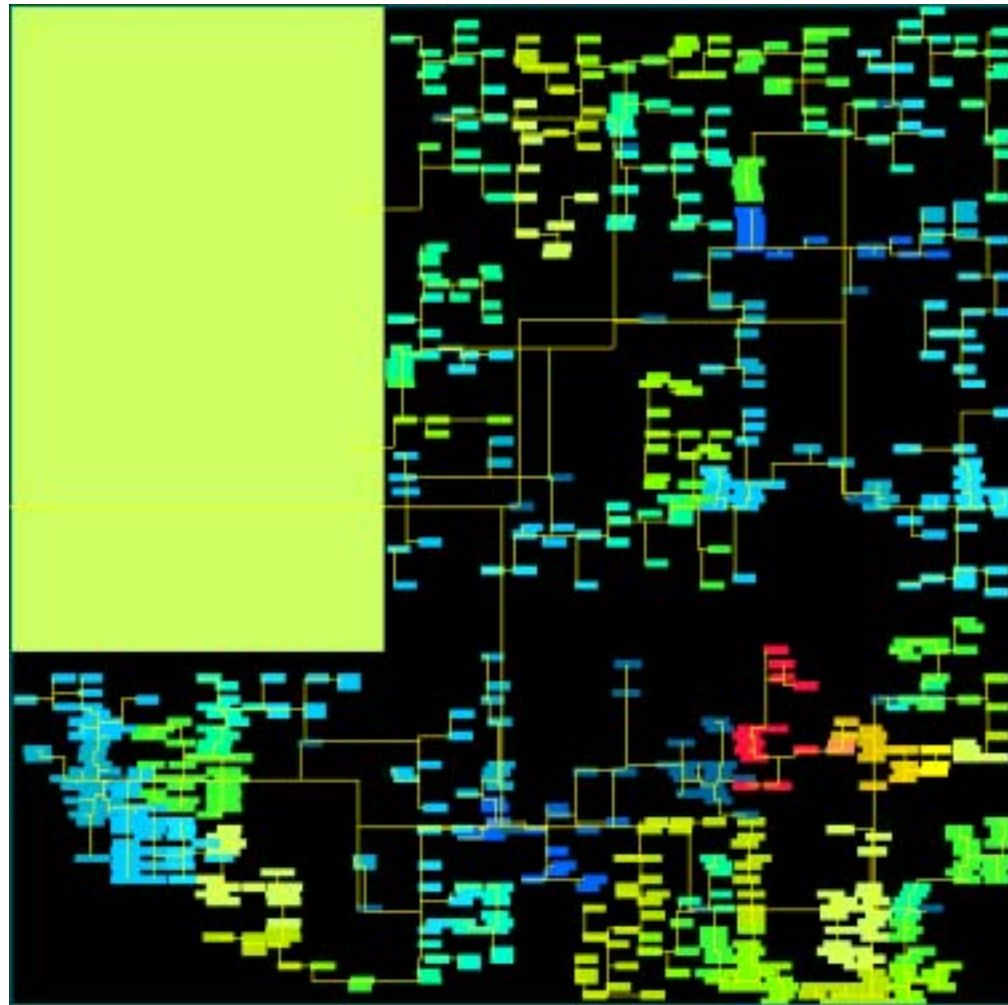
Display Clock Tree

-- by level





Display Clock Tree --by phase delay





Clock Tree Browser

Clock → Clock Tree Brower

tree	instance_name	input_delay (p
[-] TREE		
[-] 1 CLKINVX20 A	CLK__L1_I0	[37.3 37.3]
[-] 2 CLKINVX20 A	CLK__L2_I1	[323.3 320.7]
[-] 3 CLKBUX20 A	CLK__L3_I13	[701.7 705.5]
[-] 4 SDDFTRX1 CK	DCT/bdeg/ACC0/accS_reg_6_	[963.4 980.8]
[-] 4 SDDFTRX1 CK	DCT/bdeg/ACC0/accS_reg_5_	[963.3 980.7]
[-] 4 SDDFTRX1 CK	DCT/bdeg/ACC0/accS_reg_4_	[963.1 980.5]
[-] 4 SDDFTRX1 CK	DCT/bdeg/ACC0/accS_reg_3_	[960.8 978.2]

- ◆ Display trig edge, rise/fall delay, rise/fall skew, input delay, input tran of each cell.
- ◆ Resize/Delete leaf cell or clock buffer
- ◆ Reconnect clock tree



In-Place Optimization

Timing → In-Place Optimization...

◆ IPO

- setup time
- hold time
- DRV (Design Rule Violation)

A screenshot of the 'In-Place Optimization' dialog box. The title bar is 'In-Place Optimization'. The 'Timing Analysis Type' section has three radio buttons: 'setup' (selected), 'hold', and 'DRV Only'. The 'Settings' section includes a 'Max Placement Density' field with '0.95', a 'Target Slack (ns)' field with '0', and an 'Effort Level' section with radio buttons for 'Low', 'Medium' (selected), and 'High'. Below this are three checkboxes for 'DRV Types': 'Fix Max Cap' (checked), 'Fix Max Tran' (checked), and 'Fix Max Fanout' (checked). The 'Select/Exclude files' section has two checkboxes: 'Select Nets from' and 'Exclude Nets from', each followed by a text field and a folder icon button. The 'Results' section has a 'Save to Directory' field with 'CHIP_ipo', and checkboxes for 'Netlist' (checked), 'Placement' (checked), 'Routing' (checked), 'Slack Report' (checked), and 'Timing Report' (checked). The 'Timing Report' checkbox is followed by a field with '50' and the text 'paths'. The 'Base Name' field contains 'CHIP_ipo'. At the bottom are five buttons: 'OK', 'Apply', 'Advanced...', 'Cancel', and 'Help'.



Congestion Optimization

```
encounter > congOpt  
            [ -nrIterInCongOpt nrIter ]  
            [ -maxCPUTimeInCongOpt time ]
```

◆ Reduces congestion after placement in an iterative way.

◆ Parameters

➤ *nrIterInCongOpt nrIter*

✓ Specifies the total number of iteration in congestion optimization.
(default 1)

➤ *maxCPUTimeInCongOpt*

✓ specifies the maximum CPU time in congestion optimization, in hours.



Balance Slew

encounter > *balanceSlew*

[*-selNetFile selNetFileName*]

[*-excNetFile excNetFileName*]

◆ Speeds up or slows down the transition time if it is greater or less than the specified maximum transition time.

◆ Parameters

➤ selNetFile selNetFileName

✓ Specifies the file that contains the hierarchical net names that are excluded from the IPO operation

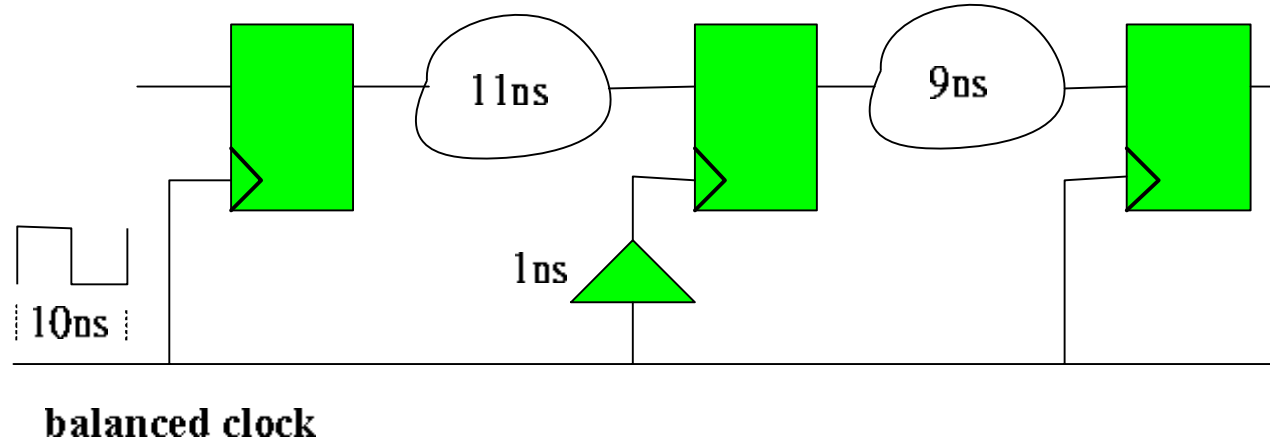
➤ excNetFile excNetFileName

✓ Specifies the file that contains the hierarchical net (path) names for the IPO operations. Only these net names are considered.



Useful Skew

```
encounter > setAnalysisMode -usefulSkew  
encounter > skewClock  
encounter > optCritPath
```





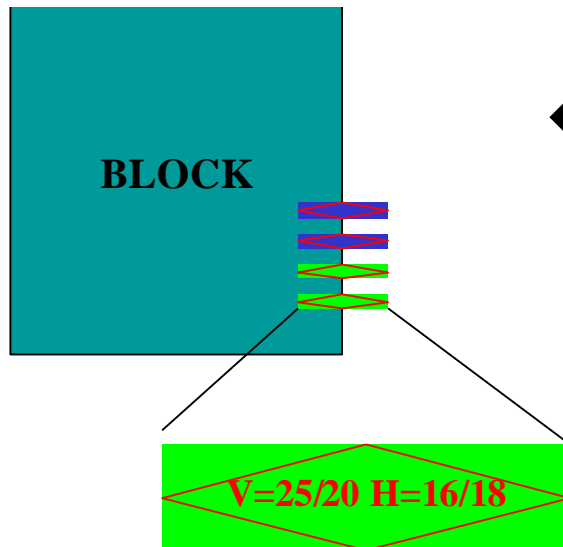
Trial Route

- ◆ perform quick routing for congestion and parasitics estimation
- ◆ Prototyping:
 - Quickly to gauge the feasibility of netlist.
 - components in design might not be routed at legal location





Trial Route Congestion Marker



◆ visually check the congestion statistics.

◆ dump congestion area:

➤ *dumpCongesArea -all file_name*

The vertical (V) overflow is 25/20 (25 tracks are required , but only 20 tracks are available) .
The Horizontal (H) overflow is 16/18 (16 tracks are required , and 18 tracks are available) .



Trial Route Congestion Marker cont.

Level	Color	Overflow Value
1	● Blue	One more track required
2	● Green	Two more track required
3	● Yellow	Three more track required
4	● Red	Four more track required
5	● Magenta	Five more track required
6 and higher	● Grey to White	Six or more track required



Timing Analysis

Timing → Specify Analysis Condition → Specify RC Extraction Mode ...

Timing → Extract RC...

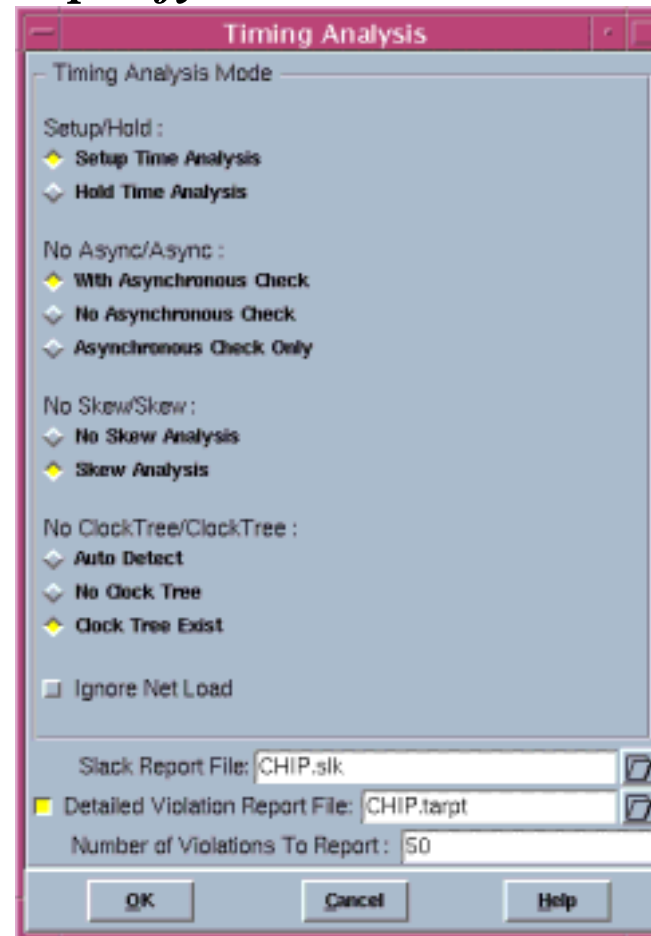
Timing → Timing Analysis...

◆ No Async/Async:

- recovery, removal check

◆ No Skew/Skew:

- check with/without clock skew constraint





Slack Browser

Timing → Timing Debug → Slack Browser...

Timing Slack Browser						
Analysis mode: -setup -skew -caseAnalysis -async -clkSrcPath						
Format: clock	timeReq	slackR/slackF	setupR/setupF	instName/pinName	#	cycle(s)
CLK1(F)→CLK1(R)	21.000	1.500/1.500	*/*	O_Z[2]	1	
CLK1(F)→CLK1(R)	21.000	1.928/1.928	*/*	O_Z[0]	1	
CLK1(F)→CLK1(R)	21.000	2.052/2.052	*/*	O_Z[1]	1	
CLK1(R)→CLK1(F)	11.662	2.167/2.167	*/*	DCT/tposemem/Bisted_DPR64x16/BistCtrl_		
CLK1(F)→CLK1(R)	21.000	2.568/2.568	*/*	O_Z[6]	1	
CLK1(F)→CLK1(R)	21.000	2.619/2.619	*/*	O_Z[4]	1	
CLK1(F)→CLK1(R)	21.000	2.677/2.677	*/*	O_Z[10]	1	
CLK1(F)→CLK1(R)	21.000	2.680/2.680	*/*	O_Z[9]	1	
CLK1(F)→CLK1(R)	21.000	2.688/2.688	*/*	O_Z[11]	1	
CLK1(F)→CLK1(R)	21.000	2.718/2.718	*/*	O_Z[3]	1	
Sort By: Original Find Inst/Pin Name:						
Cancel Help						



Power Analysis

Edit Pad Location

Pad Location
X: Y: Layer:

Auto Fetch Pad Location
✓ Net:

Pad Location List

545.440000	31.680000	M5	PAD_CoreVDD3
31.680000	865.920000	M5	PAD_CoreVDD2
785.800000	1219.440000	M5	PAD_CoreVDD1
625.560000	31.680000	M5	PAD_CoreVSS3
31.680000	946.040000	M5	PAD_CoreVSS2
865.920000	1219.440000	M5	PAD_CoreVSS1

Timing → Extract RC...

Power → Edit Pad Location...

Power → Edit Net Toggle Probability...

Edit Net Toggle Probability

Clock Info
Clock Name: ✓
Clock Rate(MHz): ✓
Net Toggle Probability: ✓

Toggle Probability List
CLK1 50.000 0.900



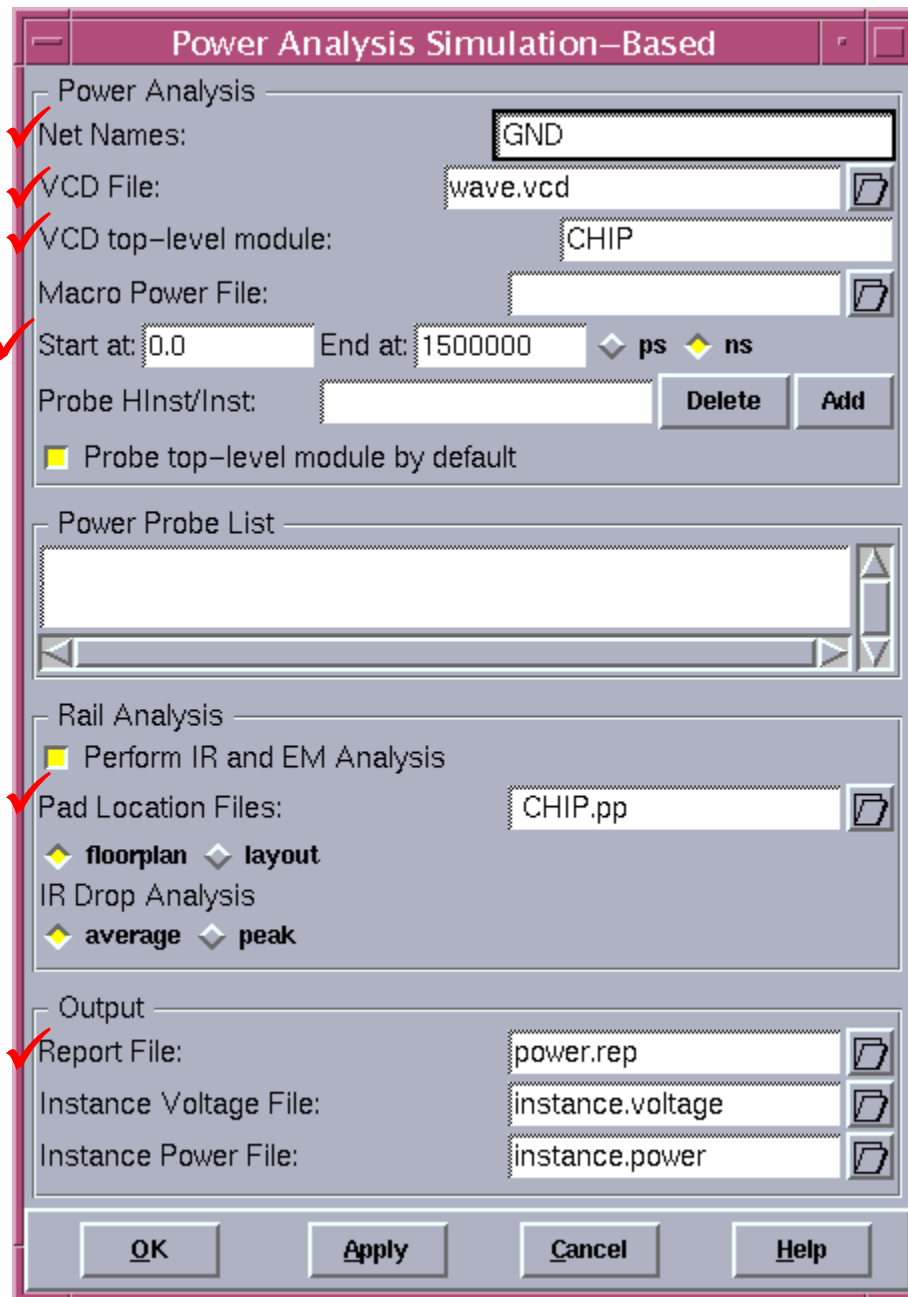
Statistical Power Analysis

Power → Power Analysis → Statistical

◆ analysis report:

- A power graph
- report contains
 - ✓ average power usage
 - ✓ worst IR drop
 - ✓ worst EM violation
- instance power file
- instance voltage file
- boundary voltage file

A screenshot of the 'Power Analysis Statistical Mode' dialog box. The dialog has a title bar with a minus, maximize, and close button. It contains several sections: 'Power Analysis' with fields for 'Net Names' (VDD), 'dummy clock', 'pre-CTS clock', and 'post-CTS clock'; 'Net Toggle Probability' (0.9); 'Clock Rate (MHz)' (100); 'Net Toggle Probability File' (CHIP.tg); 'Expected Average Power (mWatt)'; and 'Macro Power File'. The 'Rail Analysis' section includes a checkbox for 'Perform IR and EM Analysis', 'Pad Location Files' (CHIP.pp), and radio buttons for 'floorplan' and 'layout'. The 'IR Drop Analysis' section has radio buttons for 'average' and 'peak'. The 'Output' section has fields for 'Report File', 'Instance Voltage File', and 'Instance Power File' (instance.power). At the bottom are buttons for 'OK', 'Apply', 'Cancel', and 'Help'.



Simulation-Based Power Analysis

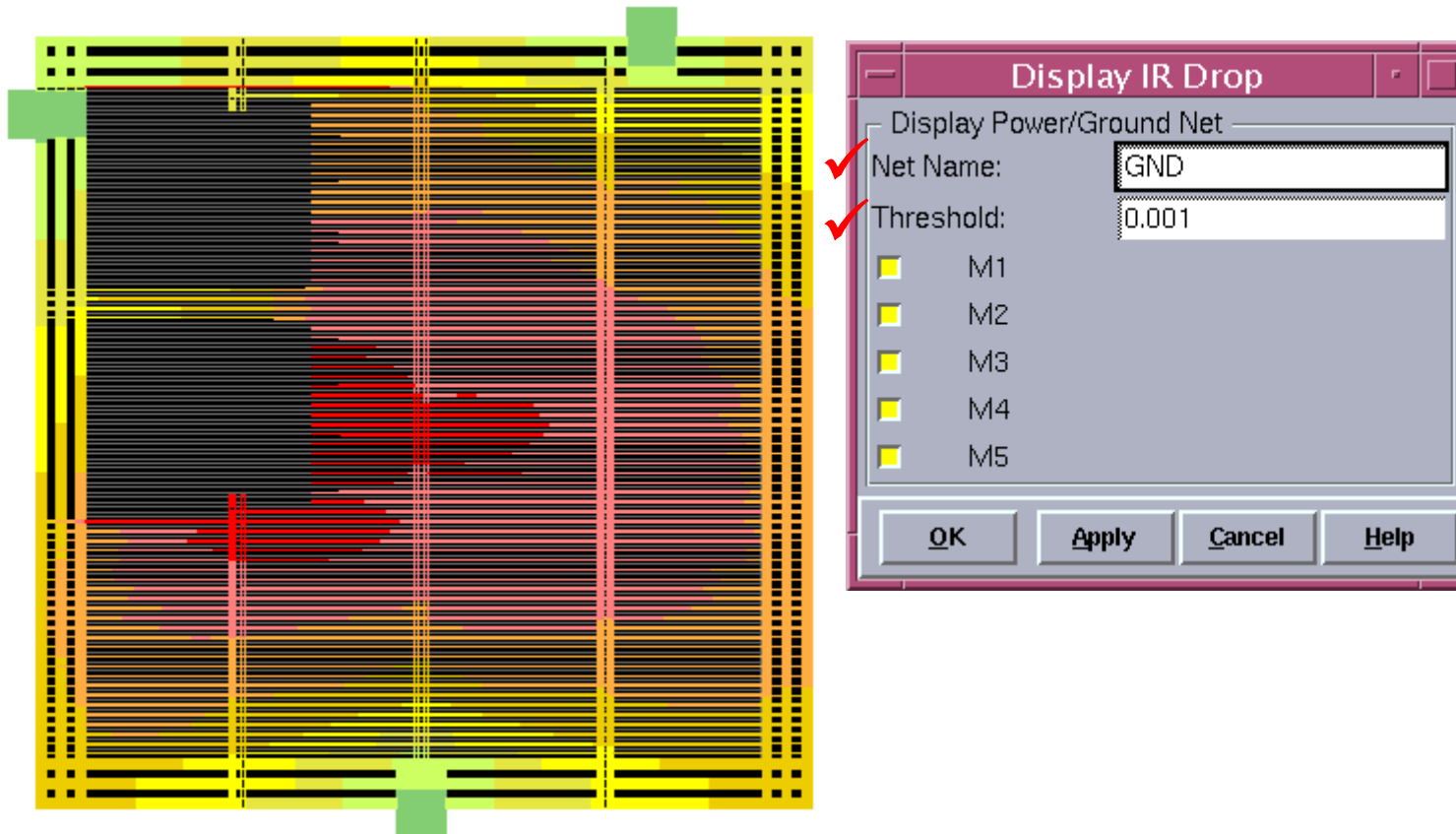
Power → Power Analysis → Simulation-Based

- ◆ save netlist for simulation
 - *Design → Save → Netlist...*
- ◆ simulation and dump vcd file.
 - \$dumpvars;
 - \$dumpfile("wave.vcd");
- ◆ Input vcd file for power analysis



Display IR Drop

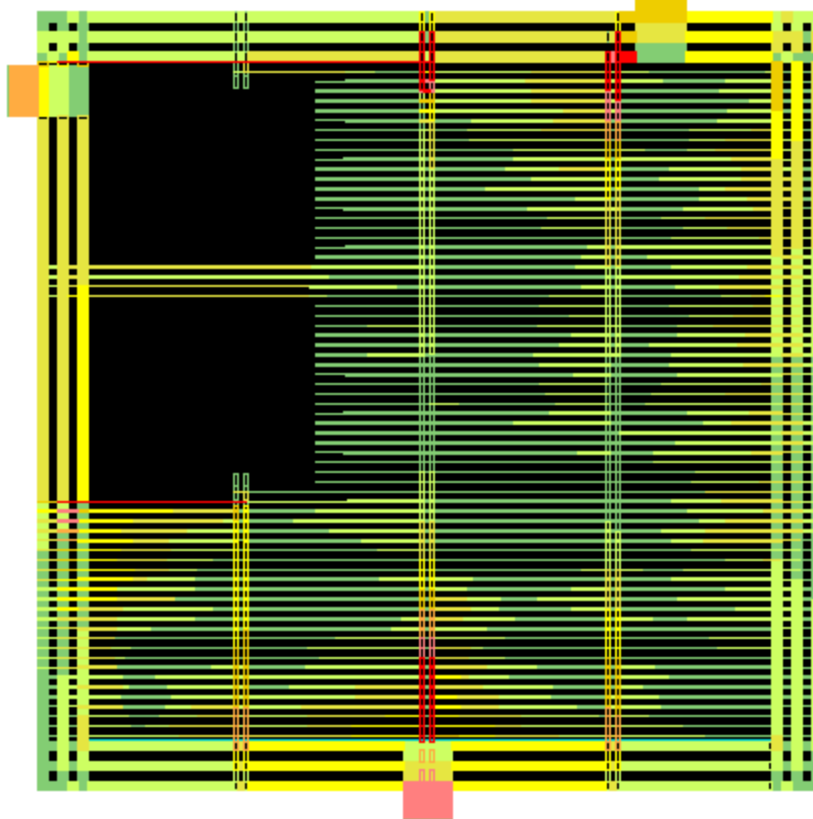
Power → Display → Display IR Drop...





Display Electron Migration

Power → Display → Display EM...



Display EM

Display Power/Ground Net

Net Name: ☒ GND

	Layer	Reset	Limit	Unit
<input type="checkbox"/>	M1	1		mA/u
<input type="checkbox"/>	M2	1		mA/u
<input type="checkbox"/>	M3	1		mA/u
<input type="checkbox"/>	M4	1		mA/u
<input type="checkbox"/>	M5	1		mA/u
<input type="checkbox"/>	V12	1		mA/cut
<input type="checkbox"/>	V23	1		mA/cut
<input type="checkbox"/>	V34	1		mA/cut
<input type="checkbox"/>	V45	1		mA/cut

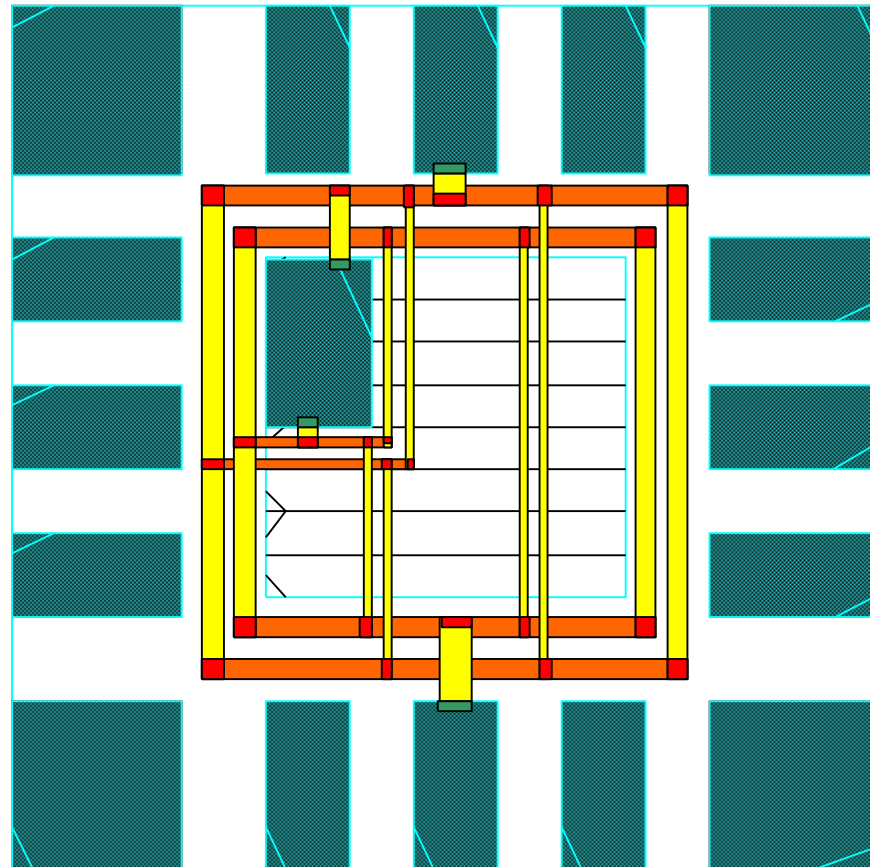
OK Apply Cancel Help



SRoute

◆ Route Special Net (power/ground net)

- Block pins
- Pad pins
- Pad rings
- Standard cell pins
- Stripes (unconnected)





Add IO filler

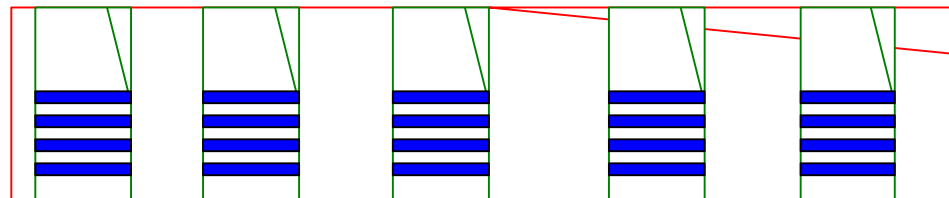
addIoFiller -cell PFILL -prefix IOFILLER

addIoFiller -cell PFILL_9 -prefix IOFILLER

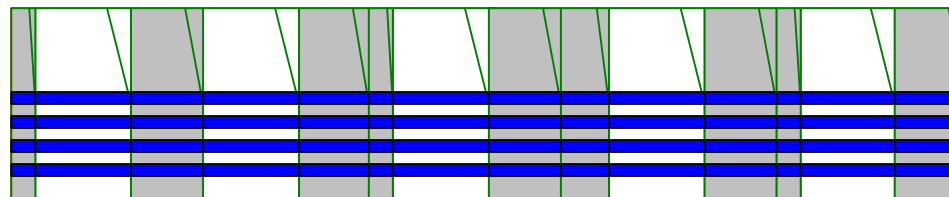
addIoFiller -cell PFILL_1 -prefix IOFILLER

addIoFiller -cell PFILL_01 -prefix IOFILLER -fillAnyGap

- ◆ Connect io pad power bus by inserting IO filler.
- ◆ Add from wider filler to narrower filler.



↓ ADD IO FILLER

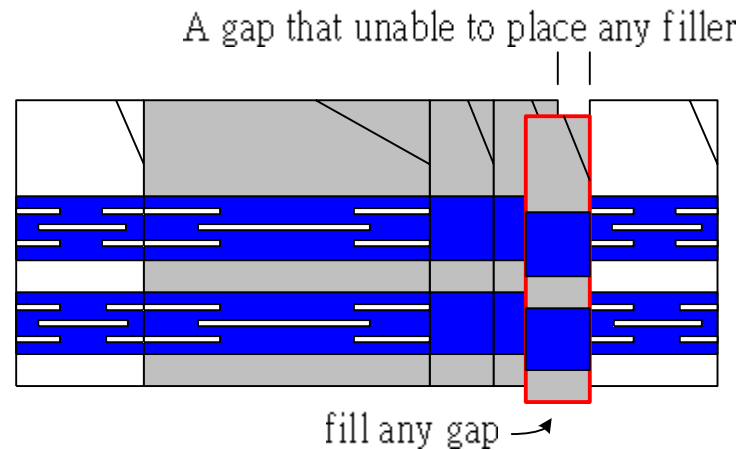




Add IO filler cont.

◆ In order to avoid DRC error

- The sequence of placing fillers must be from wider fillers to narrower ones.
- Only the smallest filler can use -fillAnyGap option.





NanoRoute

Route → NanoRoute

NanoRoute

Mode
Global Route ☒ Detail Route ☒ Batch ☐ Process Optimization ☐

Concurrent Routing Features
Fix Antenna ☒ Insert Diodes ☐ Diode Cell Name default
Timing Driven ☒
Timing Opt. ☒ Buffer Insertion ☒ Gate Sizing ☒
Fix Max Cap ☐ Fix Setup ☒ Setup Slack 0.000000
Fix Max Tran ☐ Fix Hold ☐ Hold Slack 0.000000
Don't Use Cell File default
SI Driven ☒ ☒ Low Effort ☐ High Effort
Min Cap 0.050000 Min Coupling 0.005000
Post Route SI ☐ Use SI Victim File
Job Control
Auto Stop ☒ Selected Nets ☐ ECO Route ☐ Fix Prewire ☐
Processors 1 Top Layer default Start Iteration default End Iteration default
Area Route ☐ Area Select Area and Route
OK Apply Attribute Cancel Help



NanoRoute Attributes

Route → NanoRoute/Attributes

NanoRoute/Attributes

Net Attributes

Net Type(s): ☐ Clock Nets ☐ External Nets ☐ Critical Nets

Net Name(s):

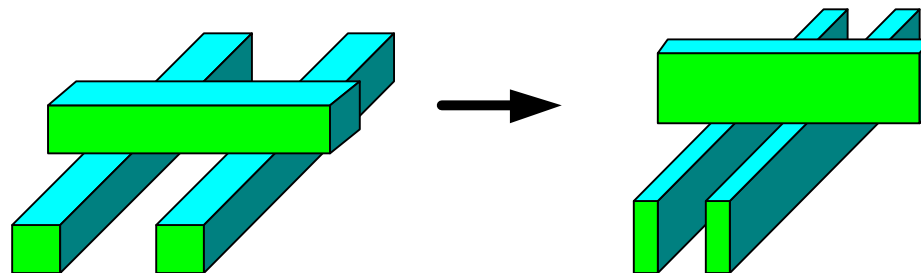
Skip Antenna	<input type="checkbox"/> TRUE <input type="checkbox"/> FALSE <input checked="" type="checkbox"/> ASIS	Top Layer	<input type="text" value="ASIS"/>	Bottom Layer	<input type="text" value="ASIS"/>
Skip Routing	<input type="checkbox"/> TRUE <input type="checkbox"/> FALSE <input checked="" type="checkbox"/> ASIS	Weight	<input type="text" value="ASIS"/>	Spacing	<input type="text" value="ASIS"/> <input type="button" value="↓"/>
Avoid Detour	<input type="checkbox"/> TRUE <input type="checkbox"/> FALSE <input checked="" type="checkbox"/> ASIS	Shield Net(s)	<input type="text" value="ASIS"/>		
SI Prevention	<input type="checkbox"/> TRUE <input type="checkbox"/> FALSE <input checked="" type="checkbox"/> ASIS	Nondefault Rule	<input type="text" value="ASIS"/>		
SI Post Route Fix	<input type="checkbox"/> TRUE <input type="checkbox"/> FALSE <input checked="" type="checkbox"/> ASIS	Pattern	<input type="text" value="ASIS"/> <input type="button" value="↓"/>		



Crosstalk

Crosstalk problem are getting more serious in 0.25um and below for:

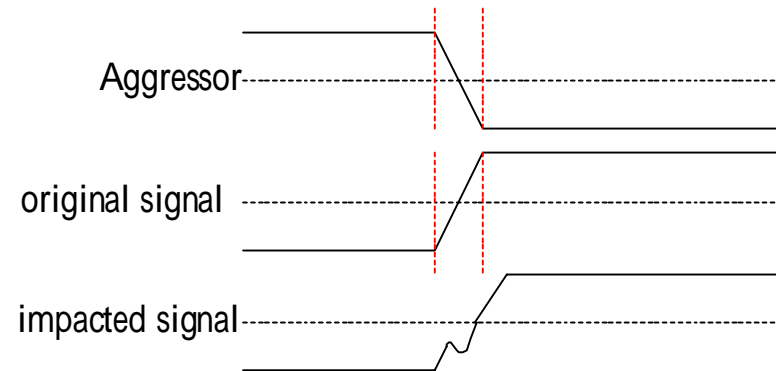
- Smaller pitches
- Greater height/width ratio
- Higher design frequency



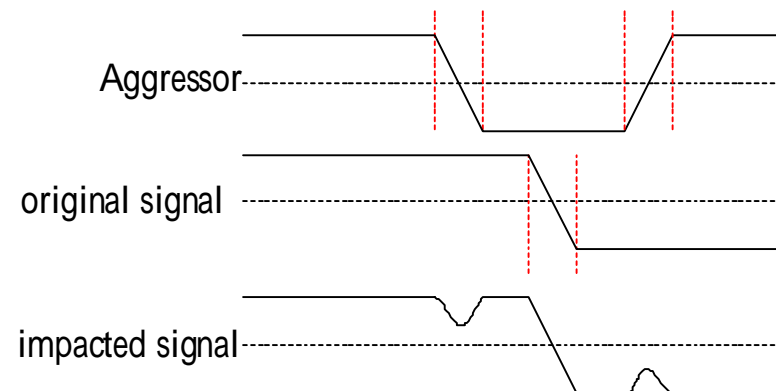


Crosstalk Problem

◆ Delay problem



◆ Noise problem

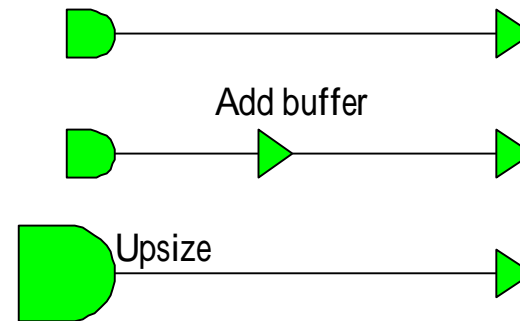




Crosstalk Prevention

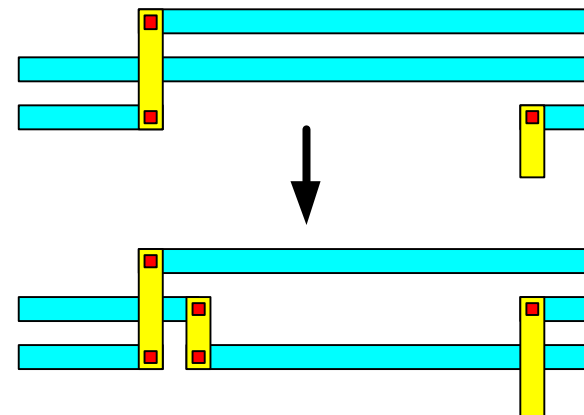
◆ Placement solution

- Insert buffer in lines
- Upsize driver
- Congestion optimization



◆ Routing solution

- Limit length of parallel nets
- Wider routing grid
- Shield special nets



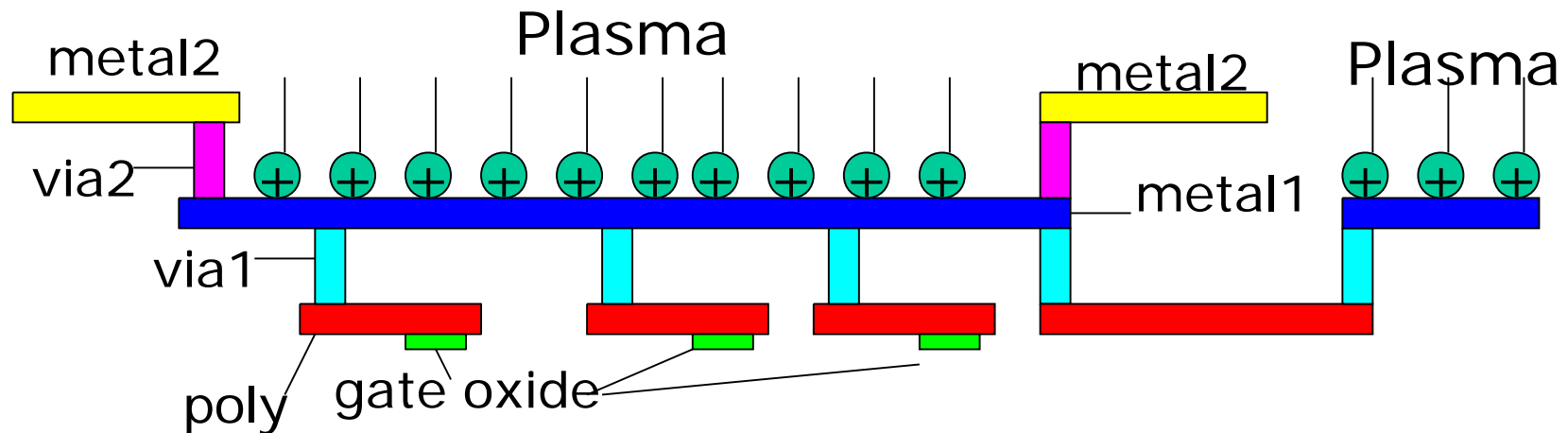


Antenna Effect

- ◆ In a chip manufacturing process, Metal is initially deposited so it covers the entire chip.
- ◆ Then, the unneeded portions of the metal are removed by etching, typically in plasma(charged particles).
- ◆ The exposed metal collect charge from plasma and form voltage potential.
- ◆ If the voltage potential across the gate oxide becomes large enough, the current can damage the gate oxide.



Antenna Ratio

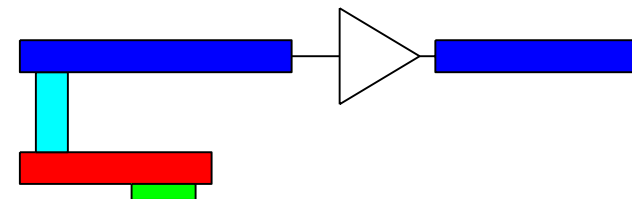
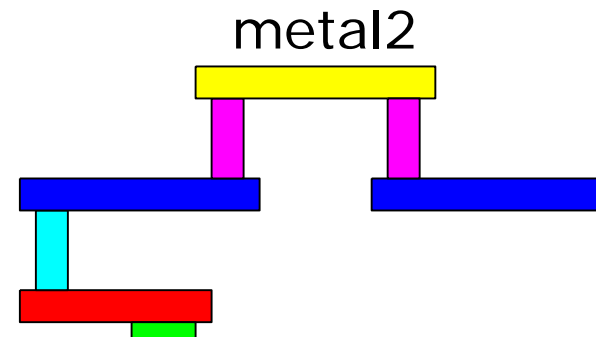
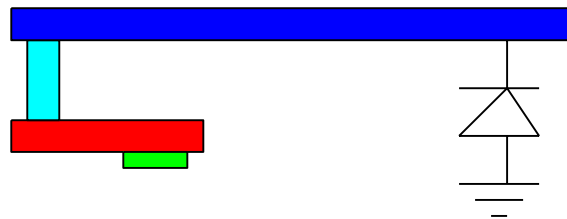
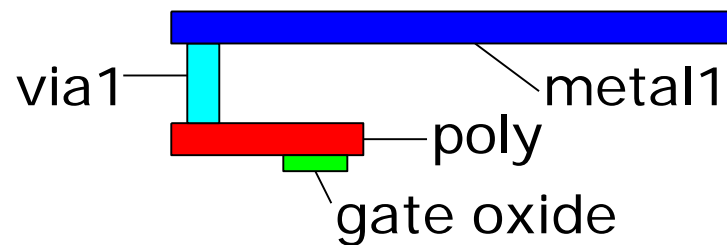


$$\text{Antenna Ratio} = \frac{\text{Area of process antennas on a node}}{\text{Area of gates to the node}}$$



Antenna Problem Repair

- ◆ Add jumper
- ◆ Add antenna cell (diode)
- ◆ Add buffer





Add Core Filler

Place → Filler → Add Filler...

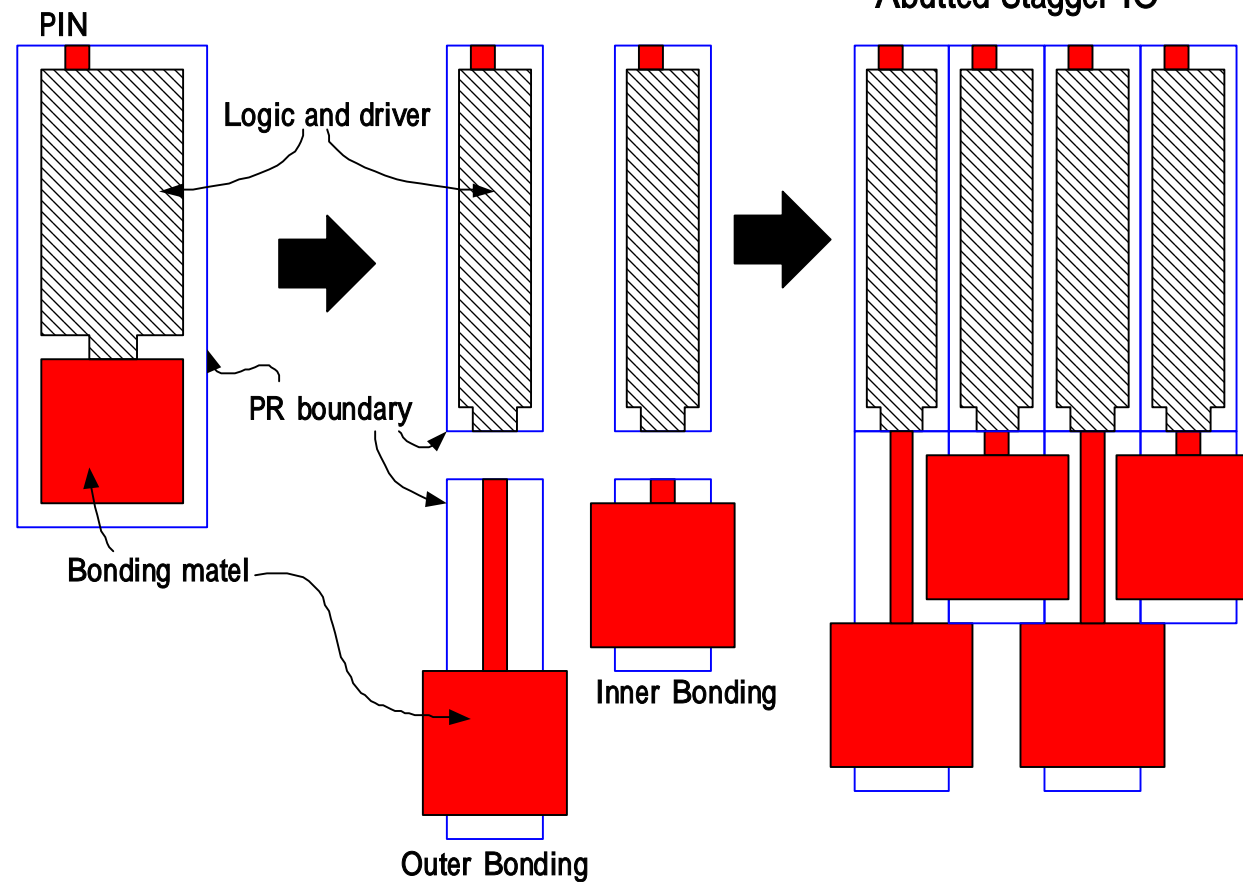
- ◆ Connect the NWELL/PWELL layer in core rows.
- ◆ Insert Well contact.
- ◆ Add from wider filler to narrower filler.

Add bonding pads (stagger IO pads only)

Linear IO pad

Stagger IO pad

Abutted Stagger IO



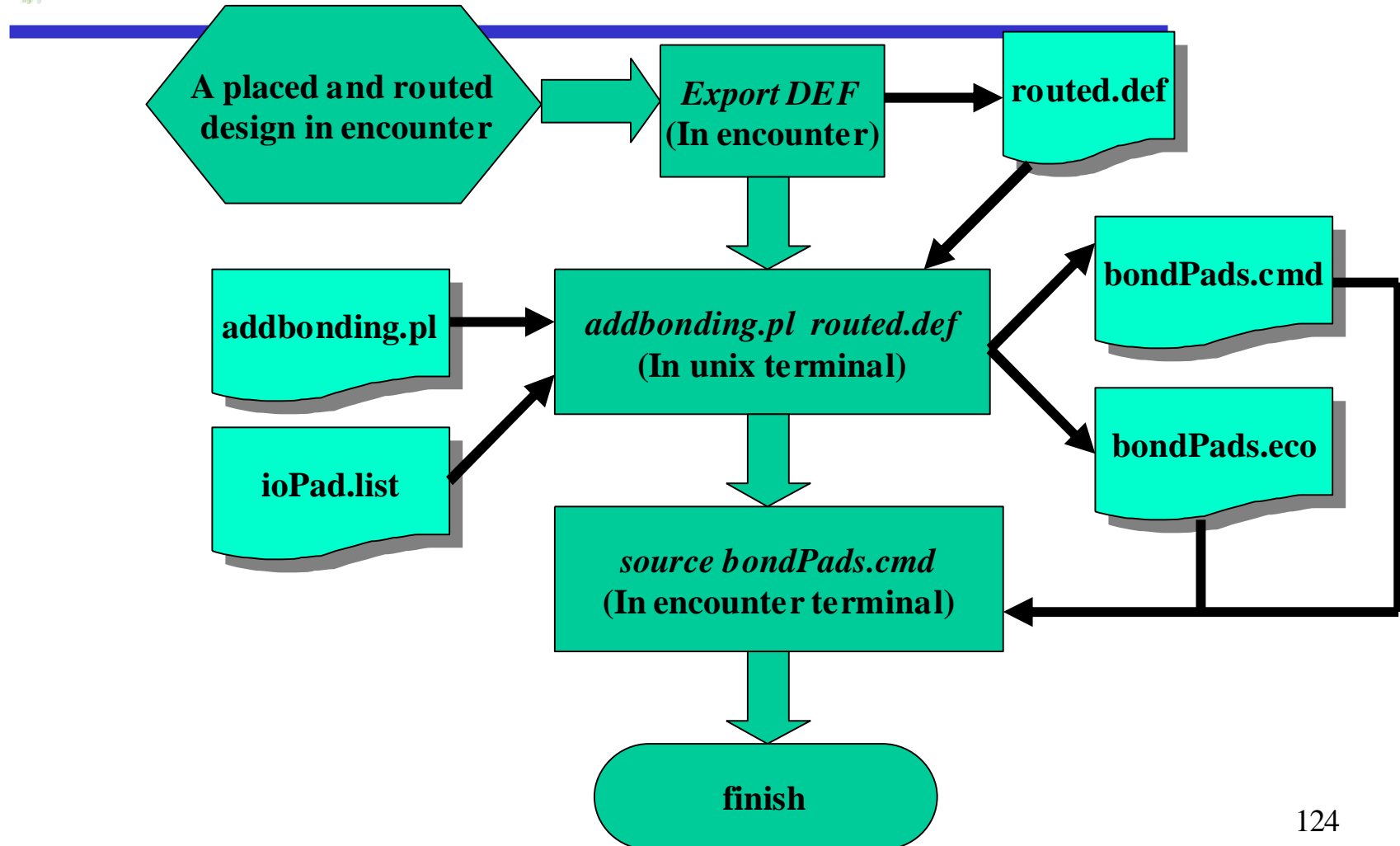


Add bonding pads (stagger IO pads only)

- ◆ For the limitation of bonding wire technique , the stagger IO pads are used in order to reduce IO pad width.
- ◆ We have to add the bonding pads after APR is finished if stagger IO pads is used. But SE does not provide a built-in function for add bonding pads, CIC reaches this purpose by the way of importing DEF.
- ◆ CIC provides a perl script to calculate the bonding pad location. The full flow is described in next page



Add bonding pads flow (stagger IO pads only)





Output Data

Design → Save → GDS...

Design → Save → Netlist...

Design → Save → DEF

- ◆ Export GDS for DRC, LVS, LPE, and tape out.
- ◆ Export Netlist for LVS and simulation.
- ◆ Export DEF for reordered scan chain.



Chapter2

Post-Layout Verification – DRC/ERC/LVS/LPE



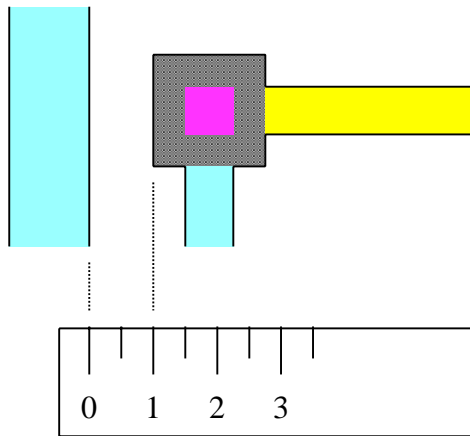
Post-Layout Verification Overview

- ◆ Post-Layout Verification do the following things :
 - DRC (Design Rule Check)
 - ERC (Electrical Rule Check)
 - LVS (Layout versus Schematic)
 - LPE/PRE (Layout Parasitic Extraction / Parasitic Resistance Extraction) and Post-Layout Simulation.

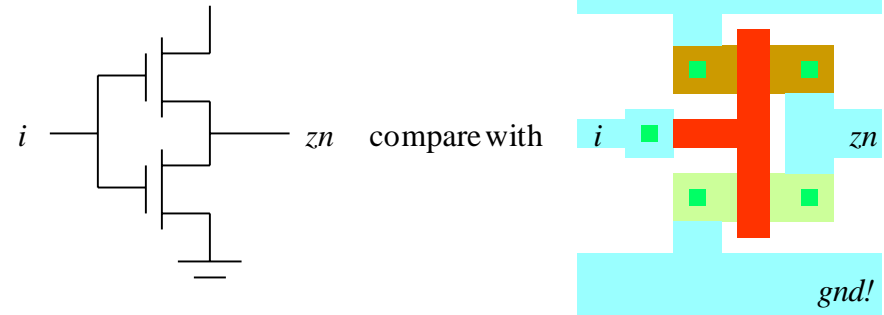


Post-Layout Verification Overview cont.

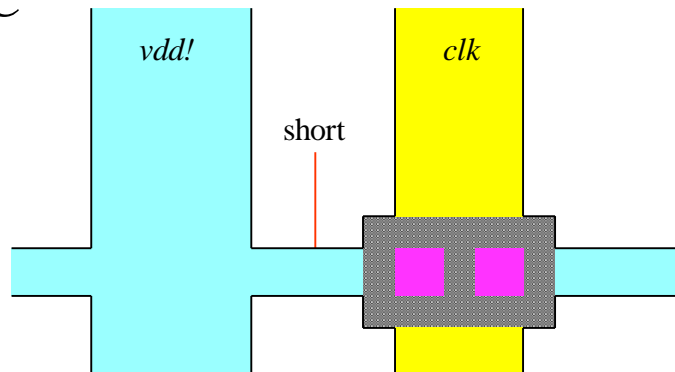
DRC



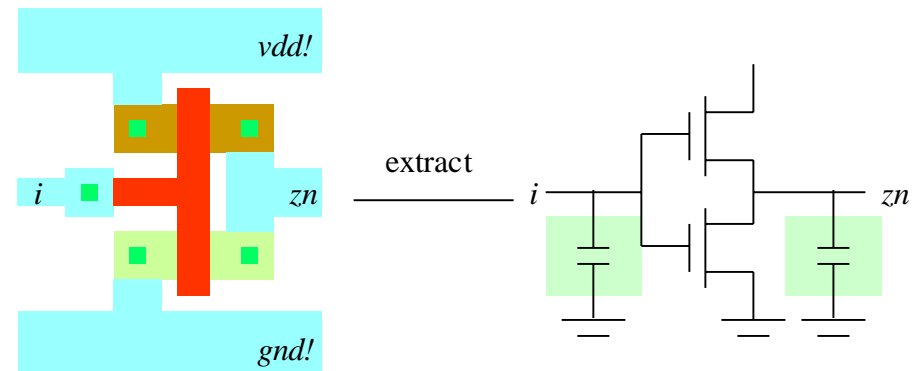
LVS



ERC

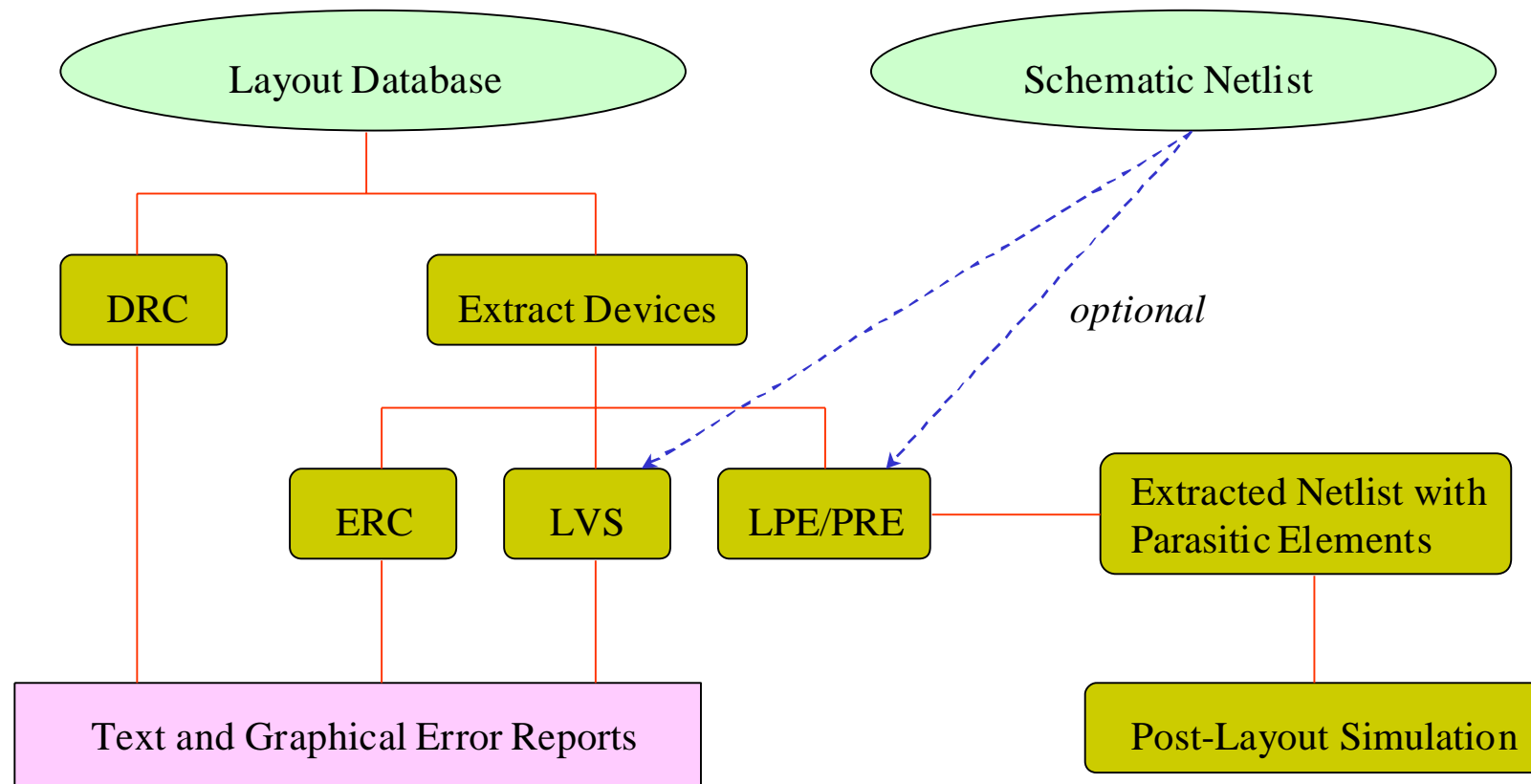


LPE/PRE





Post-Layout Verification Overview



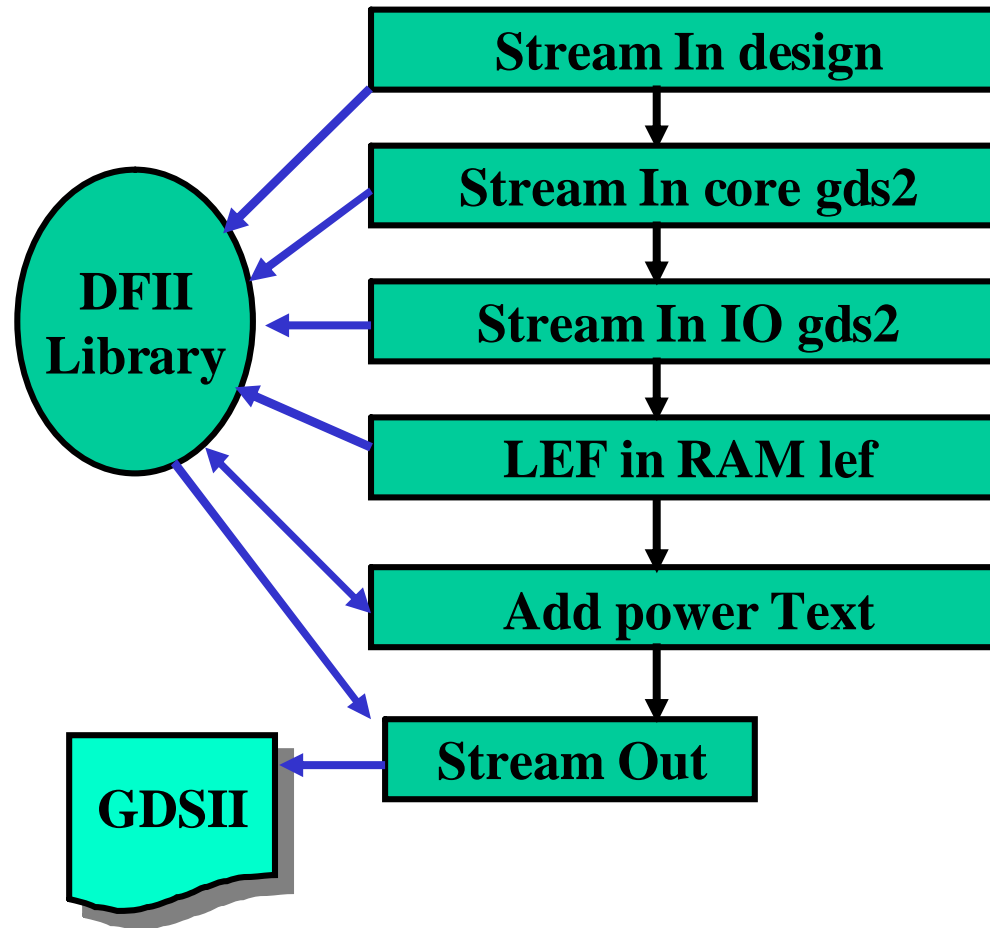


DRC flow

- ◆ Prepare Layout
 - stream in gds2
 - add power pad text
 - stream out gds2
- ◆ Prepare command file
- ◆ run DRC
- ◆ View DRC error (DRC summary/RVE)



Prepare Layout





Prepare Layout: Stream In GDSII

◆ Require:

- technology file
- display.drf

◆ *File->import->stream*

The image shows the 'Virtuoso Stream In' dialog box. It has a title bar with 'Virtuoso Stream In' and buttons for 'OK', 'Cancel', 'Defaults', 'Apply', and 'Help'. Below the title bar are two tabs: 'User-Defined Data And Options' (selected) and 'User-Defined Data'. The dialog contains several fields and options: 'Template File' with 'Load' and 'Save' buttons; 'Run Directory' with a text field; 'Input File' with a text field containing 'routed.gdsii' and a red checkmark to its left; 'Top Cell Name' with a text field containing 'CHIP'; 'Output' with three radio buttons: 'Opus DB' (selected), 'ASCII Dump', and 'TechFile'; 'Library Name' with a text field and a red checkmark to its left; 'ASCII Technology File Name' with a text field containing 'tsmc25_5lmtf' and a red checkmark to its left; 'Scale UU/DBU' with a text field containing '0.00100000'; 'Units' with three radio buttons: 'micron' (selected), 'millimeter', and 'mil'; 'Process Nice Value 0-20' with a text field containing '0'; and 'Error Message File' with a text field containing 'PIPO.LOG'.



Prepare Layout: Add Power Text

- ◆ Add power text for LVS and Nanosim
- ◆ For UMC18/artisan library
 - Add text DVDD for IO power pad
 - Add text DGND for IO ground pad
 - Add text VDD for core power pad
 - Add text GND for core ground pad



Prepare Layout: Stream Out GDSII

◆ *File->Export->stream..*

The image shows the 'Virtuoso Stream Out' dialog box. It has a title bar with a minus button and the text 'Virtuoso Stream Out'. Below the title bar are buttons for 'OK', 'Cancel', 'Defaults', 'Apply', and 'Help'. The dialog is divided into two tabs: 'User-Defined Data And Options' (selected) and 'User-Defined Data'. Under the 'User-Defined Data And Options' tab, there are several fields and options:

- 'Template File' with 'Load' and 'Save' buttons.
- 'Run Directory' with a text field.
- 'Library Name' with a text field containing 'CHIP' (marked with a red checkmark).
- 'Top Cell Name' with a text field containing 'CHIP' (marked with a red checkmark).
- 'View Name' with a text field containing 'layout'.
- 'Output' with two radio buttons: 'Stream DB' (selected) and 'ASCII Dump'.
- 'Output File' with a text field containing 'CHIP.db' (marked with a red checkmark).
- 'Scale UU/DBU' with a text field containing '0.00100000'.
- 'Units' with three radio buttons: 'micron' (selected), 'millimeter', and 'mil'.
- 'Process Nice Value 0-20' with a text field containing '0'.



Prepare command file

◆ Prepare DRC Command file:

➤ **0.18** (*CBDK018_UMC_Artisan*) Calibre

- ✓ 180nm_layers.cal
- ✓ G-DF-IXEMODE_RCMOS18-1.8V-3.3V-1P6M-MMC-Calibre-drc-2.2-p1



Prepare Calibre Command file

◆ Edit runset file

```
LAYOUT PATH "CHIP.gds2"  
LAYOUT PRIMARY "CHIP"  
LAYOUT SYSTEM GDSII  
...  
...  
...  
DRC SELECT CHECK  
    NW.W.1  
    NW.W.2  
...  
DRC UNSELECT CHECK  
    NW.S.1Y  
    NW.S.2Y  
...  
DRC ICSTATION YES  
INCLUDE "Calibre-drc-cur"
```



Submit Calibre Job

◆ Submit Calibre Job

- `calibre -drc umc18DRC.cal`

◆ Result log

- `CHIP.drc.summary` (ASCII result)
- `CHIP.drc.results` (Graphic result)



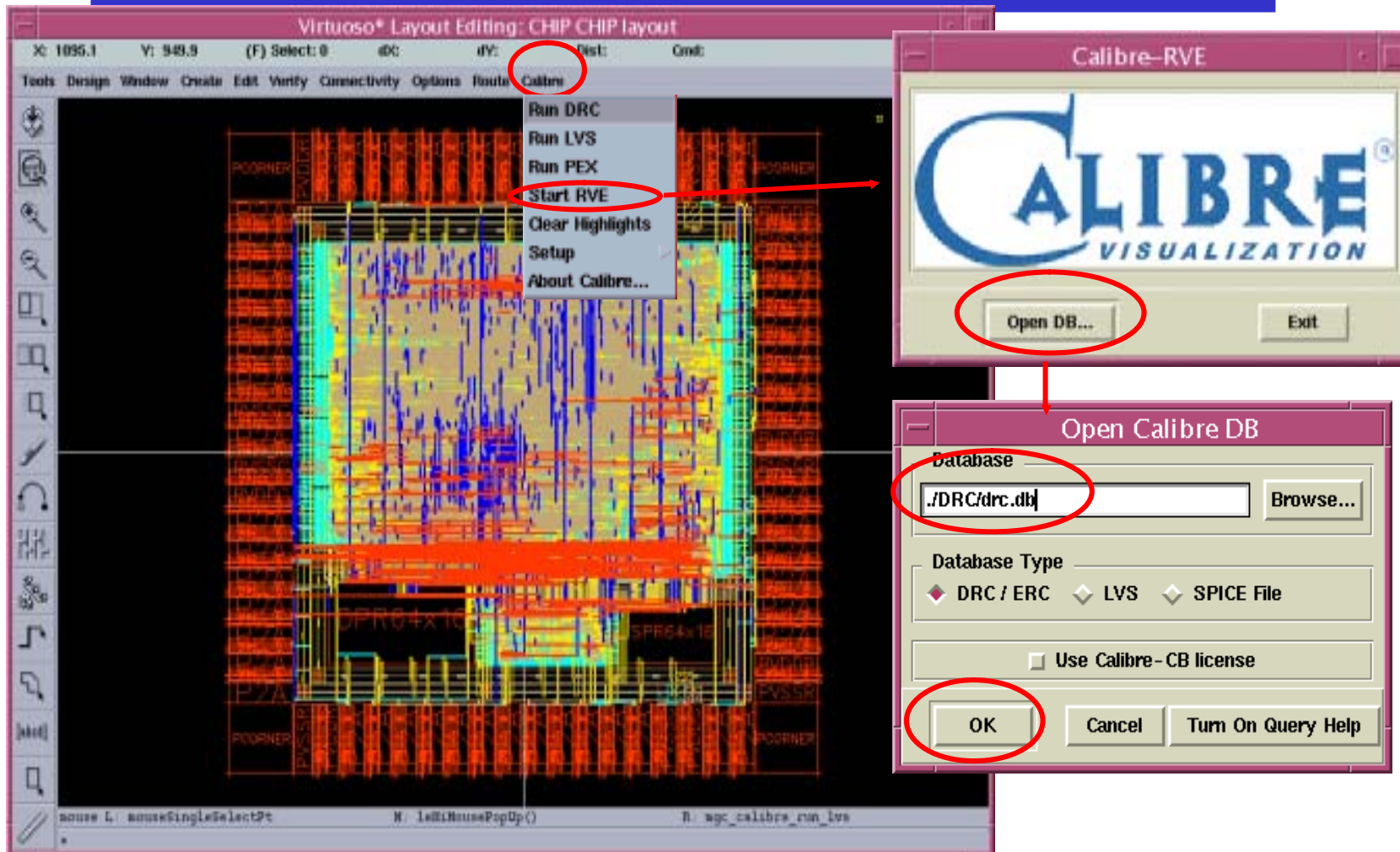
Using Calibre RVE

◆ Add in .cdsinit

```
setSkillPath(". ~/ /usr/memtor/Calibre_ss/cur/shared/pkgs/icb/tools/queryskl")  
load("calibre.skl")
```



Using Calibre RVE





Using Calibre RVE

Calibre – DRC RVE : drc.db

File View Highlight Setup Help

> < H > Z

13126 Errors (in 19 of 19 Checks)

- Cell CHIP – 13126 Errors
 - Check 4.1G.a – 1000 Errors
 - Check 4.2B.a_F – 33 Errors
 - 01 02 03 04 05 06 07 08 09 10
 - 11 12 13 14 15 16 17 18 19 20
 - 21 22 23 24 25 26 27 28 29 30
 - 31 32 33
 - Check 4.14G – 1000 Errors
 - Check 4.16C.a – 1000 Errors
 - Check 4.16C.b – 510 Errors
 - Check 4.16D.b – 1000 Errors

Cell Top

4-Vertex Polygon
(CHIP coordinates)

-301.31	-257.24
-301.27	-257.24
-301.27	-254.83
-301.31	-254.83

Checktext

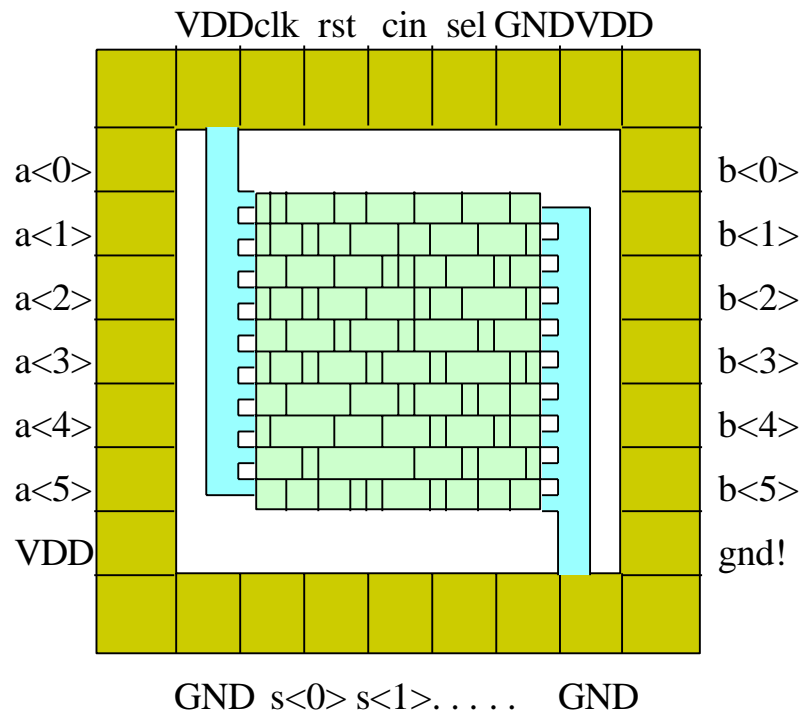
Rule File Pathname: G-DF-MIXEMODE_RFCMOS18-1.8V-3.3V-1P6M-MMC-Calibre-drc-2.2-p1
Minimum N-Well to N-Well spacing for equal-potential is 0.9

Cell CHIP [Check 4.2B.a_F] : 11 of 33 Errors

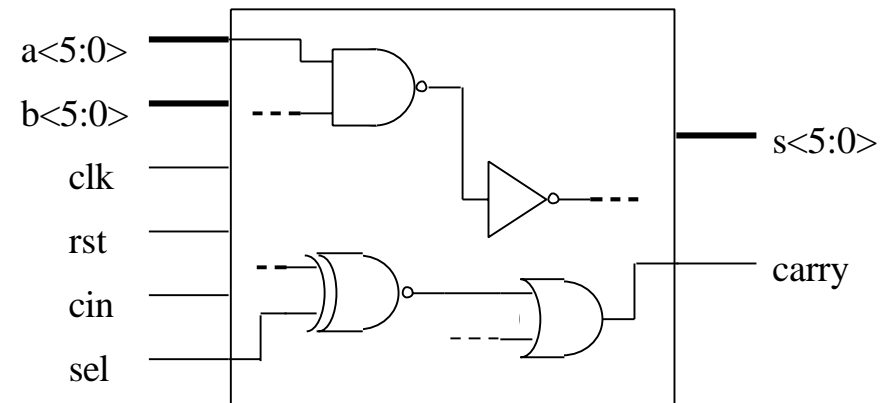


LVS Overview

Layout Data



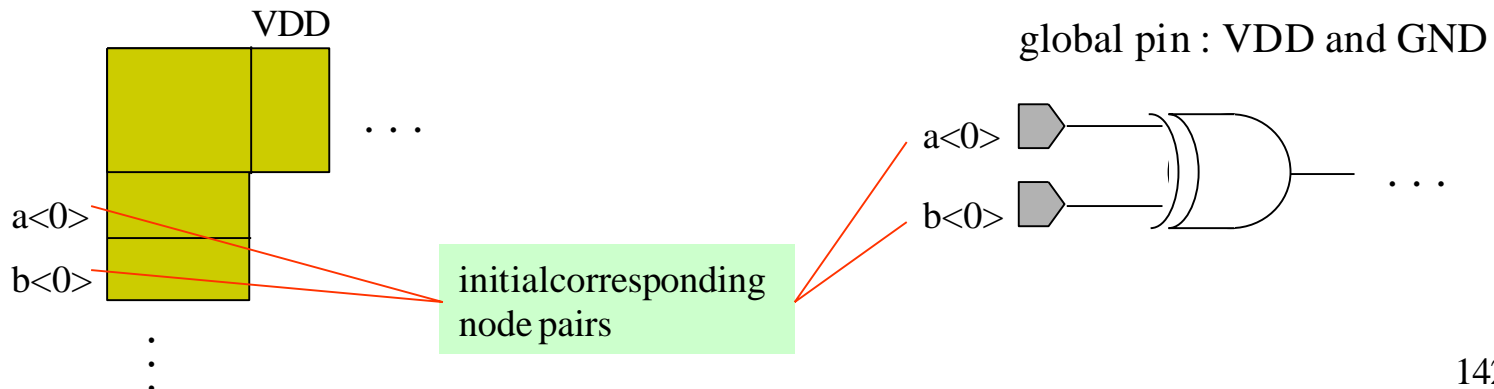
Schematic Netlist





Initial Correspondence Points

- ◆ Initial correspondence points establish a starting place for layout and schematic comparison.
- ◆ Create initial correspondence node pairs by
 - adding text strings on layout database.
 - all pins in the top of schematic netlist will be treated as an initial corresponding node if calibre finds a text string in layout which matches the node name in schematic.





Black-Box LVS

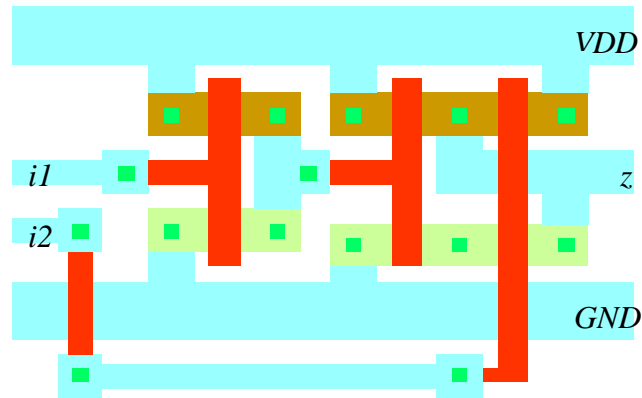
Calibre black-box LVS

- One type of hierarchical LVS.
- Black-box LVS treats every library cell as a *black box*.
- Black-box LVS checks only the interconnections between library cells in your design, but not cell inside.
- You need not know the detail layout of every library cells.
- Reduce CPU time.

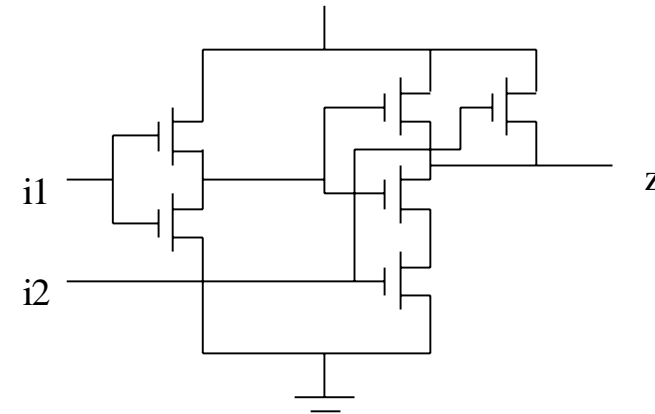


Black-Box LVS vs. Transistor-Level LVS

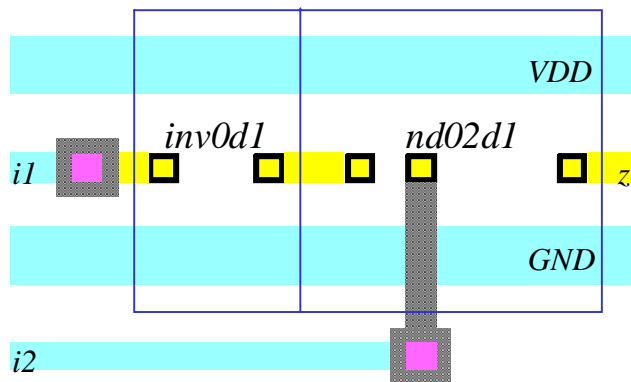
Transistor Level LVS



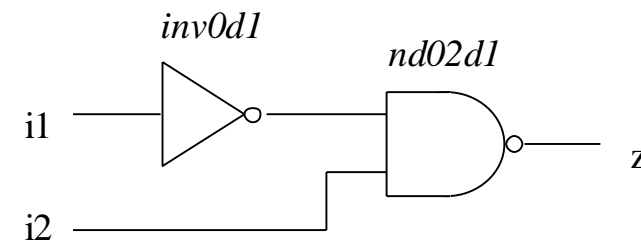
vs.



Black-Box LVS



vs.





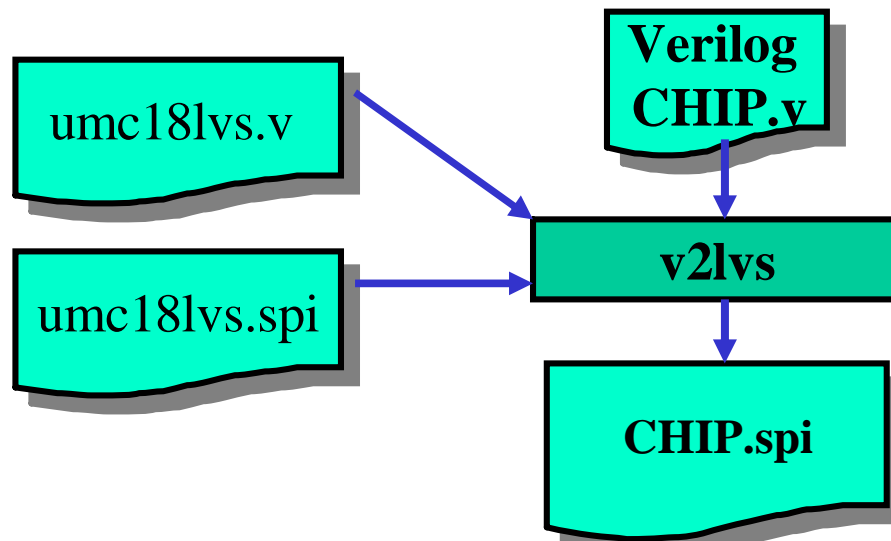
LVS flow

- ◆ Prepare Layout
 - The same as DRC Prepare Layout
- ◆ Prepare Netlist
 - v2lvs
- ◆ Prepare calibre command file
- ◆ run calibre LVS
- ◆ View LVS error (LVS summary/RVE)



Prepare Netlist for Calibre LVS

Prepare Netlist



- ◆ *v2lvs -v CHIP.v -l umc18lvs.v -o CHIP.spi -s umc18lvs.spi -s1 VDD -s0 GND*

If a macro DRAM64x16 is used

- ◆ *v2lvs -v CHIP.v -l umc18lvs.v -l DRAM64x16.v -o CHIP.spi -s umc18lvs.spi -s DRAM64x16.spi -s1 VDD -s0 GND*



CIC Supported Files (0.18)

◆ CIC supports the following files in our cell library design kit.

➤ Calibre LVS runset file

umc18LVS.cal

➤ Calibre LVS rule file

G-DF-MIXEDMODE_RFCMOS18-1.8V_3.3V-1P6M-MMC-
CALIBRE-LVS-1.2-P3.txt

➤ Black-box LVS relative files

✓ pseudo spice file

umc18LVS.spi

✓ **pseudo verilog** file

umc18LVS.v



Black Box related file

◆ Pseudo spice file

```
.GLOBAL VDD VSS  
.SUBCKT AN2D1 Z A1 A2 VDD GND  
.ENDS  
...
```

◆ Pseudo verilog file

```
module AN2D1 (Z, A1, A2);  
    output Z;  
    input A1;  
    input A2;  
endmodule  
...
```



Prepare command file for Calibre LVS

◆ Edit Calibre LVS runset

```
LAYOUT PATH "CHIP.calibre.gds"
```

```
LAYOUT PIMARY "CHIP"
```

```
LAYOUT SYSTEM GDSII
```

```
SOURCE PATH "CHIP.spi"
```

```
SOURCE PRIMARY "CHIP"
```

```
...
```

```
...
```

```
INCLUDE "/calibre/LVS/Calibre-lvs-cur"
```

◆ Edit Calibre LVS rule file

```
...
```

```
...
```

```
LVS BOX PVSSC
```

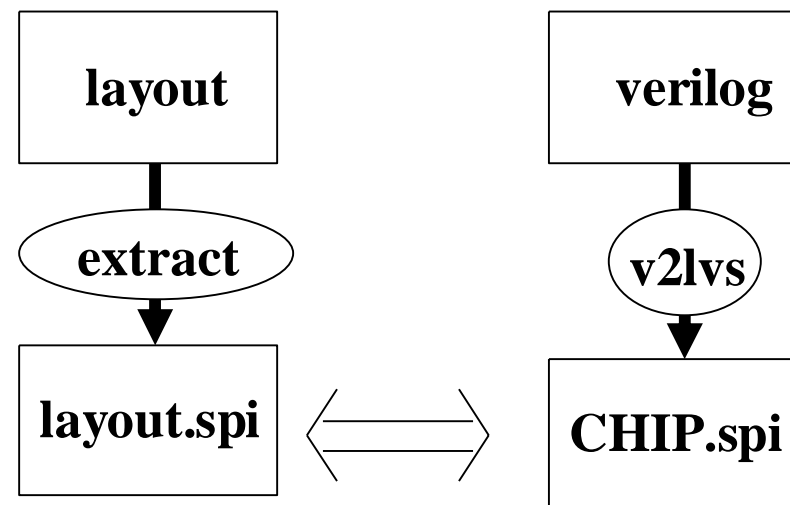
```
LVS BOX PVSSR
```

```
LVS BOX DRAM64x4s
```



Submit Calibre LVS

◆ *calibre -lvs -spice layout.spi -hier -auto umc18LVS.cal > lvs.log*





Check Calibre LVS Summary

- ◆ OVERALL COMPAISON RESULTS
- ◆ CELL SUMMARY
- ◆ INFORMATION AND WARNINGS
- ◆ Initial Correspondence Points



Check Calibre LVS Summary

OVERALL COMPAISON RESULTS

OVERALL COMPARISON RESULTS

	#	#####		—	—
	#	#	#	*	*
#	#	#	CORRECT	#	
#	#	#		#	└─┘
	#	#####			



Check Calibre LVS Summary

CELL SUMMARY

CELL SUMMARY

Result	Layout	Source
-----	-----	-----
CORRECT	CHIP	CHIP



Check Calibre LVS Summary

INFORMATION AND WARNINGS

INFORMATION AND WARNINGS

	Matched Layout	Matched Source	Unmatched Layout	Unmatched Source	Component Type
	-----	-----	-----	-----	-----
Nets:	11525	11525	0	0	
Instances:	1	1	0	0	ADDFHX1
	54	54	0	0	ADDFHX4
	79	79	0	0	ADDFX2
	542	542	0	0	AND2X1

	8	8	0	0	XOR3X2
	-----	-----	-----	-----	-----
Total Inst:	10682	10682	0	0	



Check Calibre LVS Summary

Initial Correspondence Points

o Initial Correspondence Points:

Nets: DVDD VDD DGND GND I_X[2] I_X[3] I_X[4]
I_X[5] I_X[6] I_X[7] I_X[8] I_X[9] I_X[10] I_X[11]
O_SCAN_OUT O_Z[0] O_Z[1] O_Z[2] O_Z[3] I_HALT
I_RESET_I_DoDCT I_RamBistE I_CLK I_SCAN_IN
I_SCAN_EN I_X[0] O_Z[4] I_X[1] O_Z[5] O_Z[6]
O_Z[7] O_Z[8] O_Z[9] O_Z[10] O_Z[11]



Check Calibre LVS Log

- ◆ TEXT OBJECT FOR CONNECTIVITY EXTRACTION
- ◆ PORTS
- ◆ Extraction Errors and Warnings for cell “CHIP”



Check Calibre LVS Log

TEXT OBJECT FOR CONNECTIVITY EXTRACTION

TEXT OBJECTS FOR CONNECTIVITY EXTRACTION

O_Z[0] (523.447,31.68) 105 CHIP	O_Z[1] (598.068,31.68) 105 CHIP
O_Z[2] (821.931,31.68) 105 CHIP	O_Z[3] (896.553,31.68) 105 CHIP
O_Z[4] (971.175,31.68) 105 CHIP	O_Z[5] (1164.455,372.964) 105 CHIP
O_Z[6] (1164.455,446.966) 105 CHIP	O_Z[7] (1164.455,520.968) 105 CHIP
O_Z[8] (1164.455,594.97) 105 CHIP	O_Z[9] (1164.455,668.972) 105 CHIP
O_Z[10] (1164.455,742.974) 105 CHIP	O_Z[11] (1164.455,816.976) 105 CHIP
.....	
.....	



Check Calibre LVS Log PORTS

PORTS

O_Z[0] (523.447,31.68) 105 CHIP

O_Z[2] (821.931,31.68) 105 CHIP

O_Z[4] (971.175,31.68) 105 CHIP

.....

.....

O_Z[1] (598.068,31.68) 105 CHIP

O_Z[3] (896.553,31.68) 105 CHIP

O_Z[5] (1164.455,372.964) 105 CHIP



Check Calibre LVS Log

Extraction Errors and Warnings for cell "CHIP"

Extraction Errors and Warnings for cell "CHIP"

WARNING: Short circuit - Different names on one net:

Net Id: 18

- (1) name "GND" at location (330.301,216.95) on layer 102 "M2_TEXT"
- (2) name "GND" at location (673.2,29.1) on layer 101 "M1_TEXT"
- (3) name "VDD" at location (748.1,31.5) on layer 101 "M1_TEXT"
- (4) name "VDD" at location (208.93,274.56) on layer 101 "M1_TEXT"

The name "VDD" was assigned to the net.



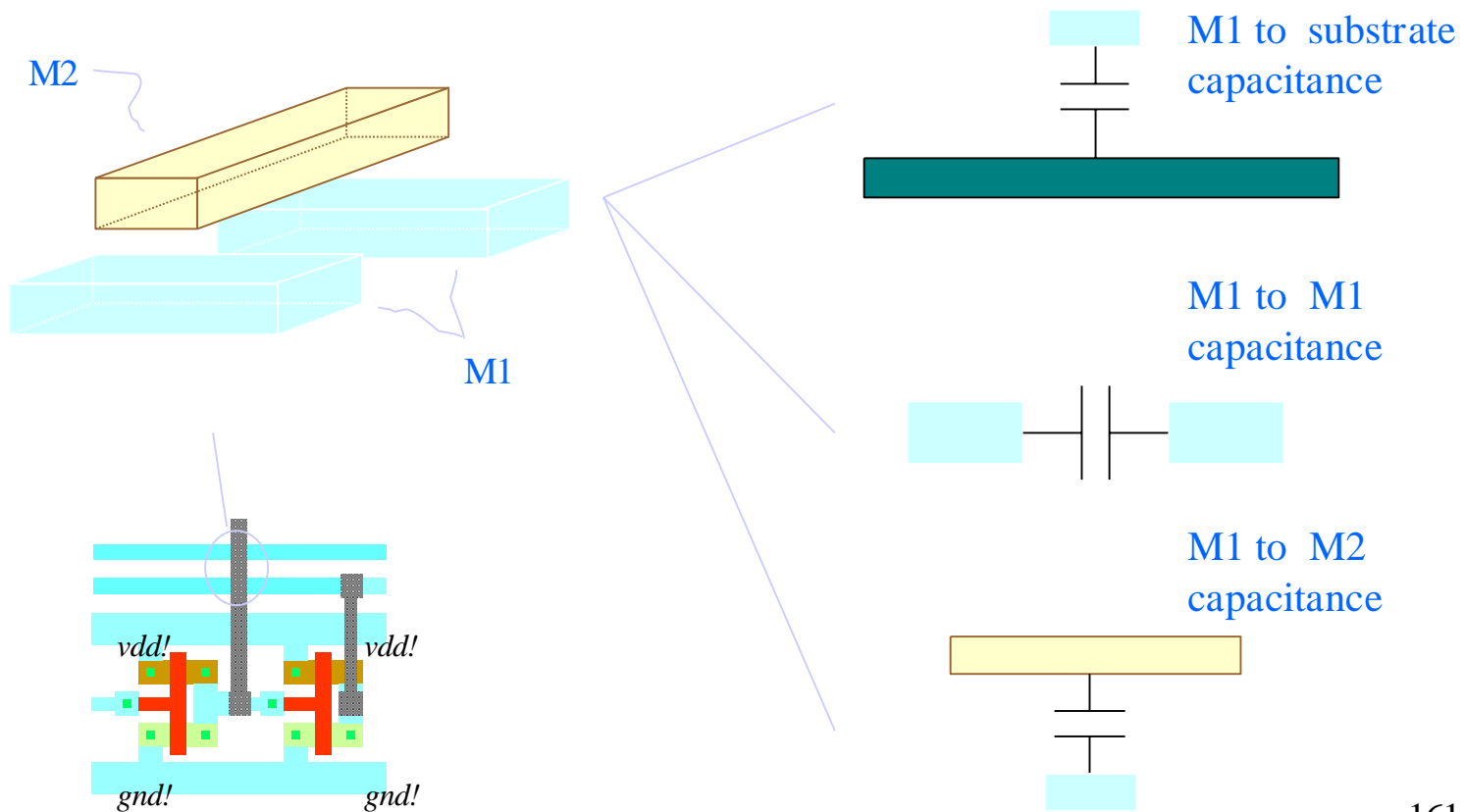
Chapter3

Post-Layout Timing Analysis -- Nanosim



What Introduce After Place&Route?

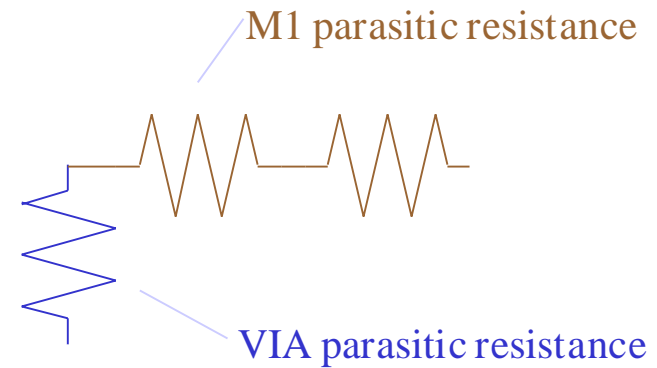
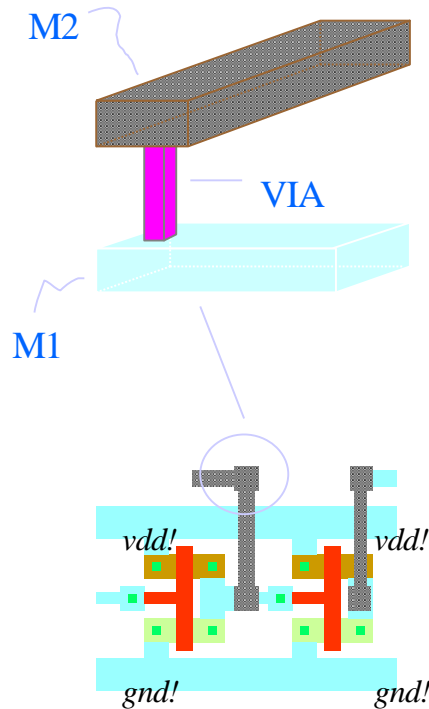
◆ Interconnection wire's parasitic capacitance.





What Introduce After Place&Route?

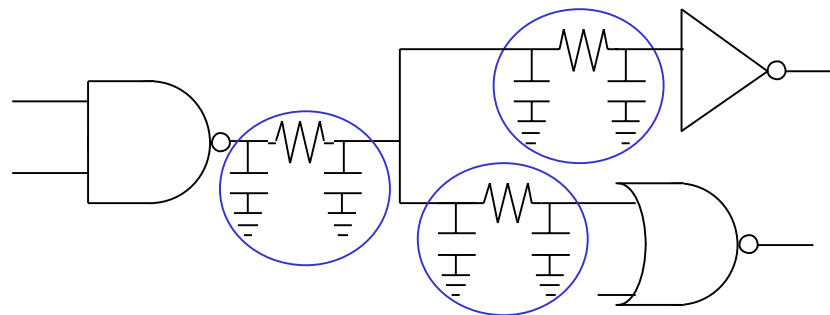
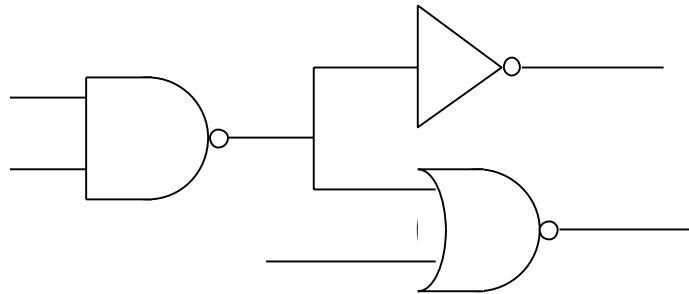
- ◆ Interconnection wires' parasitic resistance.





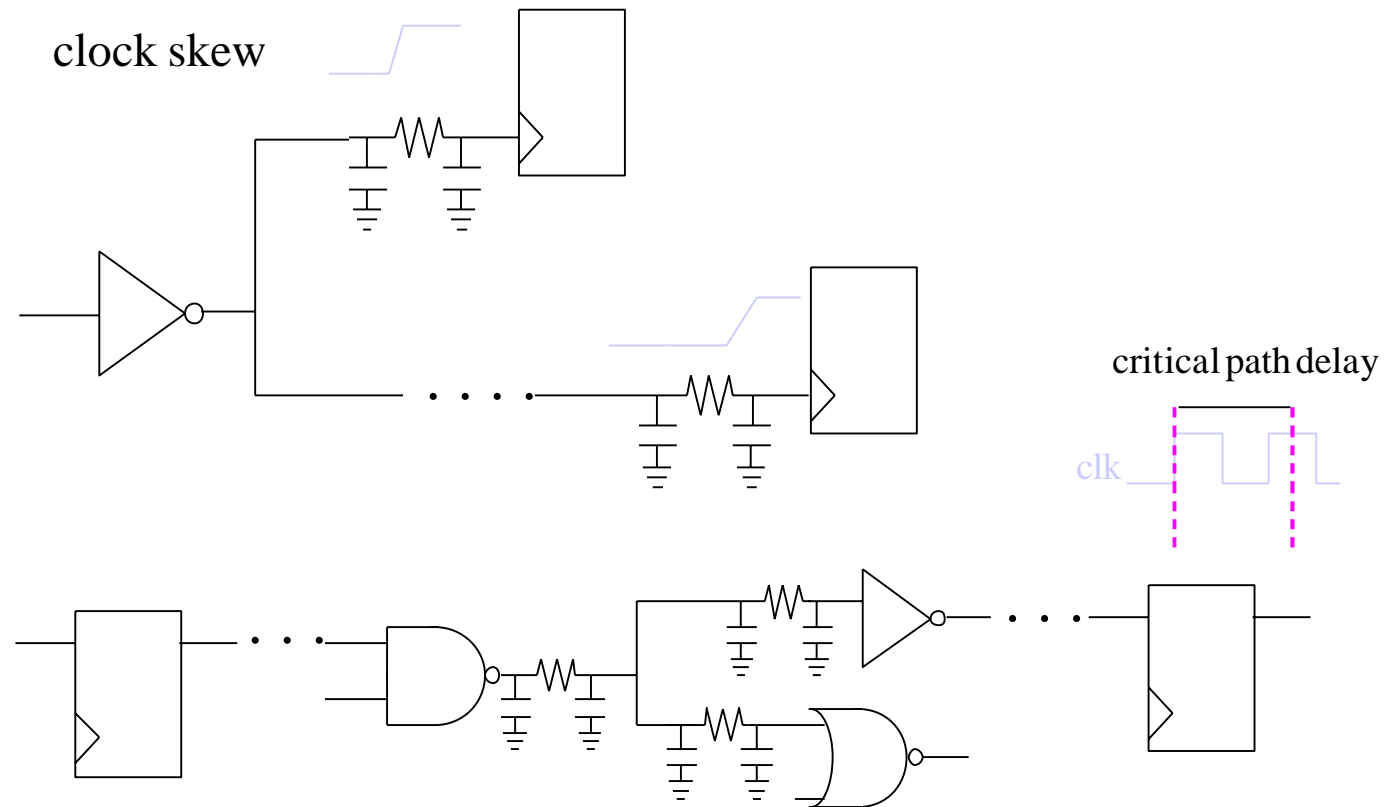

Pre-Layout And Post-Layout Design

- ◆ A pre-layout design (before P&R) and a post-layout design (after P&R)



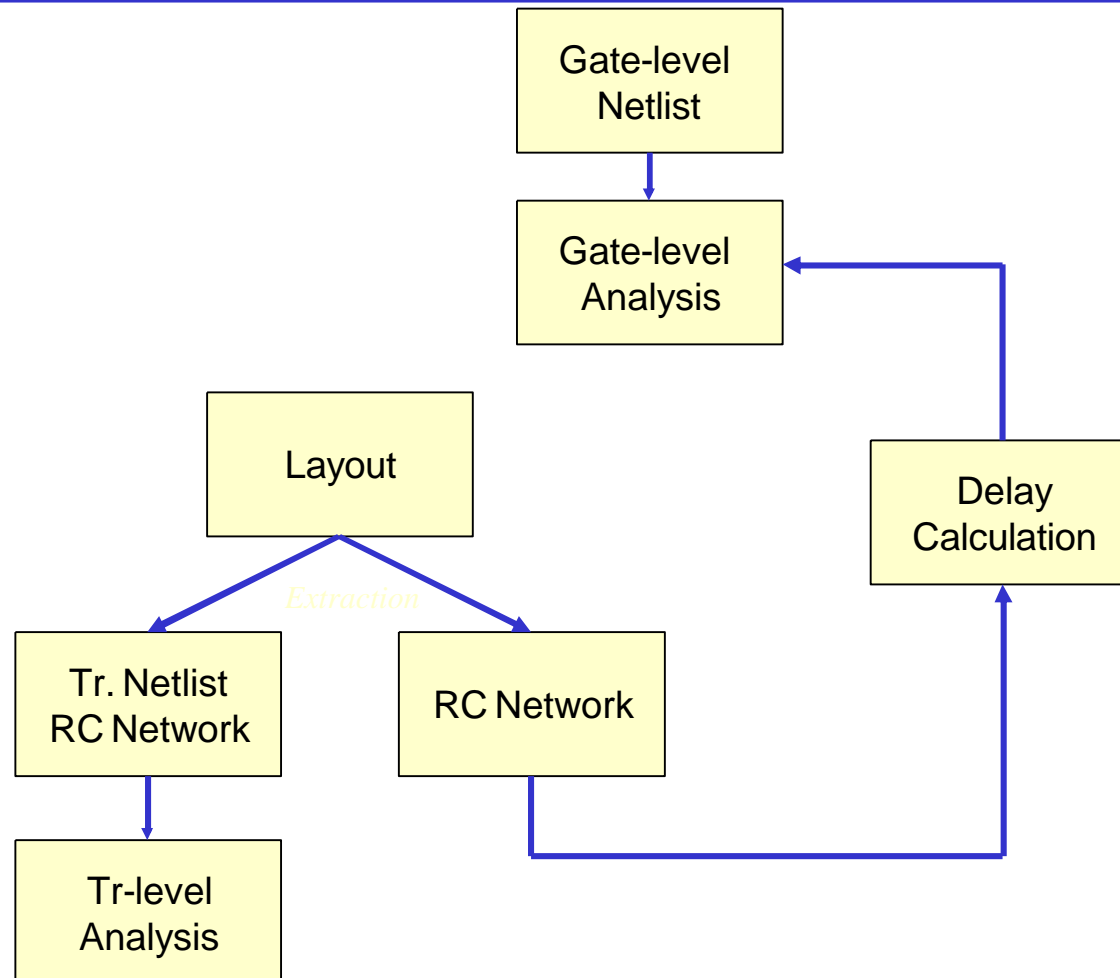


Why Post-Layout Simulation?



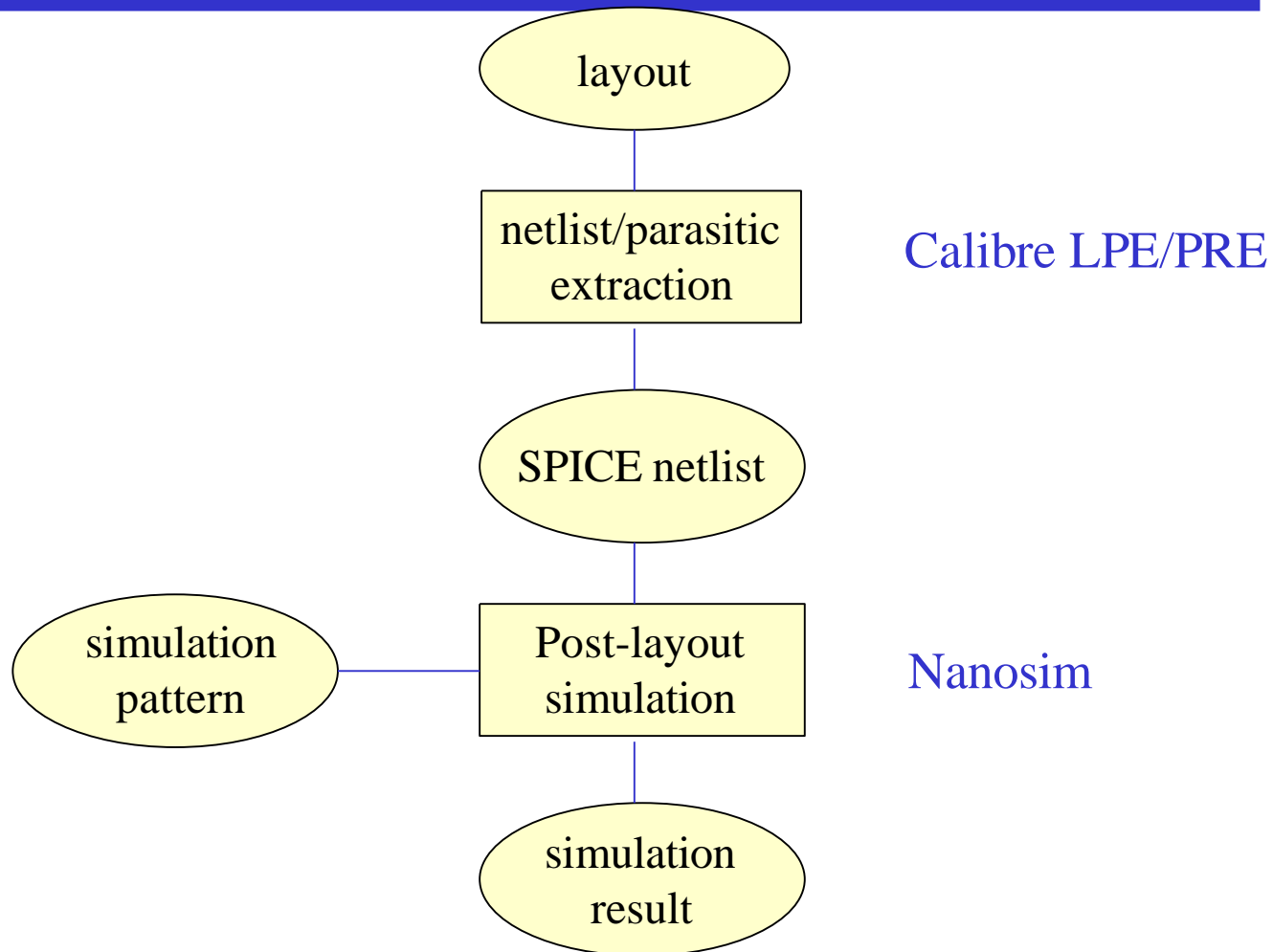


Post-layout Timing Analysis Flow





Transistor-level Post-layout Simulation





What is Nanosim

- ◆ *Nanosim* is a *transistor-level timing* simulation tool for digital and mixed signal CMOS and BiCMOS designs.
- ◆ *Nanosim* handles voltage simulation and timing check.
- ◆ Simulation is event driven, targeting between SPICE (*circuit simulator*) and Verilog (*logic simulator*).



Prepare for Post-Layout Simulation

◆ Apply for a CIC account

- <http://www.cic.org.tw> ⇒ 工作站帳號申請.
- fill in your personal data and your request.

◆ Install *identd* program

- this program is used to identify yourself when you log into CIC's account from remote machine.

◆ Put your DB file to CIC's account



Replace Layout / LPE

◆ Qentry

```
-M {LPE}
-tech {UMC18 | TSMC18 | TSMC25 | TSMC35}
-f GDSII
-T Top_cell_name
-s Ram_spce_filename
-t {ra1sd | ra1sh | ra2sd | ra2sh | rf2sh |
    t18ra1sh | t18ra2sh | t18rf1sh | t18rf2sh | t18rodsh |
    18ra1sh_1 | 18ra1sh_2 | 18ra2sh}
-c {UMC18 | TSMC18 | TSMC25 | TSMC35}
-i {UMC18 | TSMC18 | TSMC25 | TSMC35}
-o Netlist_file_name
```

◆ Example:

```
➤ Qentry -M LPE -tech UMC18 -f CHIP.gds -T CHIP
-s RAM1.spec -t 18ra2sh -s RAM2.spec -t 18ra1sh_1
-s RAM3.spec -t 18ra1sh_2 -c UMC18 -i UMC18 -o CHIP.netlist
```

◆ Use `qstat` to check the status of your job.

◆ The result is stored in “`result_#`” directory.



Replace/LPE

◆ INPUT

- gds2
- ram spec

◆ OUTPUT

- output netlist
- TOP_CELL.NAME
- nodename
- spice.header
- nanosim.run
- log files for stream in, stream out, lpe



Running Nanosim

◆ Qentry

-M {NANOSIM}
-n {CHIP.io}
-nspice CHIP.netlist spice.header
-nvec CHIP.vec
-m Top_cell_name
-c {CHIP.cfg}
-z {CHIP.tech.z}
-o Output_file_name
-out fsdb
-t Total_simulation_time

◆ Example:

➤ **Qentry -M NANOSIM -nspice CHIP.netlist spice.header -nvec
CHIP.vec -m CHIP -c CHIP.cfg -z CHIP.tech.z -o UMC18 -t 100**

◆ Use Qstat to check the status of your job.

◆ The result is stored in “result_#” directory.



Spice Header File

◆ Spice Header File → Modify PVT

- `.lib 'l18u18v.012' L18U_BJD`
- `.lib 'l18u18v.012' L18U18V_TT`
- `.lib 'l18u33v_g2.011' l18u33v_tt`
- `*epic tech="voltage 3.3"`
- `*epic tech="temperature 100"`



Generate Nanosim Simulation Pattern

◆ Input simulation pattern --- *vec* format

```
type vec
signal  CLOCK,START,IN[7:0]
;      time      clock    start      in<7:0>
radix          1         1         44
io             i         i         ii
high 3.3
low 0.0
      25           0         0         xx
      50           1         0         xx
      75           0         0         xx
. . . . .
```



Generate Nanosim Simulation Pattern

◆ Input simulation pattern --- *nsvt* format

```
type nsvt
signal    CLOCK,START,IN[7:0]
;
          clock    start    in[7:0]
radix      1        1        44
io         i        i        ii
period 25
high 3.3
low 0.0
          0        0        xx
          1        0        xx
          0        0        xx
. . . . .
```



Generate Nanosim Simulation Pattern

- ◆ You can generate Nanosim simulation pattern from Verilog-XL stimulus.

Verilog *test bench* file

```
integer outf;  
initial begin  
    outf = $fopen("input.dat");  
    . . . . .  
    $fclose(outf);  
    $finish;  
end  
  
always @(sys_clock or start or in)  
    $fdisplay(outf,"%t %b %b %h",$time,sys_clock,start,in);  
    . . . . .
```



Nanosim Configuration File

Example *Nanosim_configuration* file

```
bus_notation [ : ]
print_node_logic ADRS[0]
print_node_logic CLK
print_node_logic DATA[0]
. . . . .
report_node_power VDD
set_node_gnd DGND
set_node_gnd GND
set_node_v DVDD 3.3
set_node_v VDD 1.8
```

nodename file

```
ADRS[0]
ADRS[1]
. . . . .
CLK
DATA[0]
. . . . .
```



View Simulation Result --- nWave

◆ *NOVAS nWave*

- a waveform viewer which support Timemill output waveform format.

◆ Environment setup

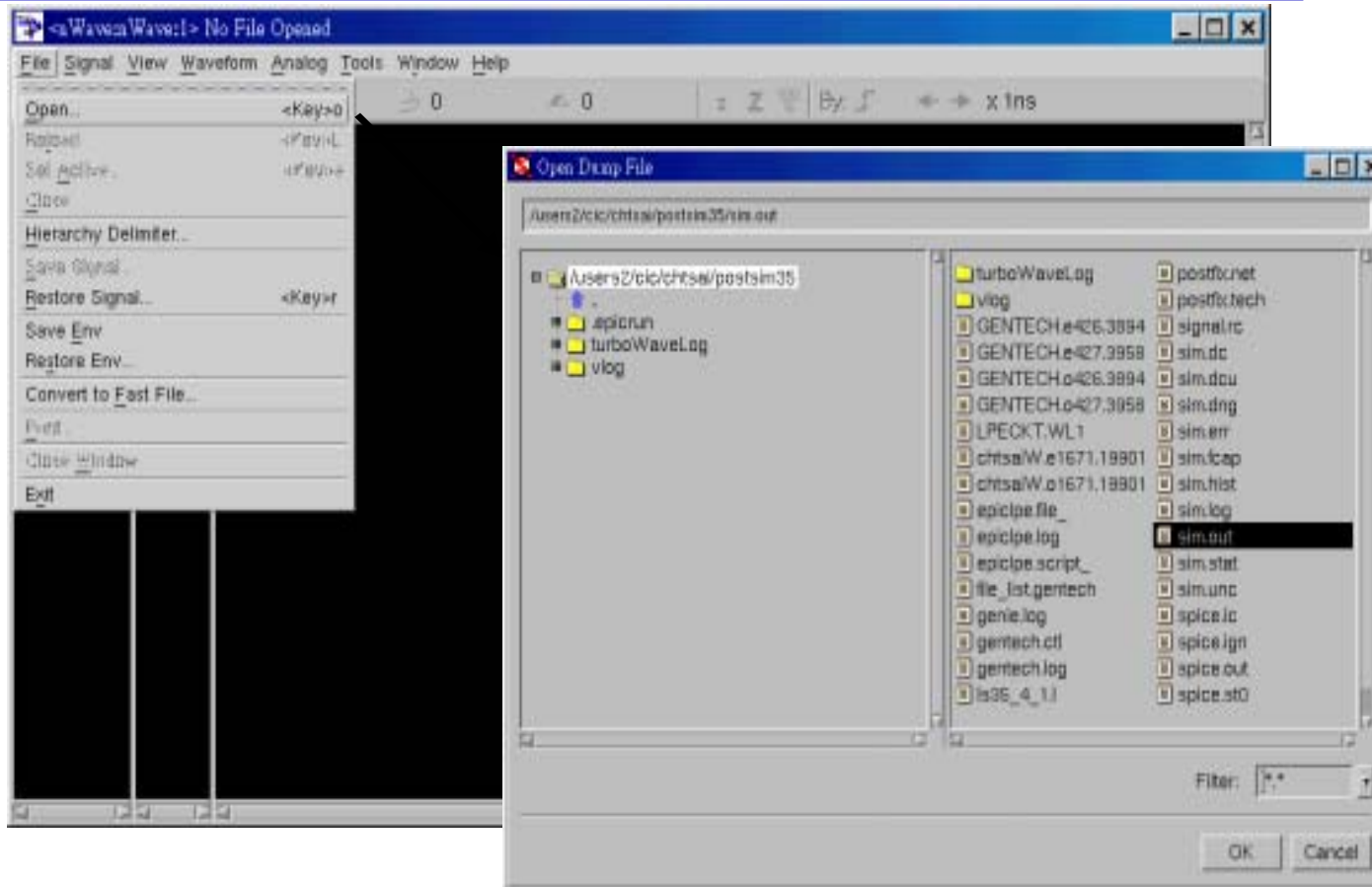
```
unix% source /usr/debussy/CIC/debussy.csh
```

◆ Starting *nWave*

```
unix% nWave &
```

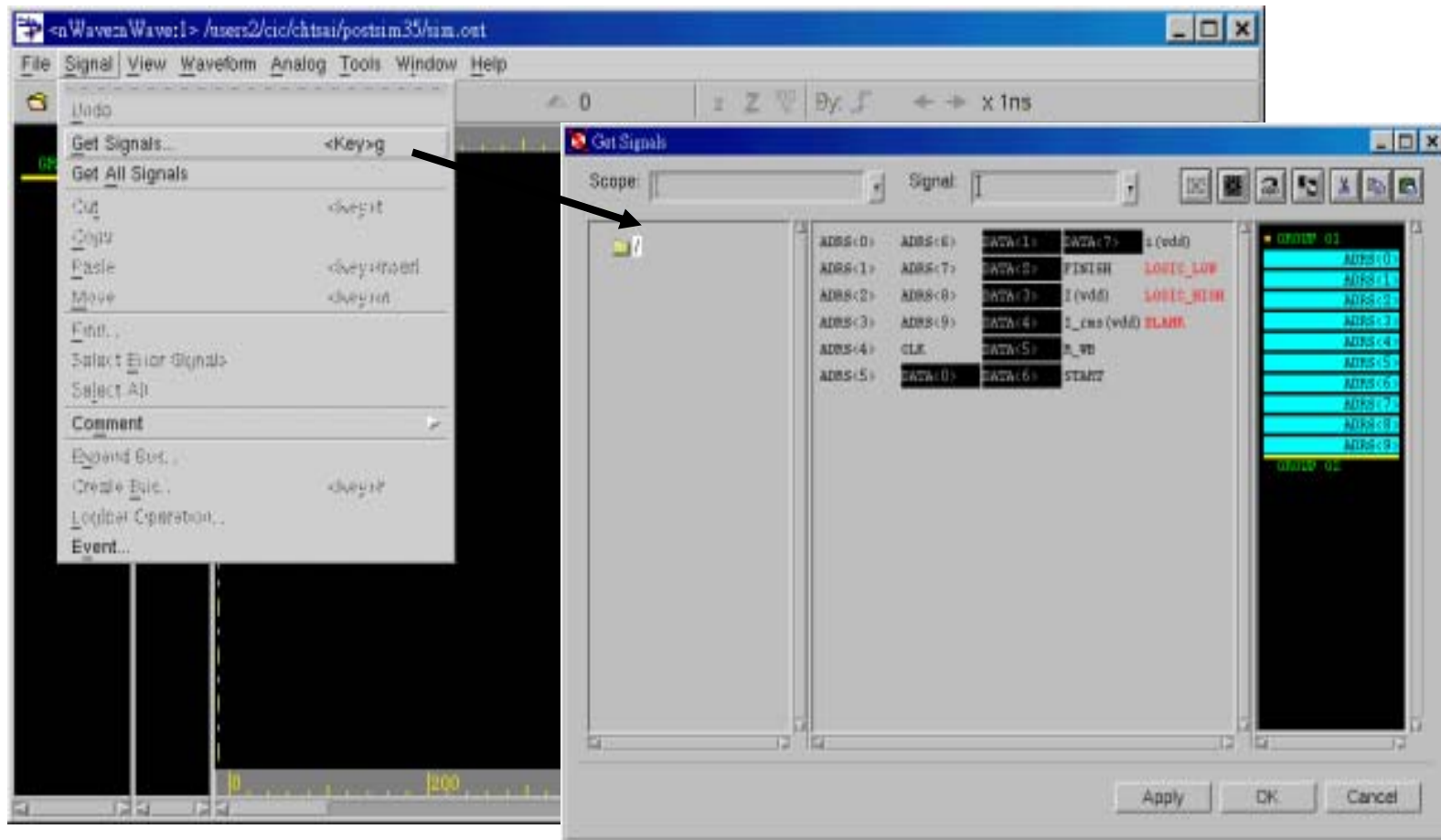


Load Simulation Result --- nWave



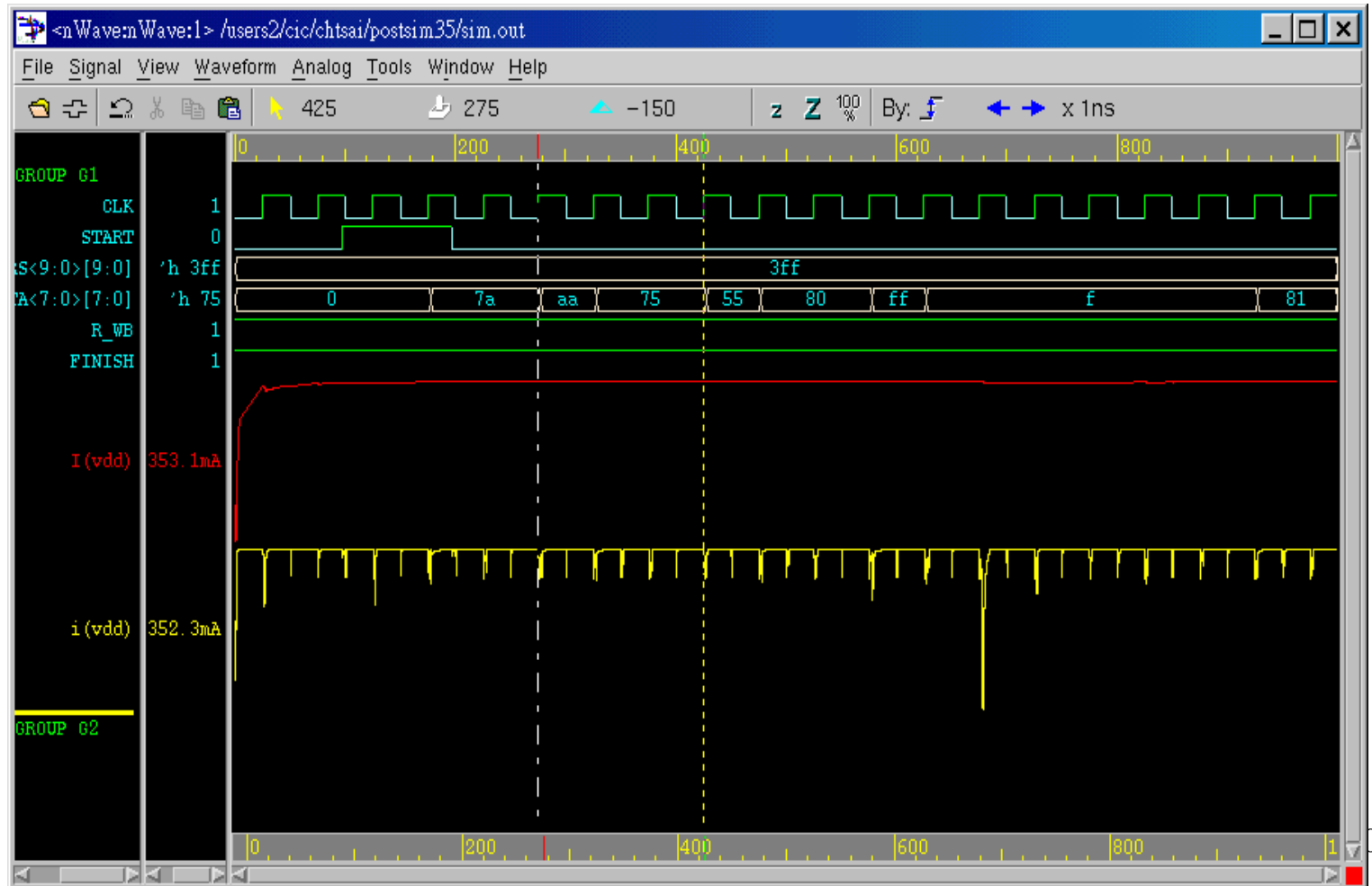


Select Signals --- nWave





Check Simulation Result --- nWave





Power Analysis Result

- ◆ The power analysis result is stored in Nanosim simulation log (*xxx.log*) file

```
. . . . .
Current information calculated over the intervals:

    0.00000e+00 - 1.00010e+03 ns

Node: VDD
  Average current      : -3.53355e+05 uA
  RMS current         :  3.53388e+05 uA

  Current peak #1      : -4.54061e+05 uA at 6.78400e+02 ns
  Current peak #2      : -4.34973e+05 uA at 4.00000e-01 ns
  Current peak #3      : -3.88048e+05 uA at 2.59000e+01 ns
  Current peak #4      : -3.87280e+05 uA at 1.27500e+02 ns
  Current peak #5      : -3.84302e+05 uA at 5.77800e+02 ns
. . . . .
```